具有可编程阈值和主机唤醒功能的 ADS7142-Q1 汽车类双通道 12 位、140kSPS、I²C 兼容型 ADC 特性

1 特性

- 符合面向汽车应用的 AEC-Q100 标准：
  - 器件温度等级 1：
    –40°C 至 125°C，T_A
- 小封装尺寸：3mm × 2mm
- 12 位无噪声分辨率
- 采样率高达 140kSPS
- 高效的主机休眠和唤醒：
  - 自主监控功耗为 900nW
  - 用于事件触发主机唤醒的窗口比较器
- 独立的配置和校准：
  - 双通道、伪差分或接地感应输入配置
  - 用于校准的可编程阈值
  - 内部校准改善了失调电压和漂移
- 错误触发防护：
  - 每个通道的可编程阈值
  - 用于实现抗噪性能的可编程迟滞
  - 用于瞬态抑制的事件计数器
- I²C 接口：
  - 兼容 1.65V 至 3.6V 的电压范围
  - 8 个可配置地址
  - 高达 3.4MHz（高速）
- 模拟电源：1.65V 至 3.6V

2 应用

通用的电压、电流和温度监测用于：

- 汽车摄像头模块
- 驾驶员监测和辅助系统
- 信息娱乐系统和仪表组
- 电动和 ICE 动力传动系统

3 说明

ADS7142-Q1 是 12 位 140kSPS 逐次逼近型寄存器 (SAR) 模数转换器 (ADC)，可以自主监测信号，同时最大限地提高系统功率、可靠性和性能。该器件使用具有可编程高低警报阈值、迟滞和事件计数器的数字窗口比较器，实施每通道事件触发的中断。器件包含一个在 SAR ADC 前端的双通道模拟多路复用器，然后是一个用于转换和捕捉传感器数据的内部数据缓冲器。

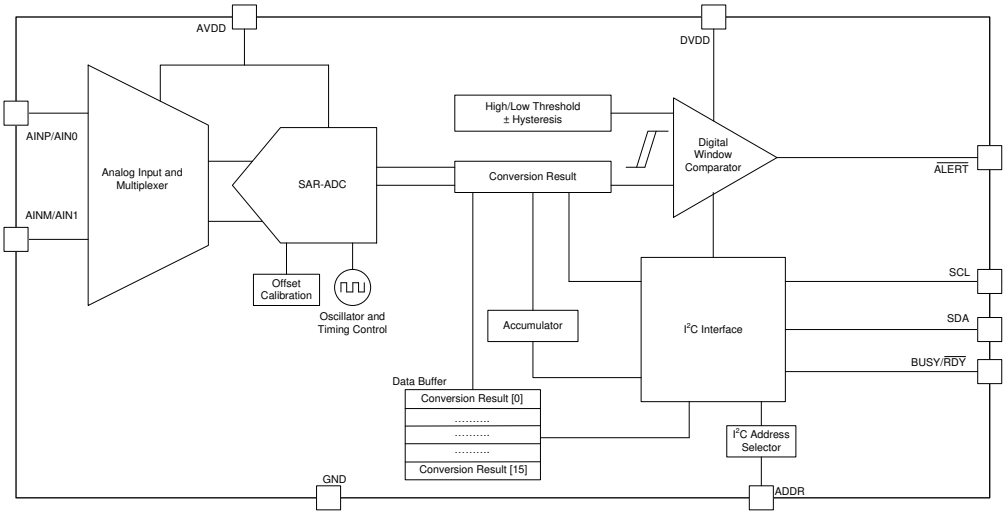
ADS7142-Q1 提供 10 引脚 WSON 封装，可以实现功耗低至 900nW。该器件体积小巧，功耗低，非常适合空间受限型 应用。

器件信息(1)

部件名称	封装	封装尺寸（标称值）
ADS7142-Q1	WSON (10)	3.00mm x 2.00mm

(1) 如需了解所有可用封装，请参阅数据表末尾的可订购产品附录。

方框图



本文档旨在为方便起见，提供有关 TI 产品中文版本的信息，以确认产品的概要。 有关适用的官方英文版本的最新信息，请访问 www.ti.com，其内容始终优先。 TI 不保证翻译的准确性和有效性。 在实际设计之前，请务必参考最新版本的英文版本。

目录

1 特性 ... 1
2 应用 ... 1
3 说明 ... 1
4 修订历史记录 ... 2
5 **Pin Configuration and Functions** ... 3
6 **Specifications** ... 4
6.1 Absolute Maximum Ratings ... 4
6.2 ESD Ratings ... 4
6.3 Recommended Operating Conditions ... 4
6.4 Thermal Information ... 4
6.5 Electrical Characteristics: All Modes ... 5
6.6 Electrical Characteristics: Manual Mode ... 6
6.7 Electrical Characteristics: Autonomous Modes ... 7
6.8 Electrical Characteristics: High Precision Mode ... 8
6.9 Timing Requirements ... 8
6.10 Switching Characteristics ... 10
6.11 Typical Characteristics: All Modes ... 12
6.12 Typical Characteristics: Manual Mode ... 13
6.13 Typical Characteristics: Autonomous Modes ... 17
6.14 Typical Characteristics: High-Precision Mode ... 18
7 **Detailed Description** ... 19
7.1 Overview ... 19
7.2 Functional Block Diagram ... 19
7.3 Feature Description ... 20
7.4 Device Functional Modes ... 28
7.5 Programming ... 39
7.6 Register Map ... 42
8 **Application and Implementation** ... 59
8.1 Application Information ... 59
8.2 Typical Applications ... 59
9 **Power Supply Recommendations** ... 65
9.1 AVDD and DVDD Supply Recommendations ... 65
10 **Layout** ... 66
10.1 Layout Guidelines ... 66
10.2 Layout Example ... 67
11 器件和文档支持 ... 68
11.1 接收文档更新通知 ... 68
11.2 社区资源 ... 68
11.3 商标 ... 68
11.4 静电放电警告 ... 68
11.5 Glossary ... 68
12 机械、封装和可订购信息 ... 69

4 修订历史记录

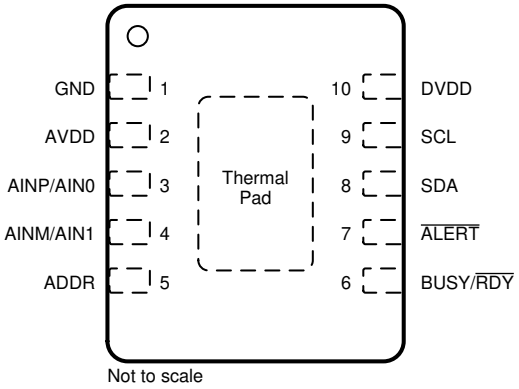
Changes from Original (November 2018) to Revision A **Page**

- 已更改 将文档状态从预告信息更改为生产数据 ... 1

Copyright © 2018–2019, Texas Instruments Incorporated

5 Pin Configuration and Functions

DQC Package
10-Pin WSON
Top View



Not to scale

Pin Functions

PIN		I/O	DESCRIPTION
NO.	NAME		
1	GND	Supply	Ground for power supply, all analog and digital signals are referred to this pin.
2	AVDD	Supply	Analog supply input, also used as the reference voltage for analog-to-digital conversion.
3	AINP/AIN0	Analog input	Single-channel operation: positive analog signal input. Two-channel operation: analog signal input, channel 0.
4	AINM/AIN1	Analog input	Single-channel operation: negative analog signal input. Two-channel operation: analog signal input, channel 1.
5	ADDR	Analog Input	Input for selecting the I^2C address of the device. See the *I2C Address Selection* section for details.
6	BUSY/$\overline{\text{RDY}}$	Digital output	The device pulls this pin high when scanning through channels in a sequence and brings this pin low when the sequence is completed or aborted.
7	$\overline{\text{ALERT}}$	Digital output	Active low, open-drain output. The status of this pin is controlled by the digital window comparator block. Connect a pullup resistor from DVDD to this pin.
8	SDA	Digital input/output	Serial data input/output for the I^2C interface. Connect a pullup resistor from DVDD to this pin.
9	SCL	Digital input	Serial clock for the I^2C interface. Connect a pullup resistor from DVDD to this pin.
10	DVDD	Supply	Digital I/O supply voltage.

Copyright © 2018–2019, Texas Instruments Incorporated

6 Specifications

6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)(1)

	MIN	MAX	UNIT
ADDR to GND	–0.3	AVDD + 0.3	V
AVDD to GND	–0.3	3.9	V
DVDD to GND	–0.3	3.9	V
AINP/AIN0 to GND	–0.3	AVDD + 0.3	V
AINM/AIN1 to GND	–0.3	AVDD + 0.3	V
Input current on any pin except supply pins	–10	10	mA
Digital input to GND	–0.3	DVDD + 0.3	V
Junction temperature, T_J	–40	150	°C
Storage temperature, T_{stg}	–60	150	°C

(1) Stresses beyond those listed under *Absolute Maximum Rating* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Condition*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

6.2 ESD Ratings

				VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human-body model (HBM), per AEC Q100-002(1)		±2000	V
		Charged-device model (CDM), per AEC Q100-011	Corner pins (1, 5, 6, and 10)	±750	
			All other pins	±500	

(1) AEC Q100-002 indicates that HBM stressing shall be in accordance with the ANSI/ESDA/JEDEC JS-001 specification.

6.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

		MIN	NOM	MAX	UNIT
AVDD	Analog supply voltage range	1.65		3.6	V
DVDD	Digital supply voltage range	1.65		3.6	V
T_A	Ambient temperature	–40		125	°C

6.4 Thermal Information

THERMAL METRIC(1)		ADS7142-Q1 DQC (WSON) 10 PINS	UNIT
$R_{\theta JA}$	Junction-to-ambient thermal resistance	61.8	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	66.3	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	29.8	°C/W
Ψ_{JT}	Junction-to-top characterization parameter	2.1	°C/W
Ψ_{JB}	Junction-to-board characterization parameter	29.7	°C/W
$R_{\theta JC(bot)}$	Junction-to-case (bottom) thermal resistance	6.1	°C/W

(1) For more information about traditional and new thermal metrics, see the Semiconductor and IC Package Thermal Metrics application report.

Copyright © 2018–2019, Texas Instruments Incorporated

6.5 Electrical Characteristics: All Modes

at T_A = -40°C to 125°C, AVDD = 3 V, DVDD = 1.65 V to 3.6 V, All Channel Configurations (unless otherwise noted)(1)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
ANALOG INPUT (Two-Channel Single-Ended Configuration)						
	Full-scale input voltage span(1)	AINP/AIN0 to GND or AINM/AIN1 to GND	0		AVDD	V
	Absolute input voltage range	AINP/AIN0 to GND or AINM/AIN1 to GND	–0.1		AVDD + 0.1	V
ANALOG INPUT (Single-Channel Single-Ended Configuration with Remote Ground Sense)						
	Full-scale input voltage span(1)	AINP/AIN0 to AINM/AIN1	0		AVDD	V
	Absolute input voltage range	AINP/AIN0 to GND	–0.1		AVDD + 0.1	V
		AINM/AIN1 to GND	–0.1		0.1	
ANALOG INPUT (Single-Channel Pseudo-Differential Configuration with Remote Ground Sense)						
	Full-scale input voltage span(1)	AINP/AIN0 to AINM/AIN1	–AVDD/2		AVDD/2	V
	Absolute input voltage range	AINP/AIN0 to GND	–0.1		AVDD + 0.1	V
		AINM/AIN1 to GND	AVDD/2–0.1		AVDD/2+0.1	
INTERNAL OSCILLATOR						
t_{HSO}	Time period for high-speed oscillator			50	110	ns
t_{LPO}	Time period for low-power oscillator			95.2	300	µs
DIGITAL INPUT/OUTPUT (SCL, SDA)						
V_{IH}	High-level input voltage		0.7 × DVDD		DVDD	V
V_{IL}	Low-level input voltage		0		0.3 × DVDD	V
V_{OL}	Low-level output voltage	With 3 mA sink current and DVDD > 2 V	0		0.4	V
		With 3 mA sink current and 1.65 V < DVDD < 2 V	0		0.2 × DVDD	
I_{OL}	Low-level output current (sink)	V_{OL} = 0.4 V for standard and fast mode (100, 400 kHz)	3			mA
		V_{OL} = 0.6 V for fast mode (400 kHz)	6			
		V_{OL} = 0.4 V fast mode Plus (1 MHz)	20			
I_{OL}	Low-level output current (sink)	V_{OL}= 0.4 V high speed (1.7 MHz, 3.4 MHz)	25			mA
I_I	Input current on pin				10	µA
C_I	Input capacitance on pin				10	pF
DIGITAL OUTPUT (BUSY/$\overline{\text{RDY}}$)						
V_{OH}	High-level output voltage	I_{source} = 2 mA	0.7 × DVDD		DVDD	V
V_{OL}	Low-level output voltage	I_{sink} = 2 mA	0		0.3 × DVDD	V
DIGITAL OUTPUT ($\overline{\text{ALERT}}$)						
I_{OL}	Low-level output current	V_{OL} < 0.25 V		5		mA
V_{OL}	Low-level output voltage	I_{sink} = 5 mA	0		0.25	V
POWER-SUPPLY REQUIREMENTS						
AVDD	Analog supply voltage		1.65		3.6	V
DVDD	Digital I/O supply voltage		1.65		3.6	V

(1) Ideal Input span, does not include gain or offset error.

Copyright © 2018–2019, Texas Instruments Incorporated

6.6 Electrical Characteristics: Manual Mode

at T_A = -40°C to 125°C, AVDD = 3 V, DVDD = 1.65 V to 3.6 V, All Channel Configurations (unless otherwise noted)(1)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
SAMPLING DYNAMICS						
t_{conv}	Conversion time	AVDD = 1.65 V to 3.6 V			1.8	µs
t_{acq}	Acquisition time	AVDD = 1.65 V to 3.6 V		18		T_{SCL}
t_{cycle}	Cycle time	AVDD = 1.65 V to 3.6 V, SCL = 3.4 MHz			7.1	µs
DC SPECIFICATIONS						
	Resolution			12		Bits
NMC	No missing codes	AVDD = 1.65 V to 3.6 V	12			Bits
DNL	Differential nonlinearity	AVDD = 1.65 V to 3.6 V	–0.99	±0.3	1	LSB(1)
INL	Integral nonlinearity		–2.75	±0.5	2.75	LSB
E_O	Offset error	Post offset calibration	–4	±0.5	4	LSB
dV_{OS}/dT	Offset drift with temperature	Post offset calibration		5		ppm/°C
E_G	Gain error		–0.1	±0.03	0.1	%FSR
	Gain error drift with temperature			5		ppm/°C
AC SPECIFICATIONS						
SNR(2)	Signal-to-noise ratio	f_{IN} = 2 kHz, AVDD = 3 V, f_{SAMPLE} = 140 kSPS	68.75	70		dB
		f_{IN} = 2 kHz, AVDD = 1.8 V, f_{SAMPLE} = 140 kSPS		68		
THD(2)(3)	Total harmonic distortion	f_{IN} = 2 kHz, AVDD = 3 V, f_{SAMPLE} = 140 kSPS		–85		dB
		f_{IN} = 2 kHz, AVDD = 1.8 V, f_{SAMPLE} = 140 kSPS		–80		
SINAD(2)	Signal-to-noise and distortion	f_{IN} = 2 kHz, AVDD = 3 V, f_{SAMPLE} = 140 kSPS	68.5	69.5		dB
		f_{IN} = 2 kHz, AVDD = 1.8 V, f_{SAMPLE} = 140 kSPS		67.5		
SFDR(2)	Spurious-free dynamic range	f_{IN} = 2 kHz, AVDD = 3 V, f_{SAMPLE} = 140 kSPS		90		dB
BW	–3-dB small-signal bandwidth			25		MHz
POWER CONSUMPTION						
I_{AVDD}	Analog supply current	f_{SAMPLE} = 140 kSPS, SCL = 3.4 MHz		265	300	µA
		f_{SAMPLE}= 5.5 kSPS, SCL = 100 kHz		8		
		f_{SAMPLE} = 140 kSPS, SCL = 3.4 MHz, AVDD = 1.8 V		160		
		f_{SAMPLE} = 5.5 kSPS, SCL = 100 kHz, AVDD = 1.8 V		5		
I_{DVDD}	Digital supply current	f_{SAMPLE} = 140 kSPS, SCL = 3.4 MHz, SDA = AAA0h		25		µA
		f_{SAMPLE} = 5.5 kSPS, SCL = 100 kHz, SDA = AAA0h		2		
		f_{SAMPLE} = 140 kSPS, SCL = 3.4 MHz, AVDD = 1.8 V, SDA = AAA0h		15		
I_{AVDD}	Static analog supply current	No activity on SCL and SDA		6		nA
I_{DVDD}	Static digital supply current	No activity on SCL and SDA		2		nA

(1) LSB means least significant byte. See the ADC Transfer Function for details.
(2) All specifications expressed in decibels (dB) refer to the full-scale input (FSR) and are tested with an input signal 0.5 dB below full-scale, unless otherwise specified.
(3) Calculated on the first nine harmonics of the input frequency.

Copyright © 2018–2019, Texas Instruments Incorporated

6.7 Electrical Characteristics: Autonomous Modes

at T_A = -40°C to 125°C, AVDD = 3 V, DVDD = 1.65 V to 3.6 V, All Channel Configurations (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
SAMPLING DYNAMICS						
t_{conv}	Conversion time	High-speed oscillator		14		t_{HSO}
		Low-power oscillator		14		t_{LPO}
t_{acq}	Acquisition time	High-speed oscillator	7			t_{HSO}
		Low-power oscillator	4			t_{LPO}
t_{cycle}	Cycle time	High-speed oscillator		nCLK		t_{HSO}
		Low-power oscillator		nCLK		t_{LPO}
DC SPECIFICATIONS						
	Resolution			12		Bits
E_O	Offset error	Post offset calibration		±0.5		LSB
E_G	Gain error			±0.03		%FSR
POWER CONSUMPTION						
I_{AVDD}	Analog supply current	With low-power oscillator, nCLK = 18		0.75		µA
		With low-power oscillator, AVDD = 1.8 V, nCLK = 18		0.45		
		With low-power oscillator, nCLK = 250		0.5		
		With low-power oscillator, nCLK = 21		940		
I_{DVDD}	Digital supply current	With low-power oscillator, nCLK = 18, DVDD = 3.3 V		0.15		µA
		With low-power oscillator, DVDD = 1.8 V, nCLK = 18		0.25		
		With low-power oscillator, nCLK = 250, DVDD = 3.3 V		0.15		
		With high-power oscillator, nCLK = 21, DVDD = 3.3 V		0.15		
I_{AVDD}	Static analog supply current	No activity on SCL and SDA		5		nA
I_{DVDD}	Static digital supply current	No activity on SCL and SDA		0.6		nA

Copyright © 2018–2019, Texas Instruments Incorporated

6.8 Electrical Characteristics: High Precision Mode

at T_A = -40°C to 125°C, AVDD = 3 V, DVDD = 1.65 V to 3.6 V, All Channel Configurations (unless otherwise noted)(1)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
DC SPECIFICATIONS						
	Resolution(2)			16		Bits
ENOB	Effective number of bits	With DC input of AVDD / 2(3)		15.4		
E_O	Offset error	Post offset calibration		±10		LSB
E_G	Gain error			±0.03		%FSR
POWER CONSUMPTION						
I_{AVDD}	Analog supply current	With low-power oscillator, nCLK = 18		0.6		µA
		With low-power oscillator, AVDD = 1.8 V, nCLK = 18		0.3		
		With low-power oscillator, nCLK = 250		0.5		
		With high-speed oscillator, nCLK = 21		980		
I_{DVDD}	Digital supply current	With low-power oscillator, nCLK = 21, DVDD = 3.3 V		0.2		µA
		With low-power oscillator, DVDD = 1.8 V, nCLK = 21		0.25		
		With low-power oscillator, nCLK = 250, DVDD = 3.3 V		0.2		
		With high-speed oscillator, nCLK = 21, DVDD = 3.3 V		0.2		
I_{AVDD}	Static analog supply current	No activity on SCL and SDA		5		nA
I_{DVDD}	Static analog supply current	No activity on SCL and SDA		0.7		nA

(1) Sampling dynamics for high precision mode are same as for autonomous modes.
(2) See 公式 5
(3) For DC input, ENOB = Ln[FSR/Standard deviation of Codes]/Ln[2]. See

6.9 Timing Requirements

at T_A = -40°C to 125°C, AVDD = 3 V, DVDD = 1.65 V to 3.6 V, All Channel Configurations (unless otherwise noted)(1)

PARAMETER		MIN	MAX	UNIT
STANDARD MODE (100 kHz)				
f_{SCL}	SCL clock frequency	0	100	kHz
t_{HD-STA}	Hold time (repeated) START condition	4		µs
t_{LOW}	Low period of SCL	4.7		µs
t_{HIGH}	High period of SCL	4		µs
t_{SU-STA}	Setup time for a repeated start condition	4.7		µs
t_{HD-DAT}(2)(3)	Data hold time	0		µs
t_{SU-DAT}	Data setup time	250		ns
t_{SU-STO}	Data setup time	4		µs
t_{BUF}	Bus free time between a STOP and START condition	4.7		µs
C_b	Capacitive load on each line		400	pF
FAST MODE (400 kHz)				
f_{SCL}	SCL clock frequency	0	400	kHz
t_{HD-STA}	Hold time (repeated) START condition	0.6		µs
t_{LOW}	Low period of SCL	1.3		µs
t_{HIGH}	High period of SCL	0.6		µs

(1) All values referred to $V_{IH(min)}$ (0.7 DVDD) and $V_{IL(max)}$ (0.3 DVDD).
(2) t_{HD-DAT} is the data hold time that is measured from the falling edge of SCL and applies to data in transmission and the acknowledge.
(3) The maximum t_{HD-DAT} can be 3.45 µs and 0.9 µs for standard-mode and fast-mode, but must be less than the maximum of t_{VD-DAT} or t_{VD-ACK} by a transition time. This maximum must only be met if the device does not stretch the LOW period (t_{LOW}) of the SCL signal. If the clock is streched, the data must be valid by the setup time before being released.

Copyright © 2018–2019, Texas Instruments Incorporated

Timing Requirements (continued)

at T_A = -40°C to 125°C, AVDD = 3 V, DVDD = 1.65 V to 3.6 V, All Channel Configurations (unless otherwise noted)(1)

PARAMETER		MIN	MAX	UNIT
t_{SU-STA}	Setup time for a repeated start condition	0.6		µs
t_{HD-DAT}	Data hold time	0		µs
t_{SU-DAT}	Data setup time	100		ns
t_{SU-STO}	Data setup time	0.6		µs
t_{BUF}	Bus free time between a STOP and START condition	1.3		µs
C_b	Capacitive load on each line		400	pF
FAST MODE PLUS (1000 kHz)				
f_{SCL}	SCL clock frequency	0	1000	kHz
t_{HD-STA}	Hold time (repeated) START condition	0.26		µs
t_{LOW}	Low period of SCL	0.5		µs
t_{HIGH}	High period of SCL	0.26		µs
t_{SU-STA}	Setup time for a repeated start condition	0.26		µs
t_{HD-DAT}	Data hold time	0		µs
t_{SU-DAT}	Data setup time	50		ns
t_{SU-STO}	Data setup time	0.26		µs
t_{BUF}	Bus free time between a STOP and START condition	0.5		µs
C_b	Capacitive load on each line		550	pF
HIGH SPEED MODE (1.7 MHz, C_b = 400 pF max)				
f_{SCLH}	SCLH clock frequency	0	1.7	MHz
t_{HD-STA}	Hold time (repeated) START condition	160		ns
t_{LOW}	Low period of SCL	320		ns
t_{HIGH}	High period of SCL	120		ns
t_{SU-STA}	Setup time for a repeated start condition	160		ns
t_{HD-DAT}	Data hold time	0	150	ns
t_{SU-DAT}	Data setup time	10		ns
t_{SU-STO}	Data setup time	160		ns
C_b	Capacitive load on each line		100	pF
HIGH SPEED MODE (3.4 MHz, C_b = 100 pF max)				
f_{SCLH}	SCLH clock frequency	0	3.4	MHz
t_{HD-STA}	Hold time (repeated) START condition	160		ns
t_{LOW}	Low period of SCL	160		ns
t_{HIGH}	High period of SCL	60		ns
t_{SU-STA}	Setup time for a repeated start condition	160		ns
t_{HD-DAT}	Data hold time	0	70	ns
t_{SU-DAT}	Data setup time	10		ns
t_{SU-STO}	Data setup time	160		ns
C_b	Capacitive load on each line		100	pF

Copyright © 2018–2019, Texas Instruments Incorporated

6.10 Switching Characteristics

at T_A = -40°C to 125°C, AVDD = 3 V, DVDD = 1.65 V to 3.6 V, All Channel Configurations (unless otherwise noted)(1)

PARAMETER		TEST CONDITIONS	MIN	MAX	UNIT
STANDARD MODE (100 kHz)					
t_{rCL}	Rise time of SCL			1000	ns
t_{rDA}	Rise time of SDA			1000	ns
t_{fCL}	Fall time of SCL			300	ns
t_{fDA}	Fall time of SDA			300	ns
t_{VD-DAT} (2)	Data valid time			3.45	µs
t_{VD-ACK} (2)	Data hold time			3.45	µs
FAST MODE (400 kHz)					
t_{rCL}	Rise time of SCL		20	300	ns
t_{rDA}	Rise time of SDA		20	300	ns
t_{fCL}	Fall time of SCL		20 × DVDD/3.6	300	ns
t_{fDA}	Fall time of SDA		20 × DVDD/3.6	300	ns
t_{VD-DAT}	Data valid time			0.9	µs
t_{VD-ACK}	Data hold time			0.9	µs
t_{SP} (3)	Pulse duration of spikes suppressed by the input filter		0	50	ns
FAST MODE PLUS (1000 kHz)					
t_{rCL}	Rise time of SCL			120	ns
t_{rDA}	Rise time of SDA			120	ns
t_{fCL}	Fall time of SCL		20 × DVDD/3.6	120	ns
t_{fDA}	Fall time of SDA		20 × DVDD/3.6	120	ns
t_{VD-DAT}	Data valid time			0.45	µs
t_{VD-ACK}	Data hold time			0.45	µs
t_{SP}	Pulse duration of spikes suppressed by the input filter		0	50	ns
HIGH SPEED MODE (1.7 MHz, C_b = 400 pF max)					
t_{rCL}	Rise time of SCLH		20	80	ns
t_{rCL1}	Rise time of SCLH after a repeated start condition and after an acknowledge bit		20	160	ns
t_{rDA}	Rise time of SDAH		20	160	ns
t_{fCL}	Fall time of SCLH		20	80	ns
t_{fDA}	Fall time of SDAH		20	160	ns
t_{SP}	Pulse duration of spikes suppressed by the input filter		0	10	ns
HIGH SPEED MODE (3.4 MHz, C_b = 100 pF max)					
t_{rCL}	Rise time of SCLH		10	40	ns
t_{rCL1}	Rise time of SCLH after a repeated start condition and after an acknowledge bit		10	80	ns
t_{rDA}	Rise time of SDAH		10	80	ns
t_{fCL}	Fall time of SCLH		10	40	ns
t_{fDA}	Fall time of SDAH		10	80	ns
t_{SP}	Pulse duration of spikes suppressed by the input filter		0	10	ns

(1) All values referred to $V_{IH(min)}$ (0.7 DVDD) and $V_{IL(max)}$ (0.3 DVDD).
(2) t_{VD-DAT} = time for data signal from SCL LOW to SDA output.
(3) Input filters on the SDA and SCL inputs suppress noise spikes of less than 50 ns.

Copyright © 2018–2019, Texas Instruments Incorporated

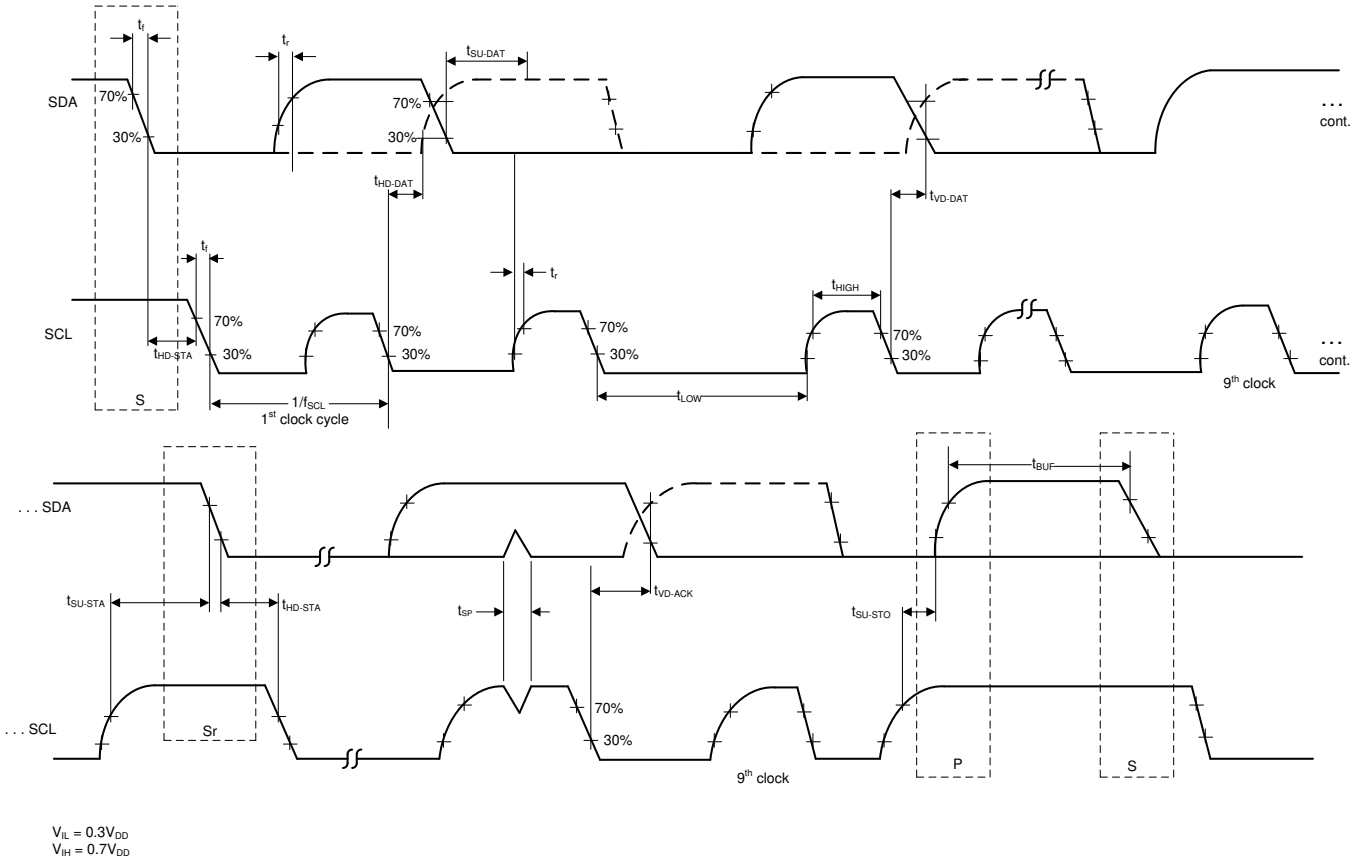
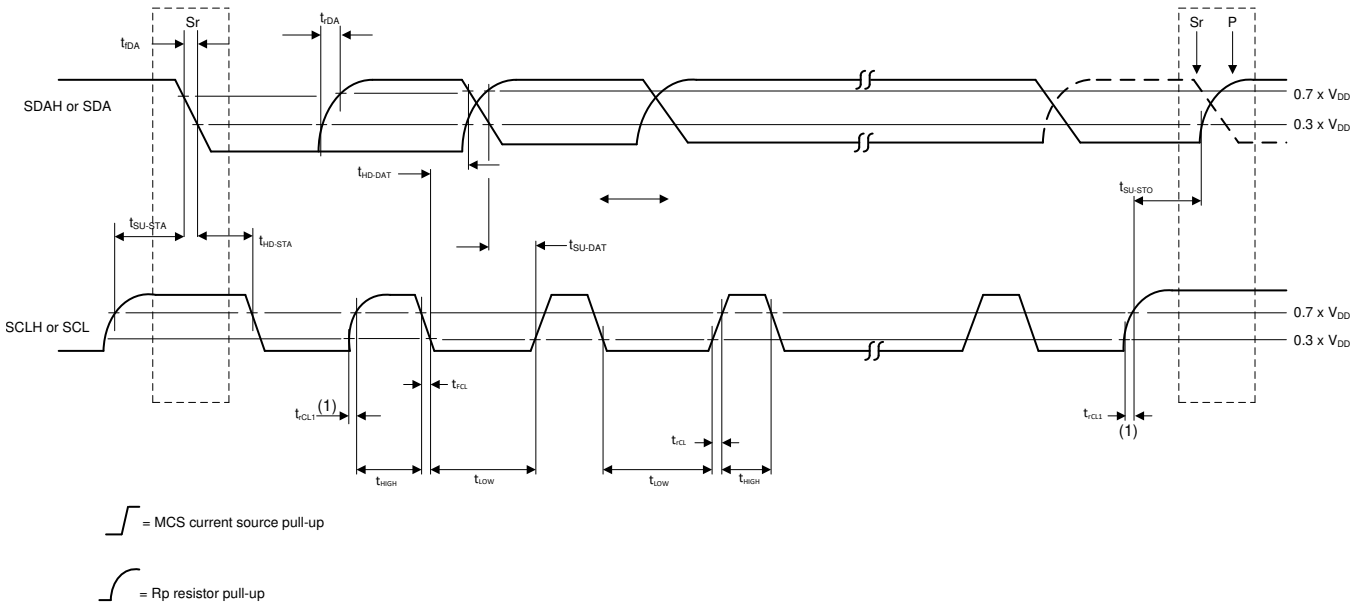


图 1. Timing Diagram for Standard Mode, Fast Mode, and Fast Mode Plus



(1) First rising edge of the SCLH signal after Sr and after each acknowledge bit.

图 2. Timing Diagram for High-Speed Mode

6.11 Typical Characteristics: All Modes

at T_A = 25°C, AVDD = 3 V, DVDD = 3.3 V, and two-channel single-ended configuration (unless otherwise noted)

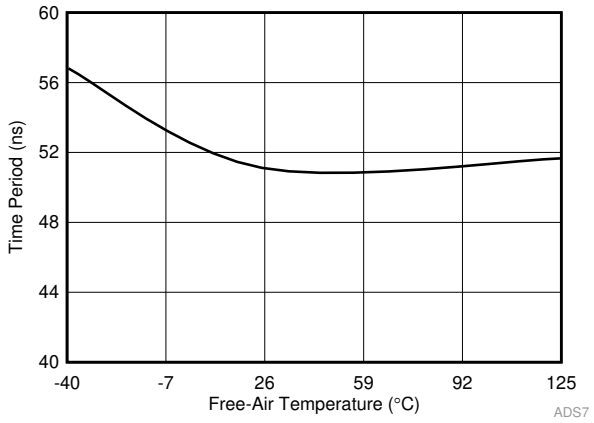


图 3. High-Speed Oscillator Time Period vs Temperature

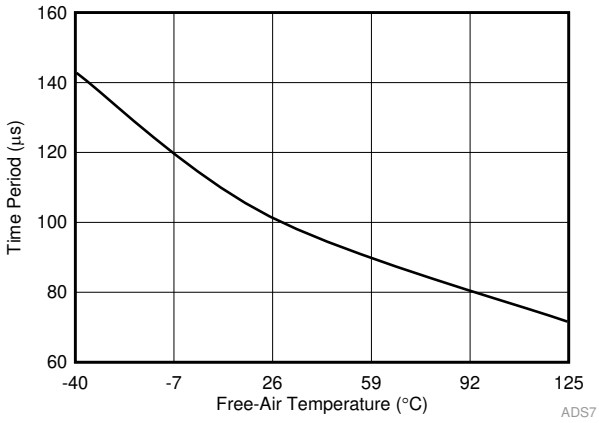
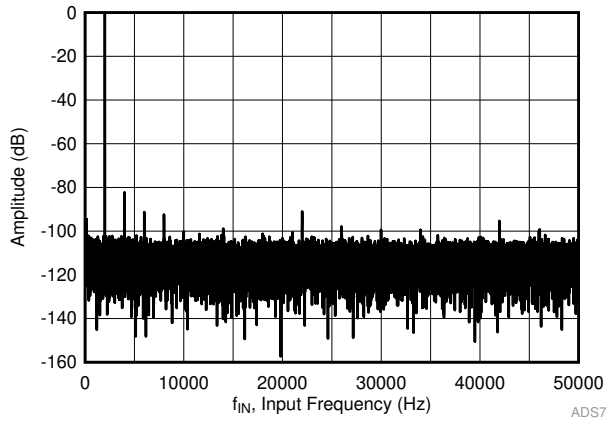


图 4. Low-Power Oscillator Time Period vs Temperature

版权 © 2018–2019, Texas Instruments Incorporated

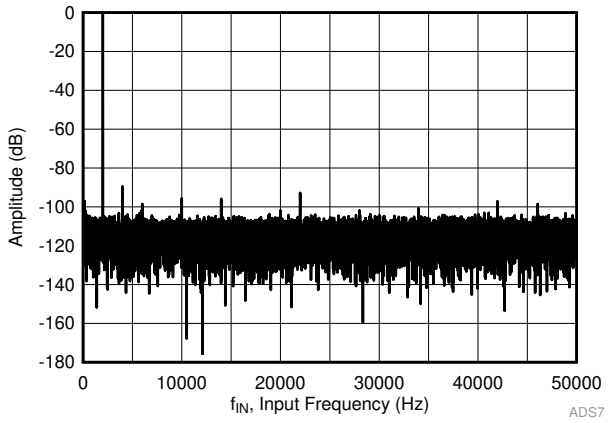
6.12 Typical Characteristics: Manual Mode

at T_A = 25°C, AVDD = 3 V, DVDD = 3.3 V, and two-channel single-ended configuration (unless otherwise noted)



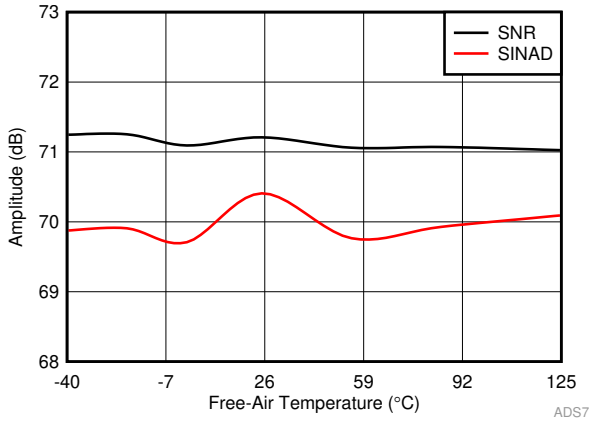
SNR = 69.6 dB, THD = –84 dB, ENOB = 11.2,
f_{sample} = 140 kSPS, SFDR = 87 dB, AVDD = 1.8 V

图 5. Typical FFT in Manual Mode



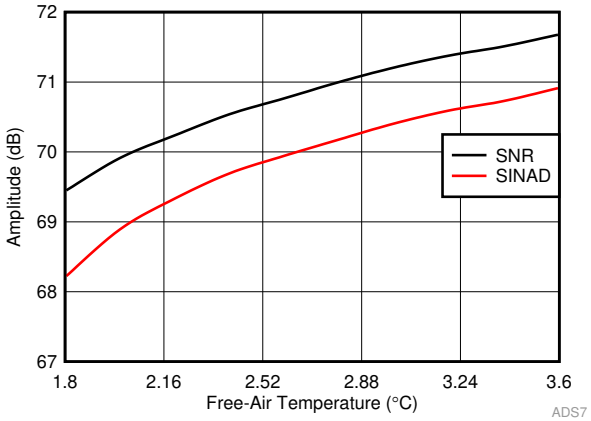
SNR = 71.3 dB, THD = –87 dB, ENOB = 11.5,
f_{sample} = 140 kSPS, SFDR = 89.3 dB, AVDD = 3 V

图 6. Typical FFT in Manual Mode



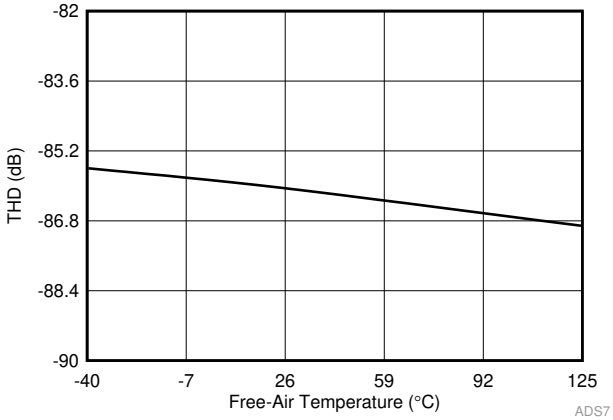
f_{sample} = 140 kSPS

图 7. SNR and SINAD in Manual Mode vs Temperature



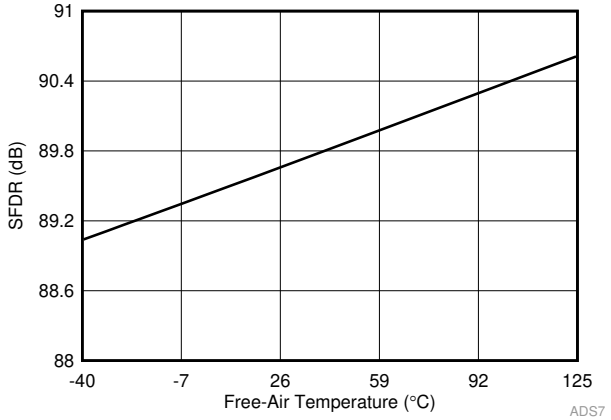
f_{sample} = 140 kSPS

图 8. SNR and SINAD in Manual Mode vs AVDD



f_{sample} = 140 kSPS

图 9. THD in Manual Mode vs Temperature

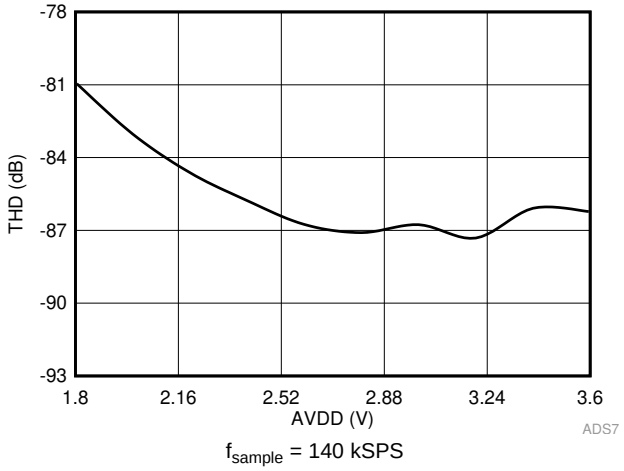


f_{sample} = 140 kSPS

图 10. SFDR in Manual Mode vs Temperature

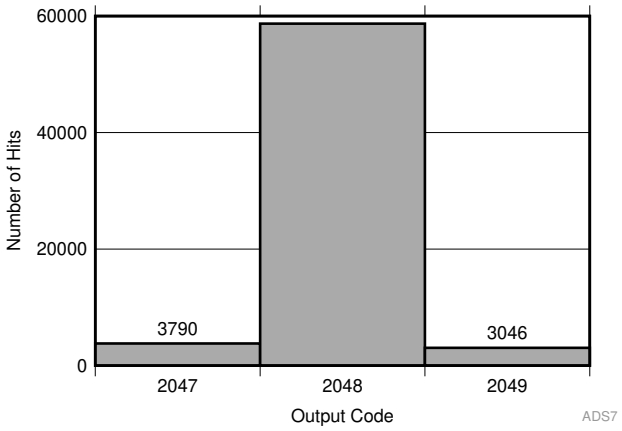
Typical Characteristics: Manual Mode (接下页)

at T_A = 25°C, AVDD = 3 V, DVDD = 3.3 V, and two-channel single-ended configuration (unless otherwise noted)



f_{sample} = 140 kSPS

图 11. THD in Manual Mode vs AVDD



Mean code = 2047.9, standard deviation = 0.32

图 12. Typical DC Code Spread in Manual Mode

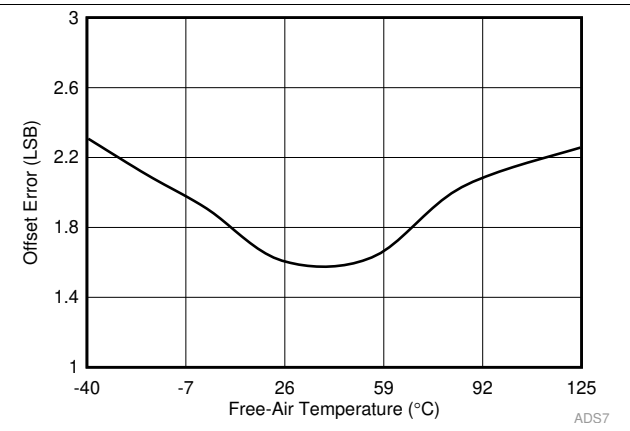


图 13. Offset Error in Manual Mode vs Temperature

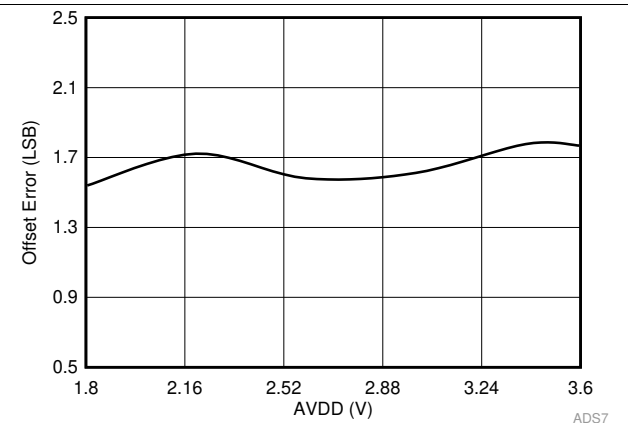


图 14. Offset Error in Manual Mode vs AVDD

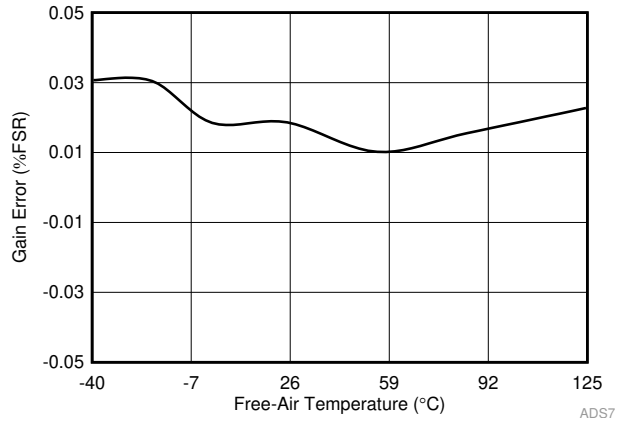


图 15. Gain Error in Manual Mode vs Free-Air Temperature

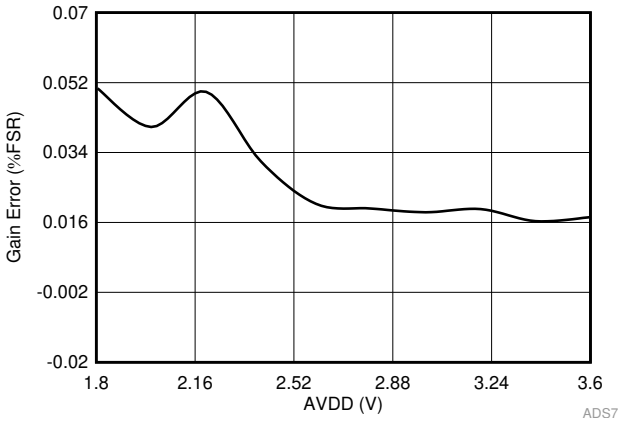


图 16. Gain Error in Manual Mode vs AVDD

版权 © 2018–2019, Texas Instruments Incorporated

Typical Characteristics: Manual Mode (接下页)

at T_A = 25°C, AVDD = 3 V, DVDD = 3.3 V, and two-channel single-ended configuration (unless otherwise noted)

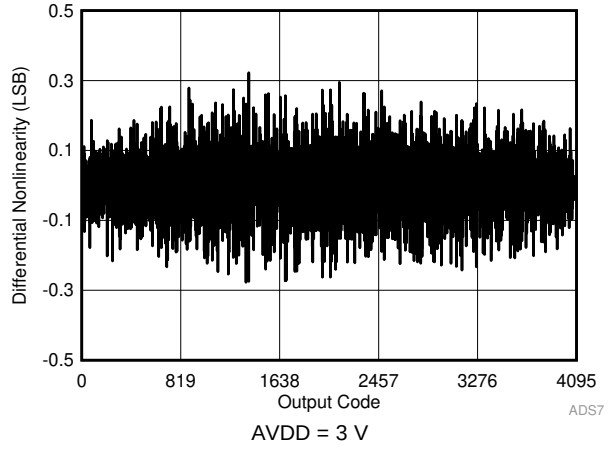


图 17. Typical DNL in Manual Mode

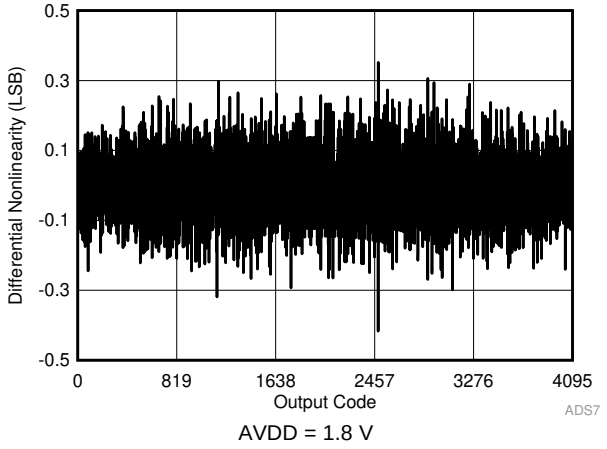


图 18. Typical DNL in Manual Mode

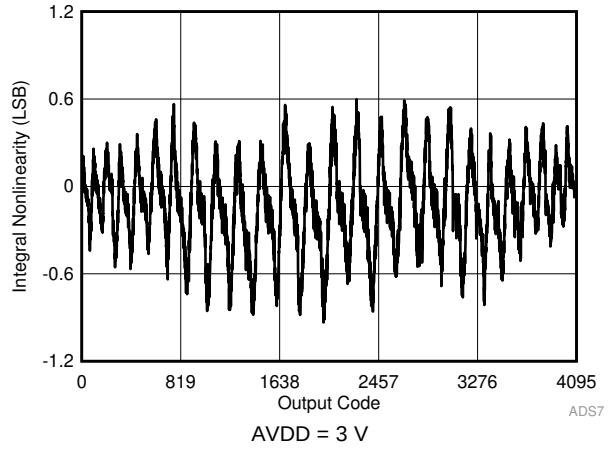


图 19. Typical INL in Manual Mode

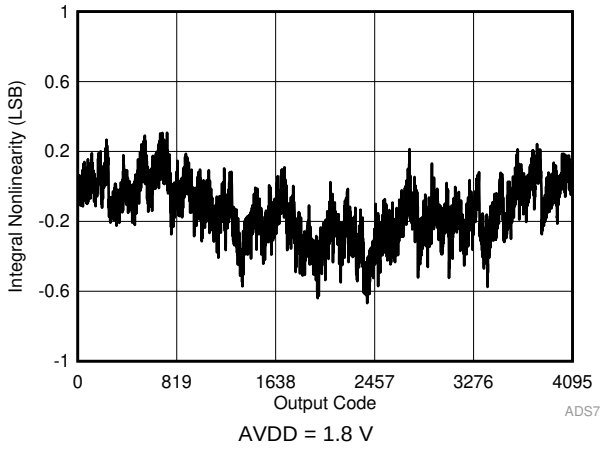


图 20. Typical INL in Manual Mode

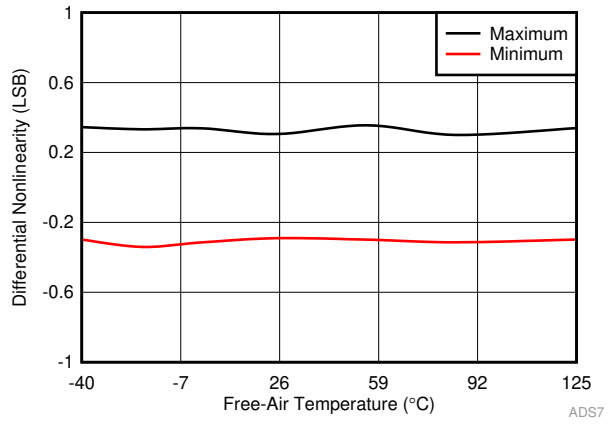


图 21. DNL in Manual Mode vs Temperature

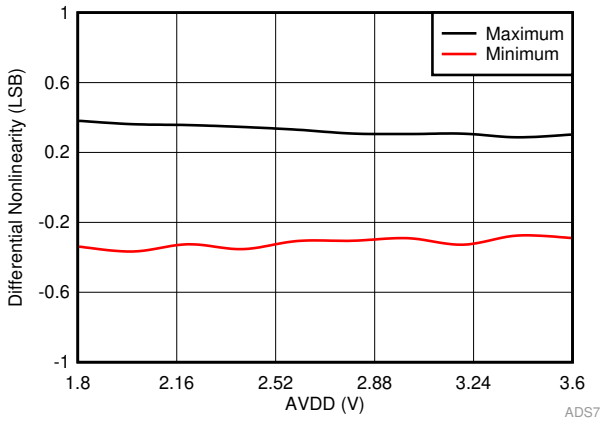


图 22. DNL in Manual Mode vs AVDD

Typical Characteristics: Manual Mode (接下页)

at T_A = 25°C, AVDD = 3 V, DVDD = 3.3 V, and two-channel single-ended configuration (unless otherwise noted)

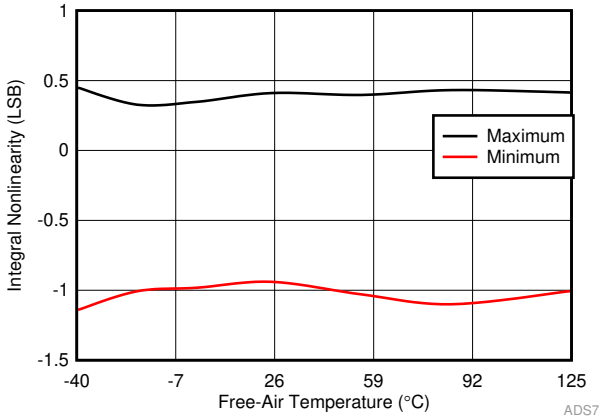


图 23. INL in Manual Mode vs Temperature

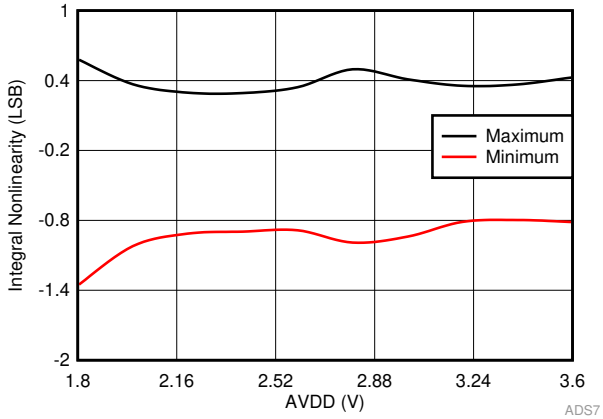
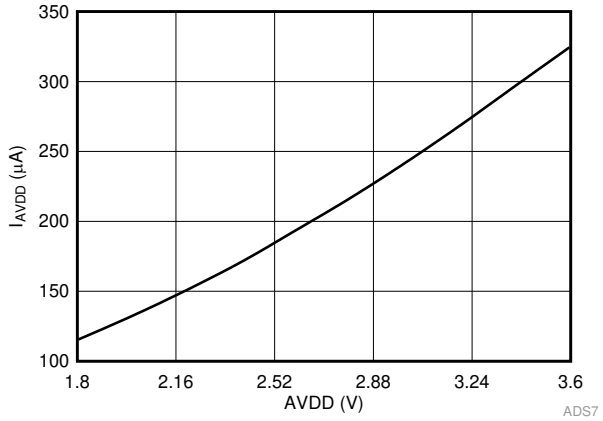


图 24. INL in Manual Mode vs AVDD



f_{Sample} = 140 kSPS, SCL = 3.4 MHz

图 25. I_{AVDD} in Manual Mode vs AVDD

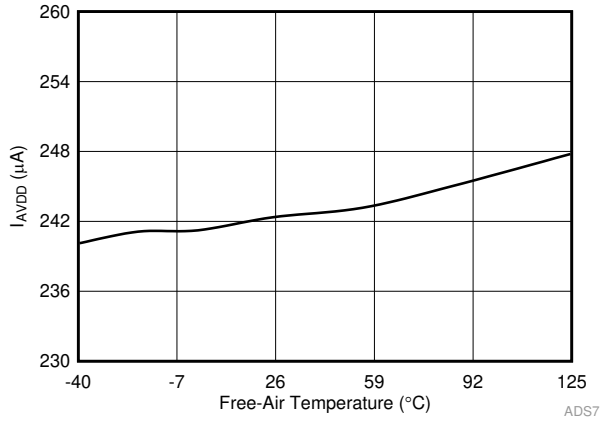
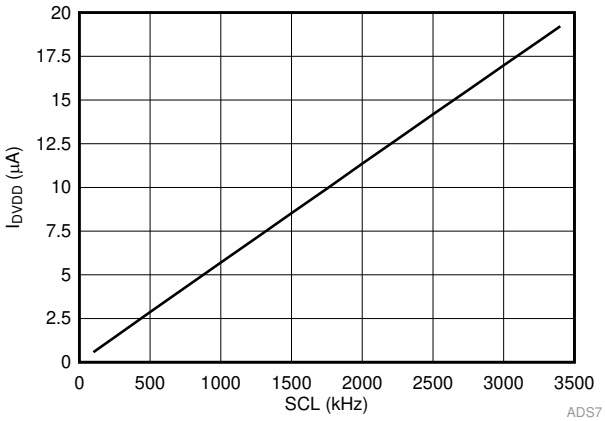
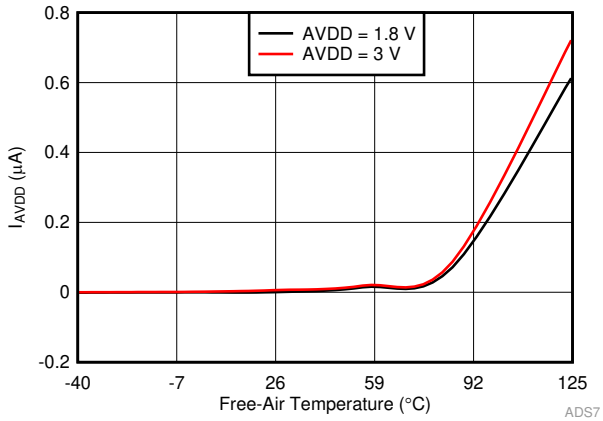


图 26. I_{AVDD} in Manual Mode vs Temperature



DVDD = 1.8 V

图 27. I_{DVDD} in Manual Mode vs SCL



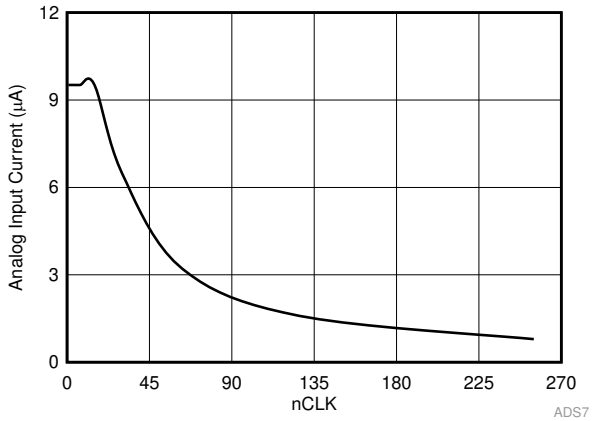
No activity on SCL and SDA

图 28. Static I_{AVDD} in Manual Mode vs Temperature

版权 © 2018–2019, Texas Instruments Incorporated

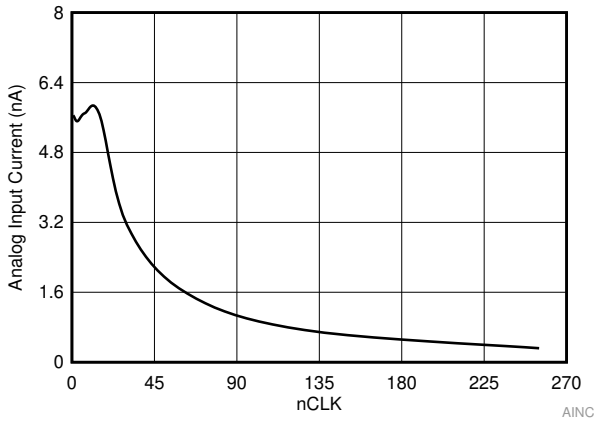
6.13 Typical Characteristics: Autonomous Modes

at T_A = 25°C, AVDD = 3 V, DVDD = 3.3 V, and two-channel single-ended configuration (unless otherwise noted)



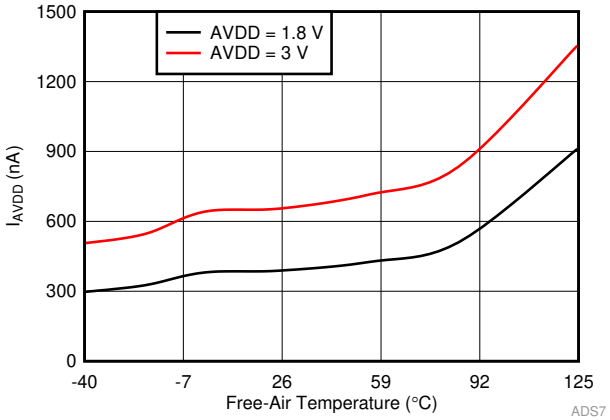
Input voltage = 1.5 V, CH0, high-speed oscillator, stop burst mode

图 29. Analog Input Current in Autonomous Modes vs nCLK



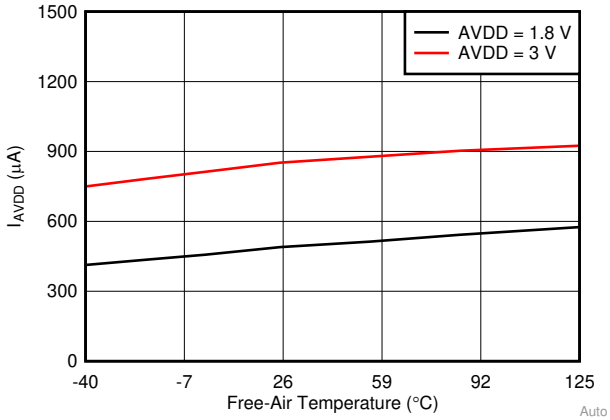
Input voltage = 1.5 V, CH0, low-power oscillator, stop burst mode

图 30. Analog Input Current in Autonomous Modes vs nCLK



Stop burst mode, low-power oscillator, nCLK = 25

图 31. I_{AVDD} in Autonomous Modes vs Temperature



Stop burst mode, high-speed oscillator, nCLK = 25

图 32. I_{AVDD} in Autonomous Modes vs Temperature

6.14 Typical Characteristics: High-Precision Mode

at T_A = 25°C, AVDD = 3 V, DVDD = 3.3 V, and two-channel single-ended configuration (unless otherwise noted)

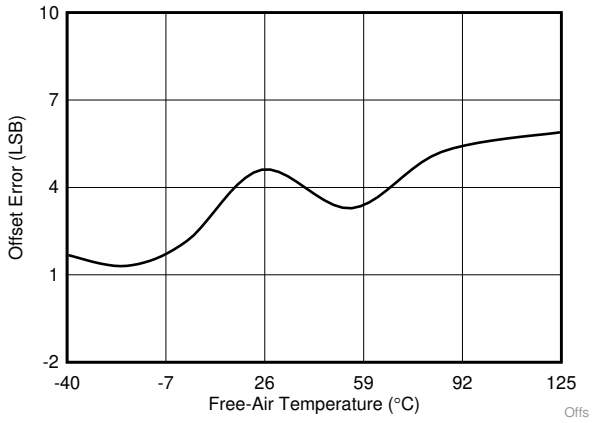


图 33. Offset Error in High-Precision Mode vs Temperature

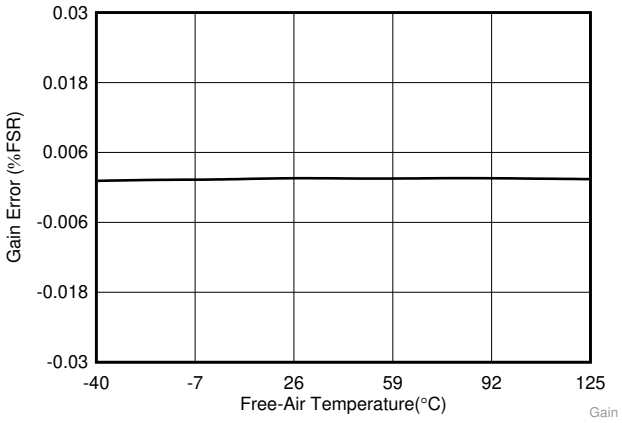
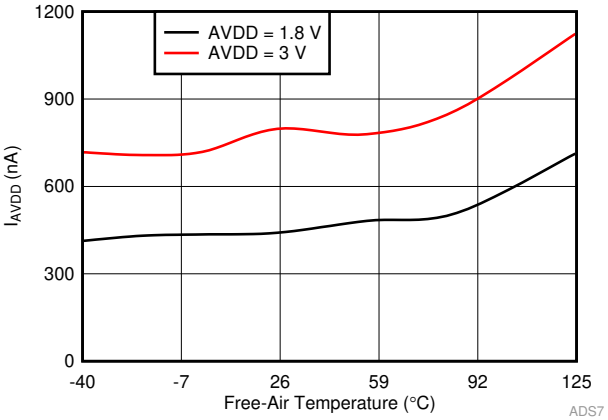
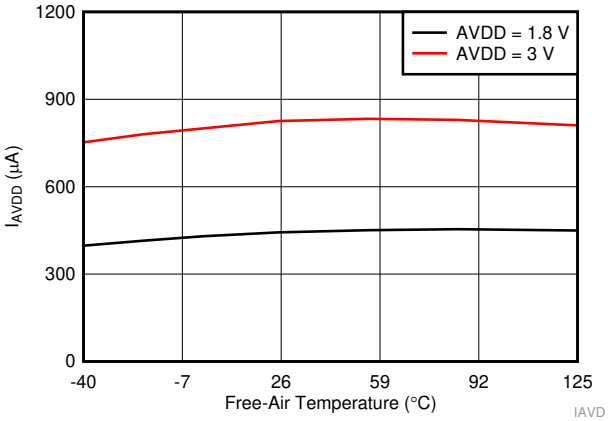


图 34. Gain Error in High-Precision Mode vs Temperature



Low-power oscillator, nCLK = 25

图 35. I_{AVDD} in High-Precision Mode vs Temperature



High-speed oscillator, nCLK = 25

图 36. I_{AVDD} in High-Precision Mode vs Temperature

版权 © 2018–2019, Texas Instruments Incorporated

7 Detailed Description

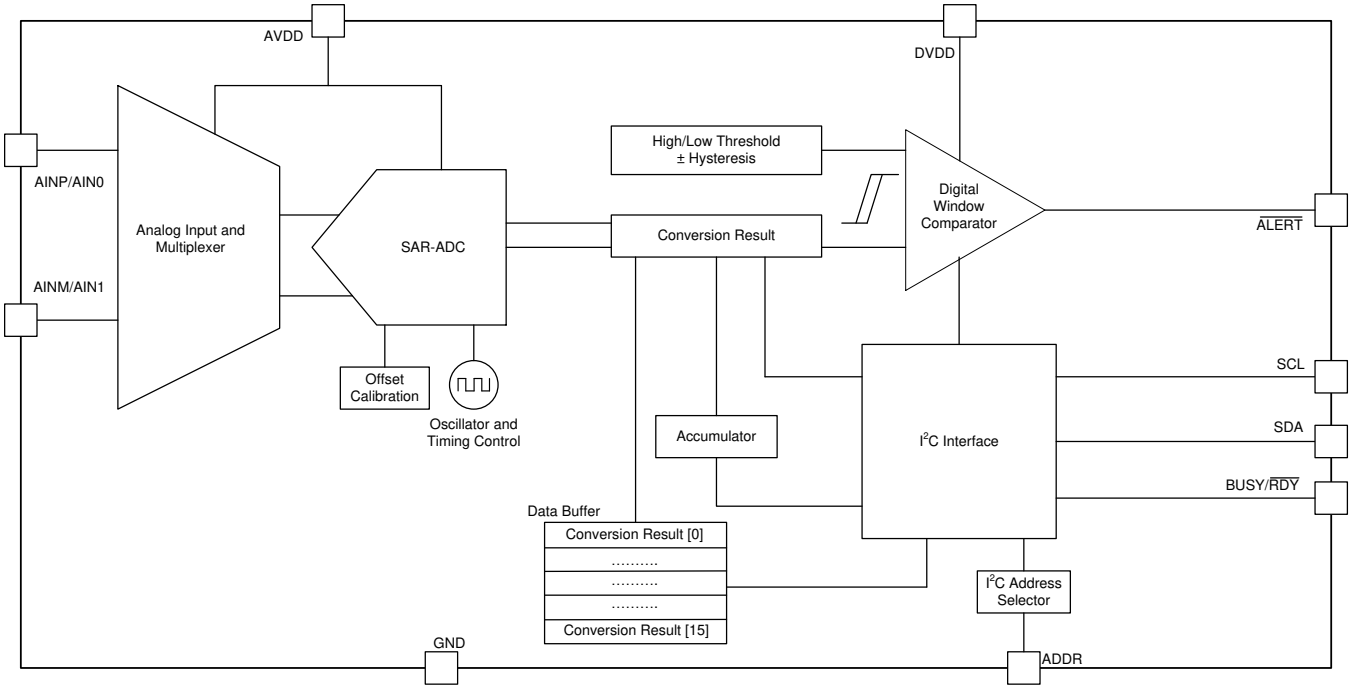
7.1 Overview

The ADS7142-Q1 is a small size, dual-channel, 12-bit programmable sensor monitor with an integrated analog-to-digital converter (ADC), input multiplexer, digital comparator, data buffer, accumulator and internal oscillator. The *input multiplexer* can be either configured as two single-ended channels, one single-ended channel with remote ground sensing, or one pseudo-differential channel where the input can swing to approximately AVDD / 2. The device includes a *digital window comparator* with a dedicated output pin, which can be used to alert the host when a programmed high or low threshold is crossed. The device address is configured by the I2C address selector block. The device uses *internal oscillators* (high speed or low power) for conversion. The start of conversion is controlled by the host in *manual mode* and by the device in the *autonomous modes*.

The device also features a data buffer and an accumulator. The data buffer can store up to 16 conversion results of the ADC in the autonomous modes and the accumulator can accumulate up to 16 conversion results of the ADC in *high-precision mode*.

The device includes an offset calibration to calibration its own offset.

7.2 Functional Block Diagram



7.3 Feature Description

7.3.1 Analog Input and Multiplexer

图 37 shows a small-signal equivalent circuit for the analog input pins. The device includes a two-channel analog multiplexer with each input pin having ESD protection diodes to AVDD and GND. The sampling switches are represented by ideal switches SW_1 and SW_2 in series with resistors R_{s1} and R_{s2} (typically 150 Ω). The sampling capacitors, C_{s1} and C_{s2}, are typically 15 pF. The multiplexer configuration is set by the CH_INPUT_CFG register.

During acquisition, switches SW_1 and SW_2 are closed to allow the input signal to charge the internal sampling capacitors.

During conversion, switches SW_1 and SW_2 are opened to disconnect the input signal from the sampling capacitors.

The analog input of the device are optimized to be driven by high impedance source (up-to 100 kΩ) in *Autonomous Modes* or in *High Precision Mode* mode with low power oscillator. It is recommended to drive the analog input of the device with an external amplifier when in *Autonomous Modes* or in *High Precision Mode* mode with a high-speed oscillator. 图 29 and 图 30 provide the analog input current for CH0 and CH1 of the device.

图 38, 图 39 and 图 40 provide a simplified circuit for analog input for input configurations described in *Two-Channel, Single-Ended Configuration*, *Single-Channel, Single-Ended Configuration* and *Single-Channel, Pseudo-Differential Configuration* respectively. The analog multiplexer supports following input configurations (set by writing into the CH_INPUT_CFG register).

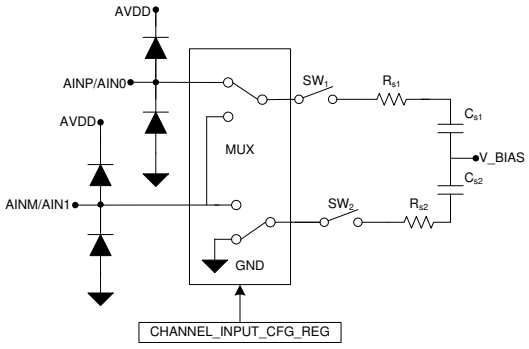


图 37. Equivalent Circuit for Analog Input

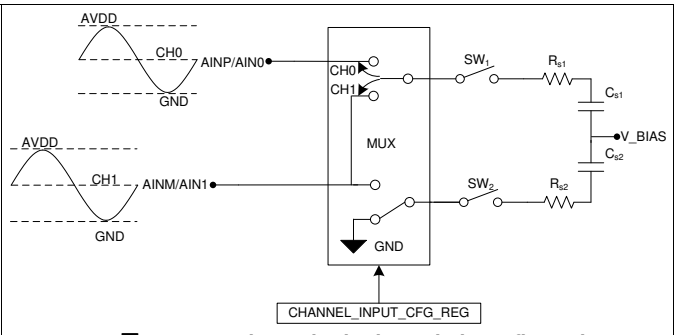


图 38. Two-Channel, Single-Ended Configuration

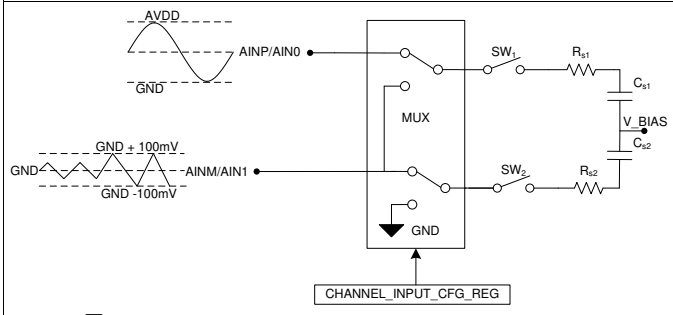


图 39. Single-Channel, Single-Ended Configuration With Remote Ground Sensing

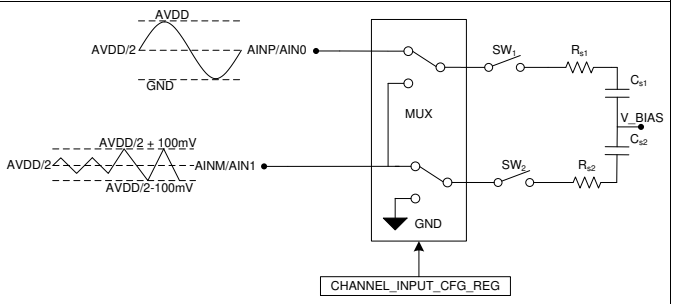


图 40. Single-Channel, Pseudo-Differential Configuration

7.3.1.1 *Two-Channel, Single-Ended Configuration*

图 38 shows a simplified block diagram showing a two-channel, single-ended configuration. Set the CH0_CH1_IP_CFG bits = 00b or 11b to select this configuration. This configuration is also the default for the device after power up. In this configuration, C_{S2} always samples the GND pin and C_{S1} samples the input signal provided on channel 0 (AINP/AIN0) or channel 1 (AINM/AIN1) based on the channel selection. Each analog input channel can accept input signals in the range 0 V to AVDD V.

版权 © 2018–2019, Texas Instruments Incorporated

Feature Description (接下页)

On power-up, the device wakes up in manual mode with two-channel, single-ended configuration and samples CH0 only. This configuration can also be set by setting OPMODE_SEL to 000b or 001b,

The device can be configured to sample either CH0 or CH1 or both channels by setting bits in the AUTO_SEQ_CHEN register to select the channels.

- To select a channel in AUTO sequence, set AUTO_SEQ_CHx bit in the AUTO_SEQ_CHEN register to 1.
- Set the bits in the OPMODE_SEL register to 100b or 101b for manual mode with AUTO sequence.
- Set the bits in the OPMODE_SEL register to 110b for *Autonomous Modes* with AUTO sequence.
- Set the bits in the OPMODE_SEL register to 111b for *High Precision Mode* with AUTO sequence.

7.3.1.2 Single-Channel, Single-Ended Configuration

See 图 39 for a simplified block diagram showing a single-channel, single ended configuration. Set CH0_CH1_IP_CFG bits = 01b to select this configuration. In this configuration, C_{S1} samples the input signal provided on the AINP/AIN0 pin whereas C_{S2} samples input signal provided on the AINM/AIN1 pin. AINP/AIN0 pin can accept input signals in the range 0 V to AVDD V and AINM/AIN1 pin can accept input signals in the range –100 mV to +100 mV. This input configuration is useful in systems where the sensor and/or the signal conditioning block is placed far from the device and there could be a small difference between the ground potentials. In this channel configuration, remove channel 1 from AUTO sequence by setting the AUTO_SEQ_CH1 bit to 0. Selecting channel 1 in AUTO sequence leads to an error condition and the device sets an error flag in the SEQUENCE_STATUS register.

7.3.1.3 Single-Channel, Pseudo-Differential Configuration

See 图 40 for a simplified block diagram showing a single-channel, pseudo-differential configuration. Set CH0_CH1_IP_CFG bits = 10b to select this configuration. In this configuration, C_{S1} samples the input signal provided on the AINP/AIN0 pin whereas C_{S2} samples input signal provided on the AINM/AIN1 pin. AINP/AIN0 pin can accept input signals in the range 0 V to AVDD V and AINM/AIN1 pin can accept input signals in the range (AVDD/2) - 100 mV to (AVDD/2) + 100 mV. This input configuration is useful to interface with sensors that provide pseudo-differential signal with negative output as AVDD/2 like an electrochemical gas sensor. In this channel configuration, remove channel 1 from AUTO sequence by setting the AUTO_SEQ_CH1 bit to 0. Selecting channel 1 in AUTO sequence leads to an error condition and the device sets an error flag in SEQUENCE_STATUS register.

7.3.2 OFFSET Calibration

The offset can be calibrated by setting the TRIG_OFFCAL bit in the OFFSET_CAL register. During offset calibration, the sampling switches are open (图 37) and the device keeps BUSY/RDY pin high. The device calculates its offset error and corrects for this error for subsequent conversions. The device calibrates the offset on power up. To nullify the change in offset due to change in temperature or in AVDD voltage, it is recommended to perform this calibration periodically.

7.3.3 Reference

The device uses the analog supply voltage (AVDD) as a reference for the analog-to-digital conversion process. It is recommended to place a 220-nF, low-ESR ceramic decoupling capacitor between the AVDD pin and the GND pin, close to the AVDD Pin. See *Power Supply Recommendations* section.

7.3.4 ADC Transfer Function

The ADC provides data in straight binary format. The ADC resolution can be computed by 公式 1:

$$1\ LSB = V_{REF} / 2^{N} \quad (1)$$

where:

- V_{REF} = AVDD
- N = 12 for Autonomous Monitoring Modes and Manual Mode

Feature Description (接下页)

图 41 and 图 42 show the ideal transfer characteristics for single-ended input and pseudo-differential input, respectively. 表 1 show the digital output codes for the transfer functions.

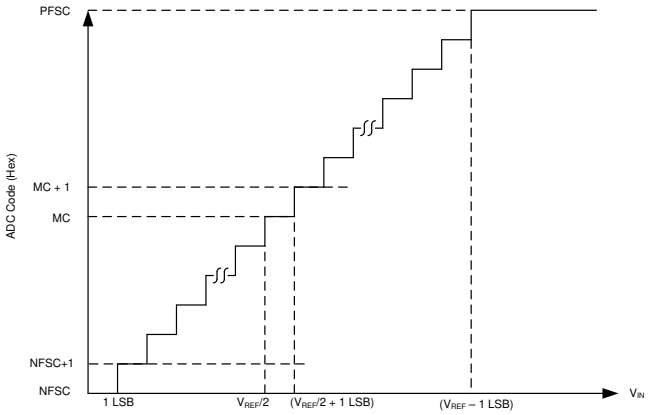


图 41. Ideal Transfer Characteristics for Single-Ended Configurations

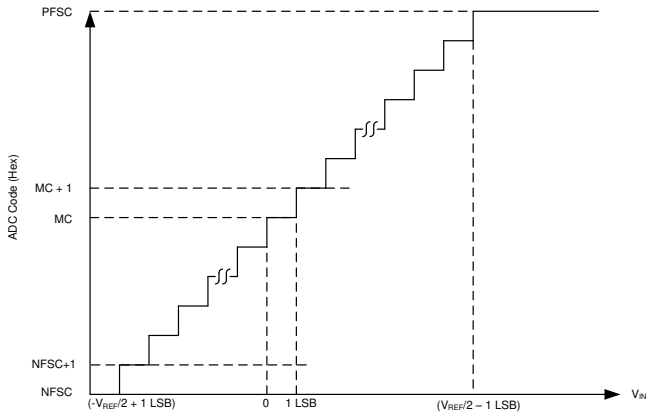


图 42. Ideal Transfer Characteristics for Pseudo-Differential Configuration

表 1. Transfer Characteristics

INPUT VOLTAGE FOR SINGLE-ENDED INPUT	INPUT VOLTAGE FOR PSEUDO DIFFERENTIAL INPUT	CODE	DESCRIPTION	IDEAL OUTPUT CODE (Autonomous Monitoring Mode or Manual Mode)
≤1 LSB	≤ (–V_{REF} / 2 + 1) LSB	NFSC	Negative full-scale code	000
1 LSB to 2 LSBs	(–V_{REF} / 2 + 1) to (–V_{REF} / 2 + 2) LSB	NFSC + 1	—	001
(V_{REF} / 2) to (V_{REF} / 2) + 1 LSB	0 LSB to 1 LSB	MC	Mid code	800
(V_{REF} / 2) + 1 LSB to (V_{REF} / 2) + 2 LSBs	1 LSB to 2 LSB	MC + 1	—	801
≥ V_{REF} – 1 LSB	≥ V_{REF} / 2 – 1 LSB	PFSC	Positive full-scale code	FFF

7.3.5 Oscillator and Timing Control

The device uses one of the two internal oscillators (low power oscillator or high speed oscillator) for converting the analog input voltage into a digital output code.

The steps for selecting the oscillator and setting the sampling speed are listed below:

1. Select the low power oscillator (OSC_SEL = 1b) to monitor slow moving signals (< 300 Hz) at extremely low power consumption and sampling speeds (< 600 SPS). Select the high speed oscillator (OSC_SEL = 0b) to scan the sensor signals with faster sampling speed (> 50 kHz).
2. Set sampling speed by programming the NCLK_SEL register:

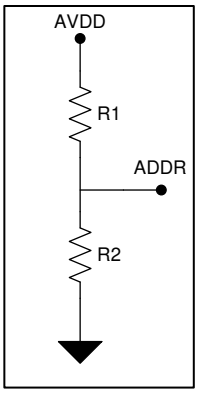
$$f_S = \frac{Oscillator\ frequency}{nCLK} \quad (2)$$

- f_s = Sampling speed
- Oscillator frequency = 1 / t_{HSO} or 1 / t_{LPO} depending on the OSC_SEL bit; see the *Specifications* section for 1 / t_{HSO} or 1 / t_{LPO}
- nCLK is number of clocks in one conversion cycle (see the NCLK_SEL register)

版权 © 2018–2019, Texas Instruments Incorporated

7.3.6 I²C Address Selector

The I²C address for the device is determined by connecting external resistors on ADDR pin. The device address are selected on power-up based on the resistor values. The device retains this address until the next power up, or until next device reset, or until the device receives a command to program its own address (*General Call With Write Software Programmable Part of Slave Address*). 图 43 provides the connection diagram for the ADDR pin and 表 2 provides the resistor values for selecting different addresses of the device.



Copyright © 2017, Texas Instruments Incorporated

图 43. External Resistor Connection Diagram for ADDR Pin

表 2. I²C Address Selection

RESISTORS		ADDRESS
R1 (1)	R2 (1)	
0 Ω	DNP (2)	0011111b (1Fh)
11 kΩ	DNP (2)	0011110b (1Eh)
33 kΩ	DNP (2)	0011101b (1Dh)
100 kΩ	DNP (2)	0011100b (1Ch)
DNP (2)	0Ω or DNP (2)	0011000b (18h)
DNP (2)	11 kΩ	0011001b (19h)
DNP (2)	33 kΩ	0011010b (1Ah)
DNP (2)	100 kΩ	0011011b (1Bh)

(1) Tolerance for R1, R2 < ±5%.
(2) DNP = Do not populate.

7.3.7 Data Buffer

When operating in autonomous monitoring mode, the device can use the internal data buffer for data storage. The internal data buffer is 16-bit wide and 16-word deep and follows the first-in, first-out (FIFO) approach.

7.3.7.1 Filling of the Data Buffer

The write operation to the data buffer starts and stops as per the settings in the DATA_BUFFER_OPMODE register. The DATA_BUFFER_STATUS register provides the number of entries filled in the data buffer and this register can be read during an active sequence to get the current status of the data buffer. The time between two consecutive conversions is set by the NCLK_SEL register and 公式 3 provides the relationship for time between two consecutive conversions of the same channel and nCLK parameter.

$$t_{cc} = k \times nCLK \times OscillatorTimePeriod \quad (3)$$

where

- t_{cc} = Time between two consecutive conversions of same channel, $t_{cc} = k \times t_{cycle}$
- k = Number of channels enabled in the device sequence
- nCLK = Number of clocks used by device for one conversion cycle
- Oscillator timer period = t_{LPO} or t_{HSO} depending on the OSC_SEL value; see the *Specifications* section for t_{LPO} or t_{HSO}

The format of the 16-bit contents of each entry in the data buffer are set by programming the DOUT_FORMAT_CFG register. The DATA_OUT_CFG register enables the channel ID and DATA_VALID flag in data buffer. Channel ID represents the channel number for the data entry in the data buffer. DATA_VALID is set to zero in either of the following conditions:

- If the entry in the data buffer is not filled after the last start of sequence.
- If the I^2C master tries to read more than 16 entries from the data buffer, the device provides zeros with DATA_VALID set to zero

At the end of the write operation, the data buffer always has results of 16 (or lesser) consecutive conversions. The data buffer is filled in the order that the data is converted by the ADC. The channels converted by the ADC are controlled by the AUTO_SEQ_CHEN register. The entries that are not filled during an active sequence are filled with zeros.

7.3.7.2 Reading Data From the Data Buffer

The device brings the BUSY/$\overline{RDY}$ pin low after completion of the sequence or after the SEQ_ABORT bit is set. As illustrated in 图 44, the device provides the contents of the data buffer (in FIFO fashion) on receiving I^2C read frame, which consists of the device address and the read bit set to 1.

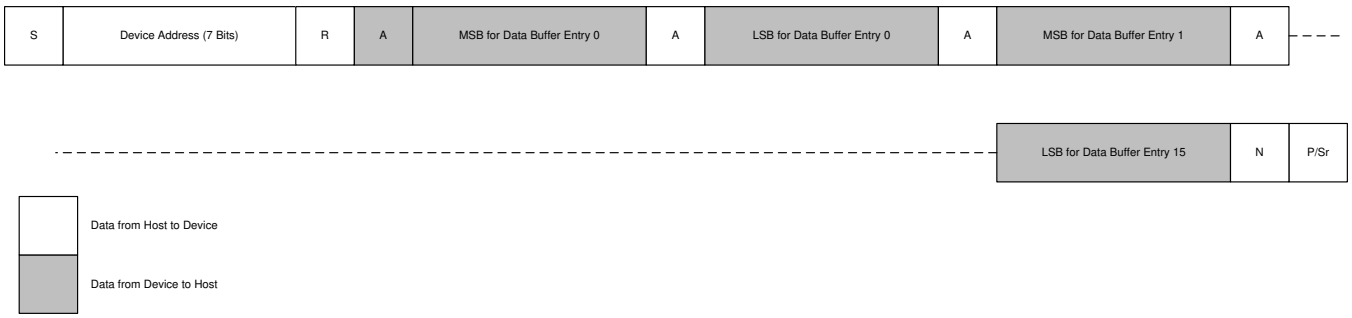


图 44. Reading Data Buffer (16 Bit Words × 16 Words)

The device returns zeroes with DATA VALID flag set to zero for all I^2C read frames received after all the valid data words from the data buffer are read or when a I^2C read frame is issued during an active sequence (indicated by high on the BUSY/$\overline{RDY}$ pin). The I^2C master needs to provide a NACK followed by a STOP or RESTART condition in an I^2C frame to finish the reading process. The data buffer is reset by setting the SEQ_START bit or after resetting the device.

版权 © 2018–2019, Texas Instruments Incorporated

7.3.8 Accumulator

When operating in *High Precision Mode*, the device offers a 16-bit internal accumulator per channel. The Accumulator for a channel is enabled only if that channel is selected in the channel scanning sequence. The accumulator adds sixteen 12-bit conversion results. The result of adding 16 twelve bit words is one 16 bit word that has an effective resolution of an 16-bit ADC. The time between two consecutive conversions for accumulation is controlled by the NCLK_SEL register and 公式 3 provides the relationship for time between two consecutive conversions of same channel and nCLK parameter.

The accumulated data can be read from the ACC_CHx_MSB and ACC_CHx_LSB registers in the device. The ACCUMULATOR_STATUS register provides the number of accumulations done in the accumulator since last conversion. This register can be read during an active sequence to get the current status of the accumulator. The accumulator is reset on setting the SEQ_START bit and on resetting the device. 公式 4 provides the relationship between high precision data and ADC conversion results.

$$\text{High Precision Data for CHx} = \sum_{k=1}^{16} \text{Conversion Result[k] for CHx} \tag{4}$$

公式 5 provides the value of LSB in high precision mode for the accumulated result.

$$1\ LSB = \frac{AVDD}{2^{16}} \tag{5}$$

7.3.9 Digital Window Comparator

The internal digital window comparator is available in all modes. In *Autonomous Modes* with Thresholds monitoring and Diagnostics, the digital window comparator controls the filling of the data and the output of the alert pin and in other modes, it only controls the output of the $\overline{\text{ALERT}}$ pin. 图 45 provides the block diagram for digital window comparator.

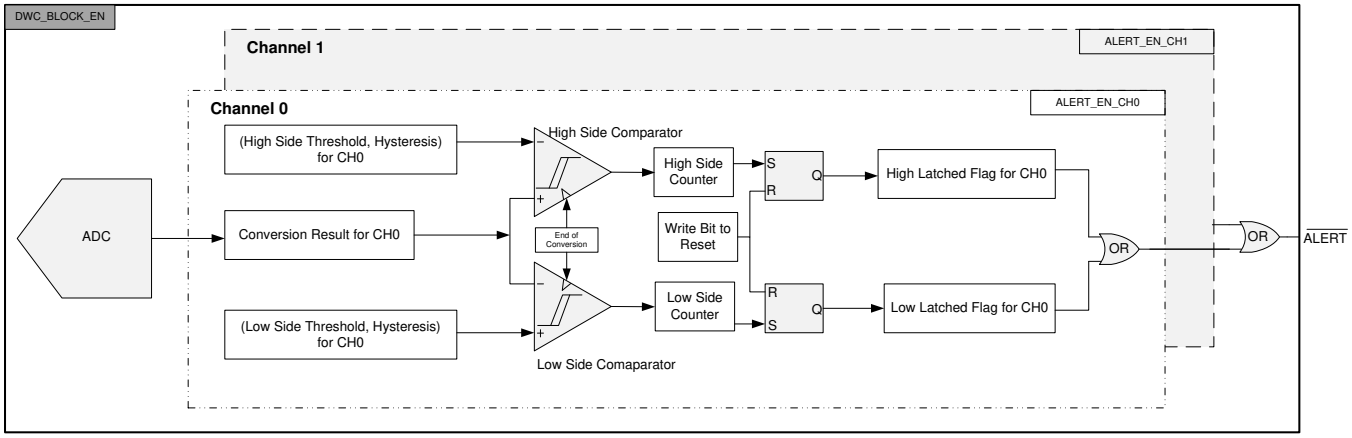


图 45. Digital Comparator Block Diagram

The low side threshold, high side threshold, and hysteresis parameters are independently programmable for each input channel. 图 46 shows the comparison thresholds and hysteresis for the two comparators. A pre-alert event counter after each comparator counts the output of the comparator and sets the latched flags. The pre-alert event counter settings are common to the two channels.

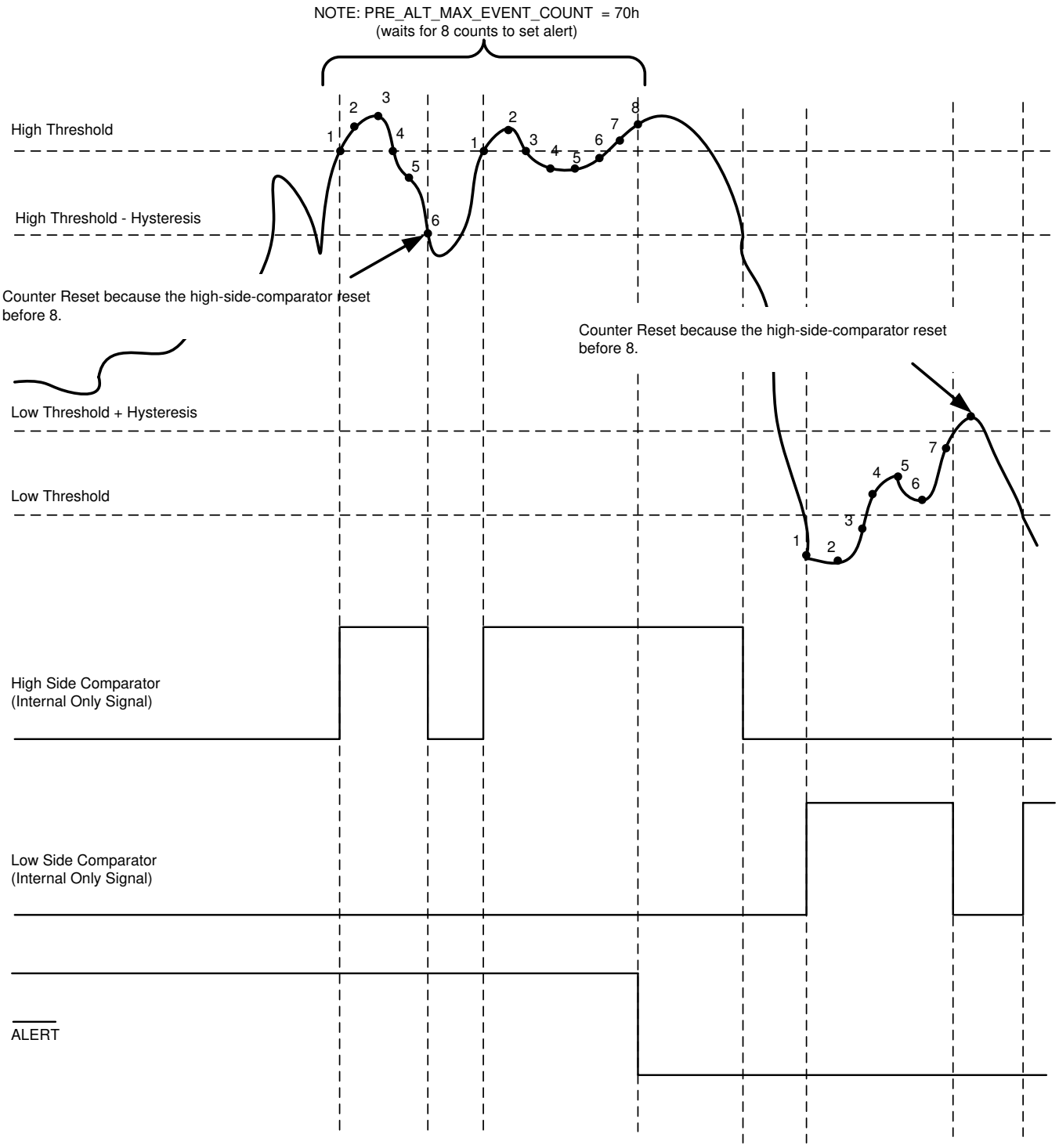


图 46. Thresholds, Hysteresis and Event Counter for Digital Window Comparator

The DWC_BLOCK_EN bit in ALERT_DWC_EN register enables/disables the complete digital window comparator block (disabled at power-up) and ALERT_EN_CHx bits in the ALERT_CHEN register enables digital window comparator for individual channels. When enabled, whenever a new conversion result is available:

1. The output of the high side comparator transitions to logic high when the conversion result is greater than the high threshold. This comparator resets when the conversion result is less than the high threshold – hysteresis.

版权 © 2018–2019, Texas Instruments Incorporated

2. The output of the low side comparator transitions to logic high when the conversion result is less than the low threshold. This comparator resets when the conversion result is greater than the low threshold + hysteresis.
3. A different threshold and hysteresis can be used for each channel.
4. When the output of either the high side or low side comparator transitions high the pre-alert event counter begins to increment for each subsequent conversion. This counter continues to increment until it reaches the value stored in the PRE_ALT_MAX_EVENT_COUNT register. When it reaches PRE_ALT_MAX_EVENT_COUNT, the alert becomes active and sets the latched flags. If the comparator output becomes zero before counter reaches PRE_ALT_MAX_EVENT_COUNT, then the event counter is reset to zero, Alert does not be set and latched flag is not set.

Therefore, the latched flags (high and low) for the channel are updated only if the respective comparator output remains 1 for the specified number of consecutive conversions (set by PRE_ALT_MAX_EVENT_COUNT).

The latched flags can be read from the ALERT_LOW_FLAGS and ALERT_HIGH_FLAGS registers. To clear a latched flag, write 1 to the applicable bit location. The $\overline{\text{ALERT}}$ pin status is re-evaluated whenever an applicable latched flag gets set or is cleared.

The response time for $\overline{\text{ALERT}}$ pin can be estimated by 公式 6

$$t_{response} = [1 + k \times (PRE_ALT_MAX_EVENT_COUNT + 1)] \times nCLK \times Oscillator\ TimePeriod \quad (6)$$

where

- k = Number of channels enabled in device sequence
- nCLK = Number of clocks used by device for one conversion cycle
- Oscillator timer period = t_{LPO} or t_{HSO} depending on the OSC_SEL value; see the *Specifications* section for t_{LPO} or t_{HSO}

7.3.10 I²C Protocol Features

7.3.10.1 General Call

On receiving a general call (00h), the device provides an ACK.

7.3.10.2 General Call With Software Reset

On receiving a general call (00h) followed with Software Reset (06h), the device resets itself.

7.3.10.3 General Call With Write Software Programmable Part of Slave Address

On receiving a general call (00h) followed by 04h, the device configures its own I²C address configured by the ADDR pin. During this operation, the device keeps BUSY/$\overline{\text{RDY}}$ Pin high and does not respond to other I²C commands except general call.

7.3.10.4 Configuring the Device Into High-Speed I²C Mode

The device can be configured in high-speed I²C mode by providing an I²C frame with one of the HS-mode master codes (08h to 0Fh).

After receiving one of the HS-mode master codes, the device sets the HS_MODE bit in the OPMODE_I2CMODE_STATUS register and remains in high-speed I²C mode until a STOP condition is received in an I²C frame.

7.3.10.5 Bus Clear

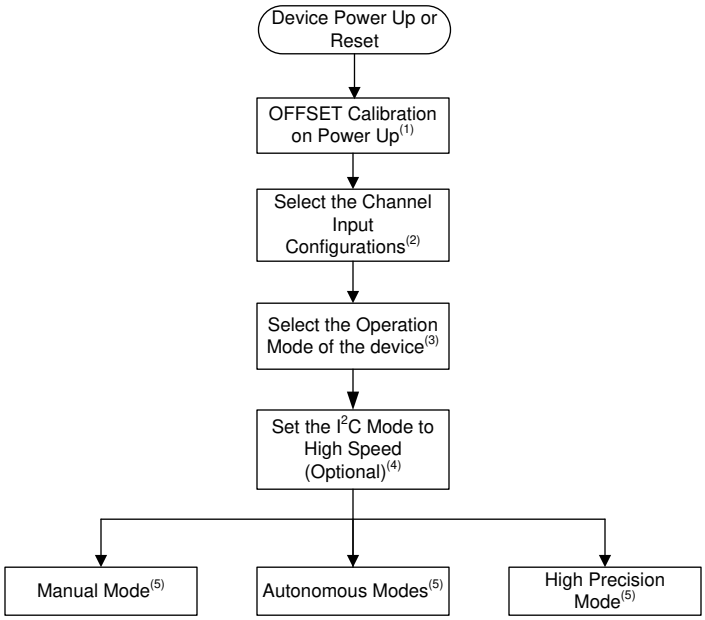
If the SDA line is stuck low because of an incomplete I²C frame, providing nine clocks on SCL is recommended. The device releases the SDA line within these nine clocks, and then the next I²C frame can be started.

7.4 Device Functional Modes

The device has below functional modes:

- Manual mode
- Autonomous modes:
  - Autonomous mode with threshold monitoring and diagnostics
  - Autonomous mode with burst data
- High-precision mode

Device powers up in manual mode and can be configured into one of the other modes of these modes by writing the configuration registers for the desired mode. Steps for configuring device into different modes are illustrated in 图 47



(1) Offset can also be calibrated anytime during normal operation by setting the bit in the OFFSET_CAL register.
(2) Configure the CH_INPUT_CFG register.
(3) Configure the OPMODE_SEL register for the desired operation mode.
(4) See the *Configuring the Device Into High-Speed I²C Mode* section.
(5) Operating mode is selected by configuring the OPMODE_SEL register in step 3.
(6) For reading and writing registers, see the *Programming* section.

图 47. Configuring Device Into Different Modes

7.4.1 Device Power Up and Reset

On power up, the device calibrates its own offset and calculates the address from the resistors connected on ADDR pin. During this time, the device keeps BUSY/$\overline{\text{RDY}}$ high.

The device can be reset by recycling power on AVDD pin, by general call (00h) followed by software reset (06h), or by writing the WKEY register followed by setting the bit in the DEVICE_RESET register.

Recycling power on the AVDD pin and on general call (00h) followed by software reset (06h), all the device configurations are reset, and the device initiates offset calibration and re-evaluates its I^2C address.

When setting the bit in DEVICE_RESET register, all the device configurations except latched flags for the digital window comparator and the WKEY register are reset, The device does not initiate offset calibration and does not re-evaluate its I^2C address.

版权 © 2018–2019, Texas Instruments Incorporated

Device Functional Modes (接下页)

7.4.2 Manual Mode

On power-up, the device is in Manual Mode using the single ended and dual channel configuration and starts by sampling the analog input applied on channel 0. In this mode, the device uses the high frequency oscillator for conversions. Manual mode allows the external host processor to directly request and control when the data is sampled. The data capture is initiated by an I^2C command from the host processor and the data is then returned over the I^2C bus at a throughput rate of up to 140-kSPS. Applications that can take advantage of this type of functionality include traditional ADC applications that require 1 or 2 channels of continuous data output.

After setting the operation mode to manual mode as illustrated in 图 47, steps for operating the device to be in manual mode and reading data are illustrated in 图 48. The host can either configure the device to scan through one channel or both channels by configuring the CH_INPUT_CFG register and AUTO_SEQ_CHEN register.

7.4.2.1 Manual Mode With CH0 Only

Set the OPMODE_SEL register to 000b or 001b for manual mode with channel 0 only. The host must provide the device address and read bit to start the conversions. To continue with conversions and reading data to the host must provide continuous SCL (图 49). In this mode, a NACK followed by a STOP condition in I^2C frame is required to abort the operation. Then the device operation mode can be changed to another operation mode.

7.4.2.2 Manual Mode With AUTO Sequence

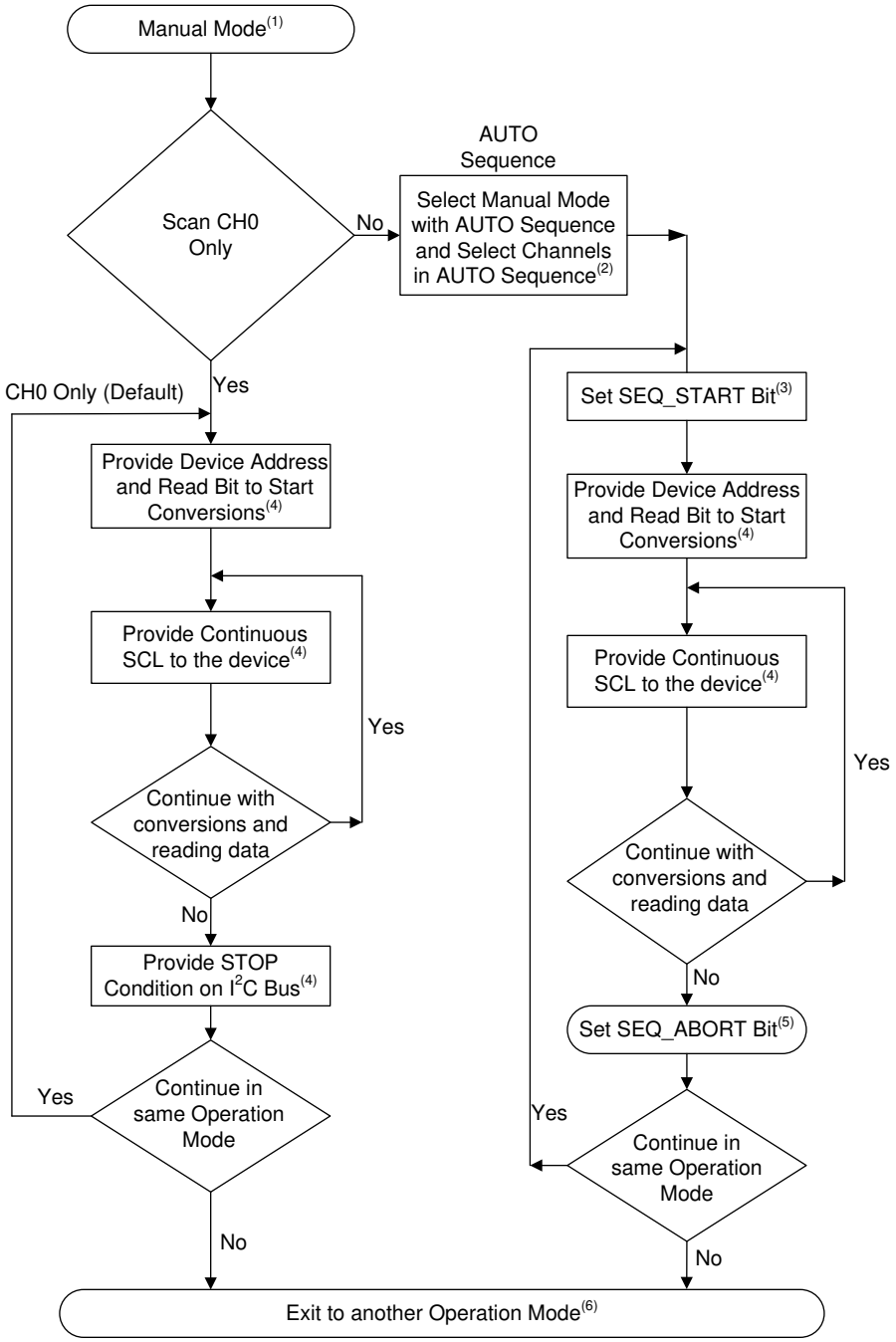
Set the OPMODE_SEL register to 100b or 101b for manual mode with AUTO Sequence. The host must set the SEQ_START bit in the START_SEQUENCE register and provide the device address and read bit to start the conversions. To continue with conversions and reading data, the host must provide continuous SCL (图 49). In this mode, the SEQ_ABORT bit in the ABORT_SEQUENCE register must be set to abort the operation. Then the device operation mode can be changed to another operation mode. In this mode, a register read aborts the AUTO sequence.

In manual mode, the device always uses the high-speed oscillator and the nCLK parameter has no effect. The maximum scan rate is given by 公式 7:

$$f_S = \frac{1000}{\left[18 \times T_{SCL} + k\right]} \quad (7)$$

- f_s = Maximum sampling speed in kSPS
- T_{SCL}= Time period of SCL clock (in µs)
- if $T_{SCL\text{-}LOW}$ (Low period of SCL) < 1.8.µs, k = (1.8 - $T_{SCL\text{-}LOW}$) and the device stretches clock in manual mode; not applicable for standard I^2C mode (100 kHz)
- if $T_{SCL\text{-}LOW}$ (low period of SCL) ≥ 1.8.µsec, k = 0 and the device does not stretch clock in manual mode

Device Functional Modes (接下页)



(1) For setting the operation mode to manual mode, see 图 47.

(2) Select manual mode with AUTO sequence in OPMODE_SEL register. Select channels in the AUTO_SEQ_CHEN register.

(3) Set the bit SEQ_START bit in the START_SEQUENCE register.

(4) See 图 49.

(5) Set the bit SEQ_ABORT bit in the ABORT_SEQUENCE register.

(6) Select another operation mode in the OPMODE_SEL register.

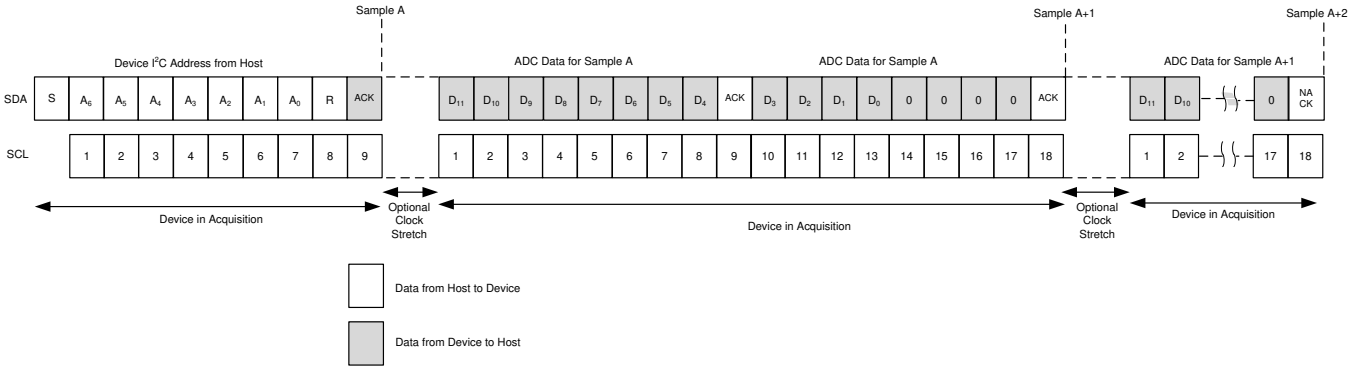
(7) For reading and writing registers, see the *Programming* section.

图 48. Device Operation in Manual Mode

版权 © 2018–2019, Texas Instruments Incorporated

Device Functional Modes (接下页)

Data can be read from the device by providing a device address and read bit followed by continuous SCL as shown in 图 49.



(1) See 公式 7 for sampling speed in manual mode.

(2) If the device scans both channels in AUTO sequence, first data (for sample A) is from channel 0 and second data (for sample A +1) is from channel 1.

图 49. Starting Conversion and Reading Data in Manual Mode

7.4.3 Autonomous Modes

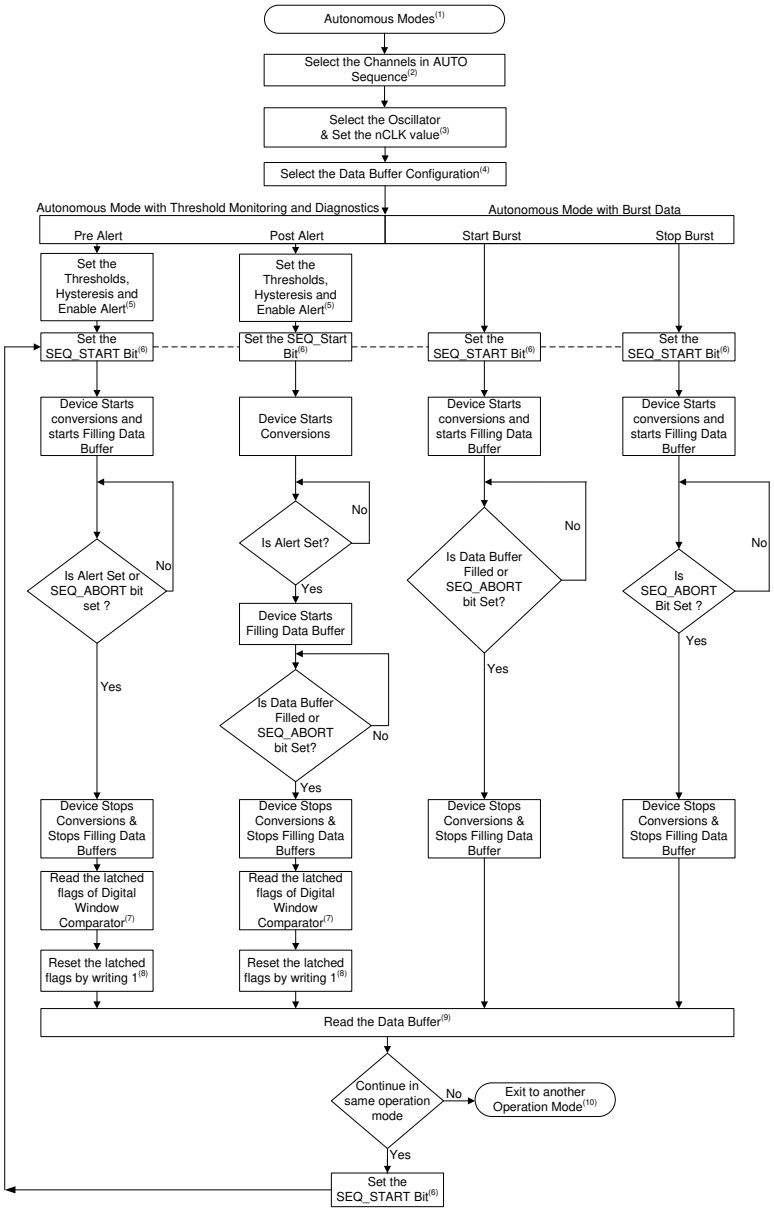
In autonomous mode, the device can be programmed to monitor the voltage applied on the analog input pins of the device and generate a signal on the $\overline{\text{ALERT}}$ pin when the programmable high or low threshold values are crossed and store the conversion results in the data buffer before or after the crossing a threshold or before setting the SEQ_ABORT bit (start burst) in the ABORT_SEQUENCE register or after setting the START_SEQUENCE bit in the START_SEQUENCE register.

In autonomous mode, the device generates the start of conversion using the internal oscillator. The first start of conversion must be provided by the host and the device generates the subsequent start of conversions.

After configuring the operation mode to autonomous mode (set the OPMODE_SEL register to 110b) as illustrated in 图 47, steps for operating the device to be in different autonomous modes are illustrated in 图 50.

版权 © 2018–2019, Texas Instruments Incorporated

Device Functional Modes (接下页)



(1) For setting the operation mode to Autonomous modes, see 图 47.

(2) Select channels in the AUTO_SEQ_CHEN register.

(3) Select the oscillator by configuring the OSC_SEL register and configure the NCLK_SEL register.

(4) Select the data buffer mode in the DATA_BUFFER_OPMODE register.

(5) Configure the thresholds in the DWC_xTH_CHx_xxx registers and hysteresis in the DWC_HYS_CHx registers. Enable the alert for channels in the ALERT_CHEN register and set the DWC_BLOCK_EN bit in the ALERT_DWC_EN register.

(6) Set the bit SEQ_START bit in the START_SEQUENCE register.

(7) Read the ALERT_LOW_FLAGS and/or ALERT_HIGH_FLAGS registers.

(8) Reset the ALERT_LOW_FLAGS and/or ALERT_HIGH_FLAGS registers by writing 03h.

(9) See the *Reading Data From the Data Buffer* section.

(10) Select another operation mode in the OPMODE_SEL register.

(11) For reading and writing registers, see the *Programming* section.

图 50. Configuring Device in Autonomous Modes

版权 © 2018–2019, Texas Instruments Incorporated

Device Functional Modes (接下页)

TI recommends aborting the present sequence by setting the SEQ_ABORT bit in the ABORT_SEQUENCE register before changing the device operation mode or device configuration.

7.4.3.1 Autonomous Mode With Threshold Monitoring and Diagnostics

The threshold monitoring mode automatically scans the input voltage on the input channels and generates a signal when the programmable high or low threshold values are crossed. This mode is useful for applications where the output of the sensor must be continuously monitored and action only taken when the sensor output deviates outside of an acceptable range. Applications that could take advantage of this type of functionality include wireless sensor nodes, environmental sensors, smoke and heat detectors, motion detectors, and so on.

In this mode, the data buffer can be configured to store the conversion results of the ADC in two different ways.

7.4.3.1.1 Autonomous Mode With Pre Alert Data

In this mode, the device stores the sixteen conversion prior to the activation of the alert. Upon activation of ALERT, conversion stops. For this mode, set DATA_BUFFER_OPMODE to 100b. In this mode, the device starts converting and stores the data on setting the SEQ_START bit in the START_SEQUENCE register and continues to store the data into the data buffer until one of the digital comparator flags is set for crossing a high threshold or a low threshold for the channels selected in the sequence. If the SEQ_ABORT bit is set before the data buffer is filled, the device aborts the sequence and stops storing the conversion results. If more than 16 conversions occur between start of sequence and alert output, the first entries written into the data buffer are over-written.

图 51 and 图 52 show the filling of data buffer in autonomous mode with Pre alert Data.

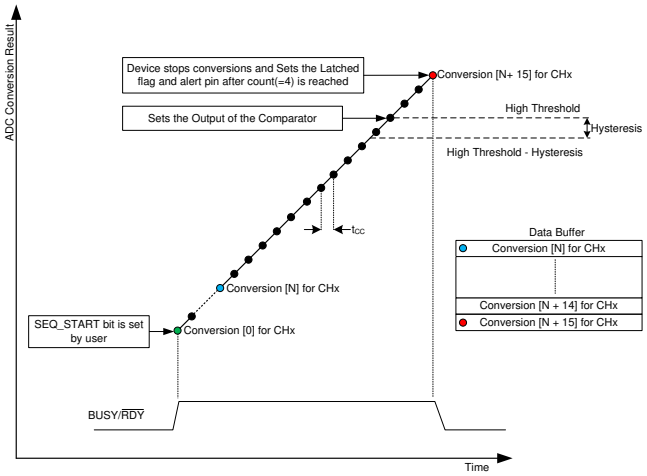


图 51. Pre Alert Data for Single Channel Configurations

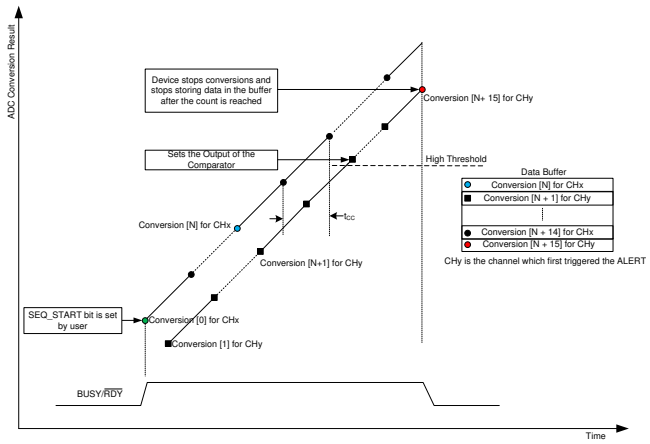


图 52. Pre Alert Data for Dual Channel Configuration

7.4.3.1.2 Autonomous Mode With Post Alert Data

In this mode, the device captures the next sixteen conversion results after the Alert is active. Once these sixteen conversions are stored in the data buffer, all conversion stops. For this mode, Set DATA_BUFFER_OPMODE to 110b. In this mode, the device starts converting the data on setting the SEQ_START bit and stores the data in the data buffer when one of the digital comparator flags is set after the crossing a high threshold or a low threshold for the channels selected in the sequence. if the SEQ_ABORT bit is set before the data buffer is filled, the device aborts the sequence and stops storing the conversion results.

图 53 and 图 54 show the filling of the data buffer in autonomous mode with Post Alert Data.

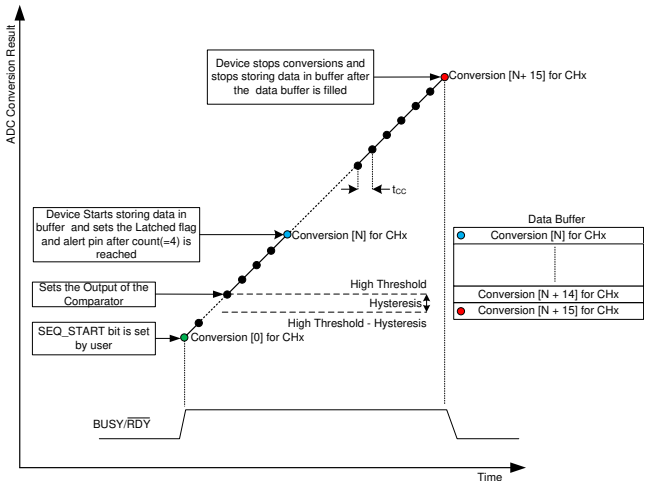


图 53. Post Alert Data for Single Channel Configurations

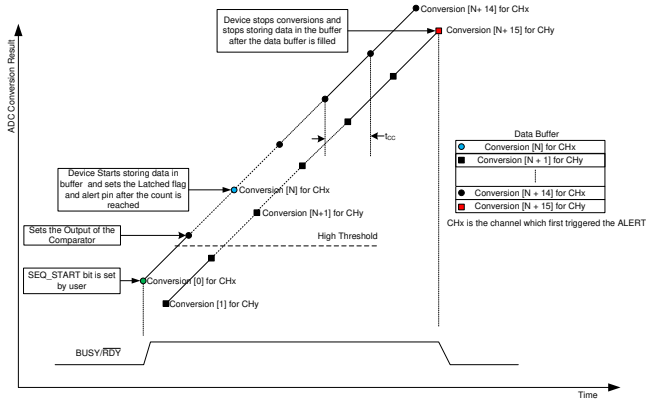


图 54. Post Alert Data for Dual Channel Configuration

版权 © 2018–2019, Texas Instruments Incorporated

7.4.3.2 Autonomous Mode With Burst Data

In this mode, the device can be configured to store up-to 16 conversion results in the data buffer based on user command. Applications that could take advantage of this mode are remote data loggers, environmental sensing and patient monitors. In this mode, the user can either start the burst or stop the burst of data as described in the following sections:

7.4.3.2.1 Autonomous Mode With Start Burst

For this mode, set DATA_BUFFER_OPMODE to 001b. With Start Burst, the user can configure the device to start the filling of data buffer with conversion results by setting the SEQ_START bit and the device stops converting data and filling the data buffer after the data buffer is filled.

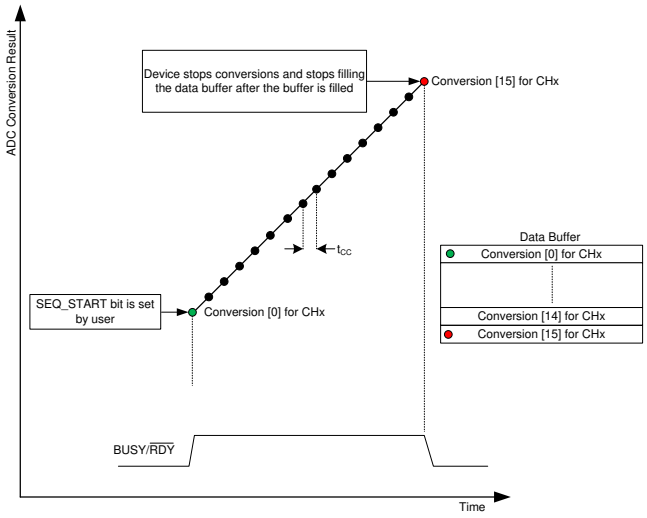


图 55. Start Burst with Single Channel Configurations

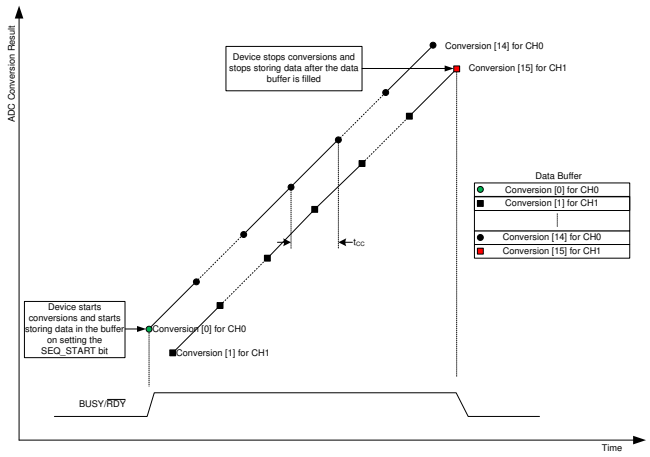


图 56. Start Burst with Dual Channel Configuration

7.4.3.2.2 Autonomous Mode With Stop Burst

For this mode, Set DATA_BUFFER_OPMODE to 000b. With Stop Burst, the user can configure the device to stop filling the data buffer with conversion results by setting the SEQ_ABORT bit. If more than 16 conversions occur between start of sequence and abort of sequence, the entries first written into the data buffer are over-written. 图 57 and 图 58 illustrate the filling of the data buffer in autonomous mode with Stop Burst.

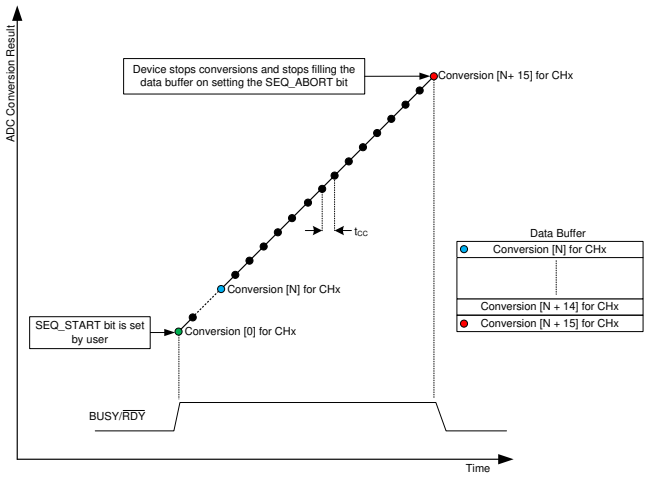


图 57. Stop Burst with Single Channel Configurations

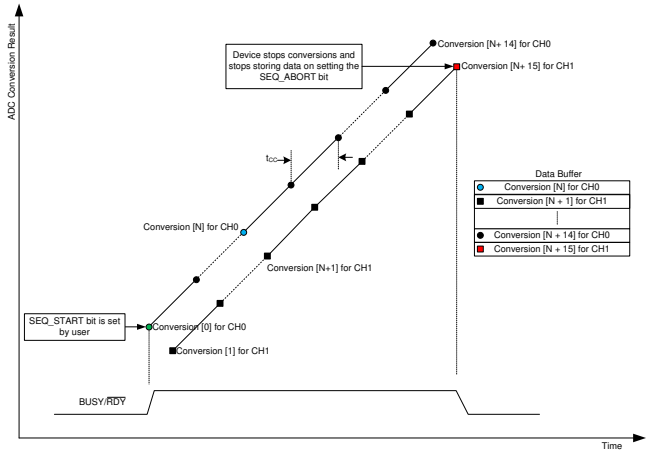


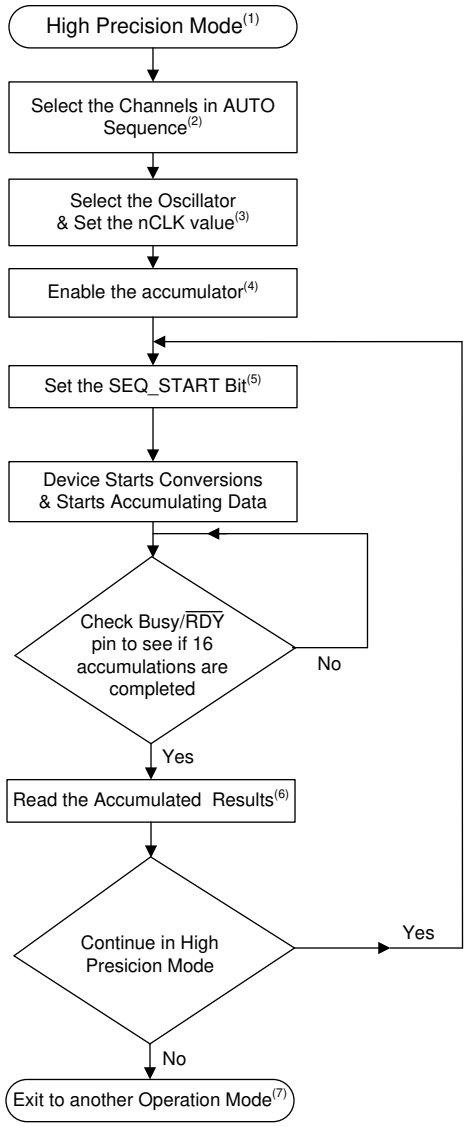
图 58. Stop Burst with Dual Channel Configuration

7.4.4 High Precision Mode

The High Precision Mode increases the accuracy of the data measurement to 16-bit accuracy. This is useful for applications where the level of precision required to accurately measure the sensor output needs to be higher than 12 bits. Applications that could take advantage of this type of functionality include gas detectors, air quality testers, water quality testers, and so on.

For this mode, Set the OPMODE_SEL register to 111b. In this mode, the device starts converting and starts accumulating the conversion results in an accumulator on setting the SEQ_START bit. The device stops accumulating the conversion results in accumulator after 16 conversions or when the SEQ_ABORT bit is set. Upon accumulating 16 twelve bit conversions, the accumulator contains one 16 bit conversion result. The device has an accumulator for each channel and the device accumulates conversion results from each channel into the respective accumulator. If the operation of the device is aborted in high precision mode before the BUSY/RDY pin goes low, the device provides invalid data. In this mode, on providing a device address and read bit for reading data buffer (图 44), the device provides zeroes as output. In this mode, the BUSY/RDY can be used to wake up the MCU or host from sleep or hibernation on completion of accumulation. The steps for configuring the device into High Precision Mode are illustrated in 图 59 .

版权 © 2018–2019, Texas Instruments Incorporated



(1) For setting the operation mode to High Precision mode, Refer to 图 47
(2) Select the channels in the AUTO_SEQ_CHEN register.
(3) Select the oscillator by configuring the OSC_SEL register and configure the NCLK_SEL register.
(4) Enable the accumulator by setting bits in the ACC_EN register.
(5) Set the bit SEQ_START bit in the START_SEQUENCE register.
(6) Read the ACC_CHx_xxx registers.
(7) Select another operation mode in the OPMODE_SEL register.
(8) For reading and writing registers, Refer to Programming section.

图 59. Configuring Device in High Precision Mode

TI recommends aborting the present sequence by setting the SEQ_ABORT bit before changing the device operation mode or device configuration.

图 60 and 图 61 show the accumulation of conversion results in high-precision mode.

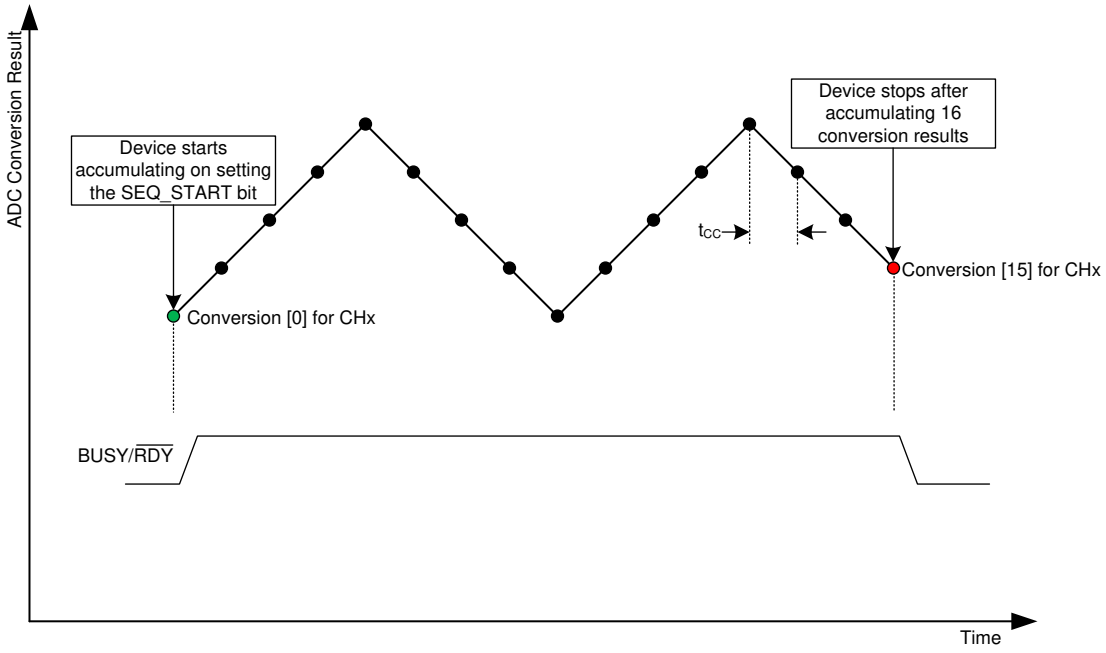


图 60. High-Precision Mode With Single-Channel Configurations

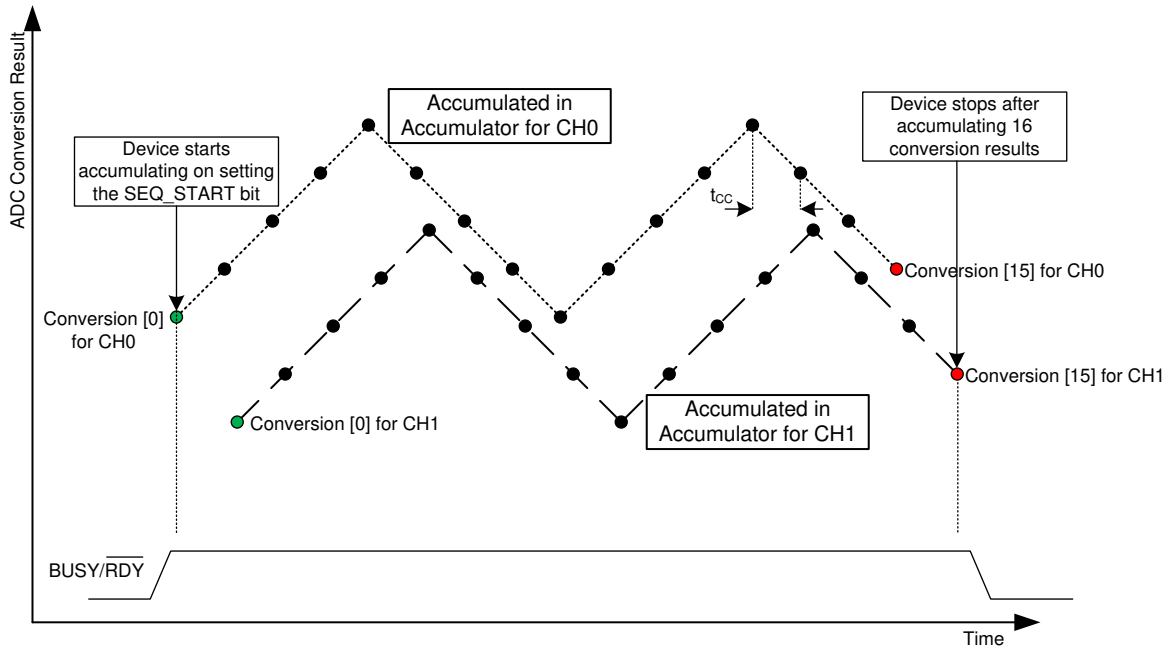


图 61. High-Precision Mode With Dual-Channel Configurations

版权 © 2018–2019, Texas Instruments Incorporated

7.5 Programming

表 3 provides the acronyms for different conditions in an I²C Frame.

表 3. I²C Frame Acronyms

SYMBOL	DESCRIPTION
S	START condition for I²C frame
Sr	RESTART condition for I²C frame
P	STOP condition for I²C frame
A	ACK (low)
N	NACK (high)
R	Read bit (high)
W	Write bit (low)

表 4. Opcodes for Commands

OPCODE	COMMAND DESCRIPTION
00010000b	Single register read
00001000b	Single register write
00011000b	Set bit
00100000b	Clear bit
00110000b	Reading a continuous block of registers
00101000b	Writing a continuous block of registers

7.5.1 Reading Registers

The I²C master can either read a single register or a continuous block registers from the device as described in *Single Register Read* and in *Reading a Continuous Block of Registers*.

7.5.1.1 Single Register Read

To read a single register from the device, the I²C master has to first provide an I²C command with three frames (of 8-bits each) to set the address as illustrated in 图 62. The register address is the address of the register which must be read. The opcode for register read command is listed in 表 4.

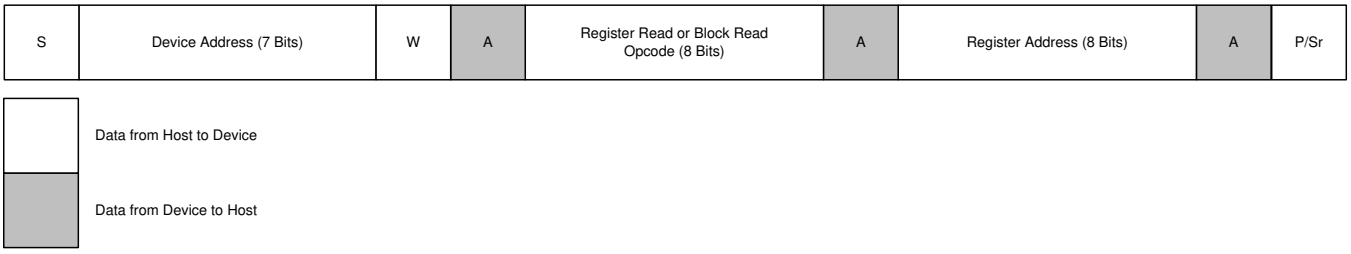


图 62. Setting Register Address for Reading Registers

After this, the I²C master has to provide another I²C frame containing the device address and read bit as illustrated in 图 63. After this frame, the device provides register data. If the host provides more clocks, the device provides same register data. To end the register read command, the master has to provide a STOP or a RESTART condition in the I²C frame.

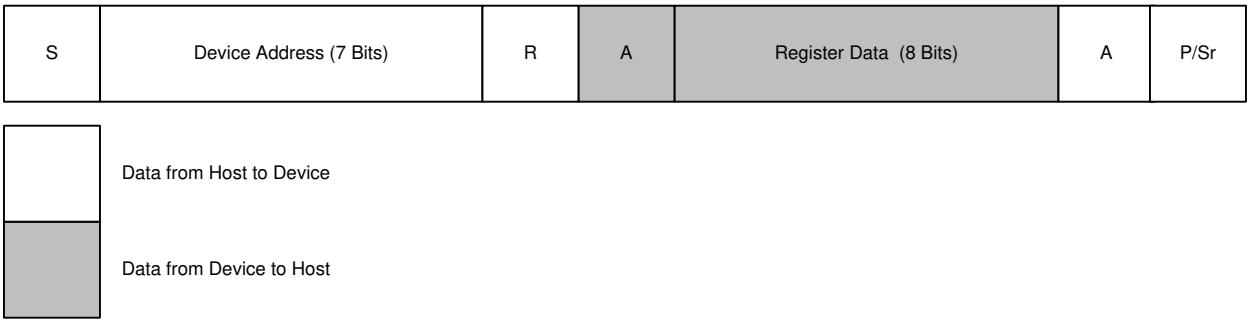


图 63. Reading Register Data

7.5.1.2 Reading a Continuous Block of Registers

To read a continuous block of registers, the I^2C master has to first provide an I^2C command to set the address as illustrated in 图 62. The register address is the address of the first register in the block which must be read. The opcode for reading a continuous block of register is listed in 表 4.

Next, the I^2C master has to provide another I^2C frame containing the device address and read bit as illustrated in 图 64. After this frame, the device provides register data. On providing more clocks, the device provides data for next register. On reading data from addresses which does not exist in the *Register Map* of the device, the device returns zeros. If the device does not have any further registers to provide the data, it provides zeros. To end the register read command, the master has to provide a STOP or a RESTART condition in the I^2C frame.

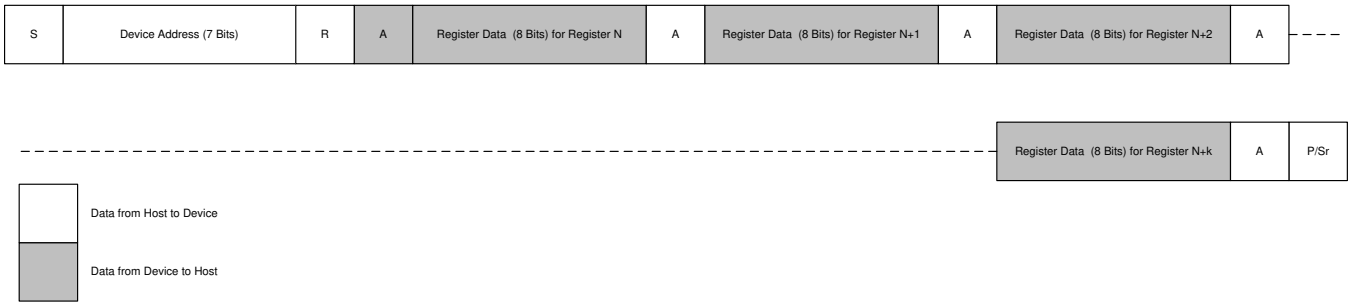


图 64. Reading a Continuous Block of Registers

7.5.2 Writing Registers

The I^2C master can either write a single register or a continuous block registers to the device. It can also set a few bits in a register or clear a few bits in a register.

7.5.2.1 Single Register Write

To write to a single register in the device, the I^2C master has to provide an I^2C command with four frames as illustrated in 图 65. The register address is the address of the register which must be written and register data is the value that must be written. The opcode for single register write is listed in 表 4. To end the register write command, the master has to provide a STOP or a RESTART condition in the I^2C frame.

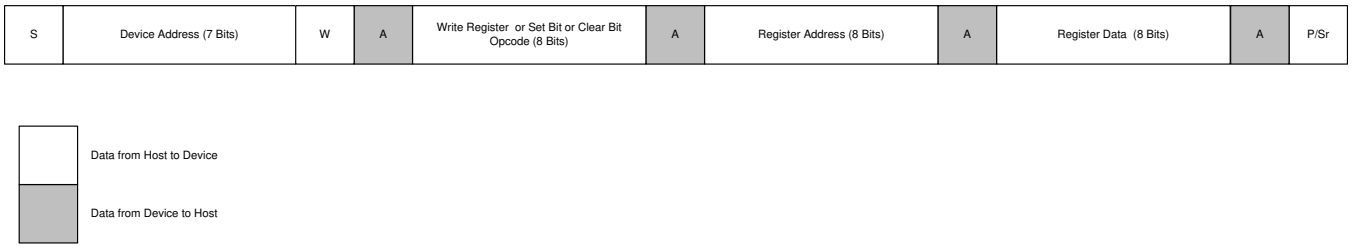


图 65. Writing a Single Register

版权 © 2018–2019, Texas Instruments Incorporated

7.5.2.2 Set Bit

To set bits in a register without changing the other bits, the I^2C master has to provide an I^2C command with four frames as illustrated in 图 65. The register address is the address of the register in which the bits needs to be set and register data is the value representing the bits which need to be set. Bits with value as 1 in register data are set and bits with value as 0 in register data are not changed. The opcode for set bit is listed in 表 4. To end this command, the master has to provide a STOP or RESTART condition in the I^2C frame.

7.5.2.3 Clear Bit

To clear bits in a register without changing the other bits, the I^2C master has to provide an I^2C command with four frames as illustrated in 图 65. The register address is the address of the register in which the bits needs to be cleared and register data is the value representing the bits which need to be cleared. Bits with value as 1 in register data are cleared and bits with value as 0 in register data are not changed. The opcode for clear bit is listed in 表 4. To end this command, the master has to provide a STOP or a RESTART condition in the I^2C frame.

7.5.2.4 Writing a Continuous Block of Registers

To write to a continuous block of registers, the I^2C master has to provide an I^2C command as illustrated in 图 66. The register address is the address of the first register in the block which needs to be written. The I^2C master has to provide data for registers in subsequent I^2C frames in an ascending order of register addresses. Writing data to addresses which do not exist in the *Register Map* of the device has no effect. The opcode for writing a continuous block of registers is listed in 表 4. If the data provided by the I^2C master exceeds the address space of the device, the device neglects the data beyond the address space. To end the register write command, the master has to provide a STOP or a RESTART condition in the I^2C frame.

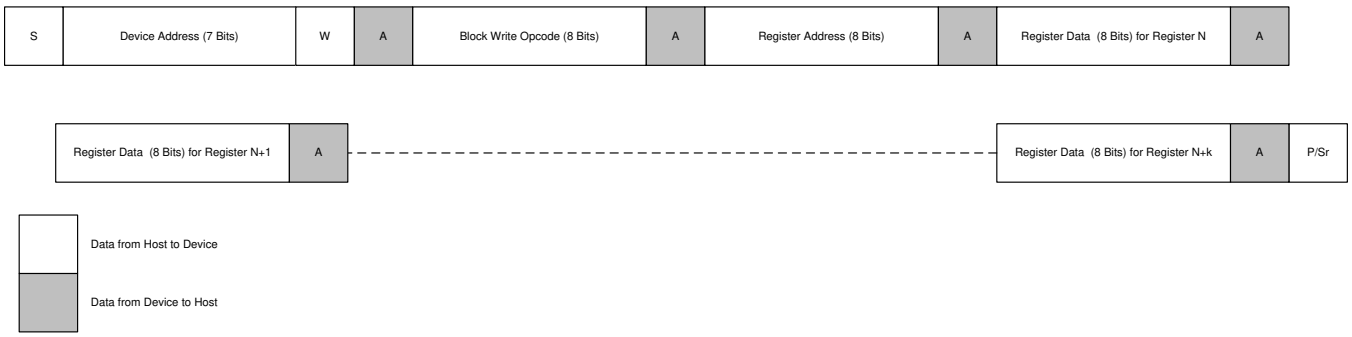


图 66. Writing a Continuous Block of Registers

7.6 Register Map

7.6.1 ADS7142-Q1 Registers

Table 5 lists the ADS7142-Q1 registers. All register offset addresses not listed in Table 5 should be considered as reserved locations and the register contents should not be modified.

Table 5. ADS7142-Q1 Registers

Offset	Acronym	Register Name	Section
0h	OPMODE_I2CMODE_STATUS	Device operation mode register	OPMODE_I2CMODE_STATUS Register (Offset = 0h) [reset = 0h]
1h	DATA_BUFFER_STATUS	Data buffer status register	DATA_BUFFER_STATUS Register (Offset = 1h) [reset = 0h]
2h	ACCUMULATOR_STATUS	Status of ADC accumulator	ACCUMULATOR_STATUS Register (Offset = 2h) [reset = 0h]
3h	ALERT_TRIG_CHID	Alert trigeer channel ID	ALERT_TRIG_CHID Register (Offset = 3h) [reset = 0h]
4h	SEQUENCE_STATUS	Sequence status register	SEQUENCE_STATUS Register (Offset = 4h) [reset = 0h]
8h	ACC_CH0_LSB	CH0 accumulator data register (LSB)	ACC_CH0_LSB Register (Offset = 8h) [reset = 0h]
9h	ACC_CH0_MSB	CH0 accumulated data register (MSB)	ACC_CH0_MSB Register (Offset = 9h) [reset = 0h]
Ah	ACC_CH1_LSB	CH1 accumulated data register (LSB)	ACC_CH1_LSB Register (Offset = Ah) [reset = 0h]
Bh	ACC_CH1_MSB	CH1 accumulated data register (MSB)	ACC_CH1_MSB Register (Offset = Bh) [reset = 0h]
Ch	ALERT_LOW_FLAGS	Alert low flags register	ALERT_LOW_FLAGS Register (Offset = Ch) [reset = 0h]
Eh	ALERT_HIGH_FLAGS	Alert high flags register	ALERT_HIGH_FLAGS Register (Offset = Eh) [reset = 0h]
14h	DEVICE_RESET	Device reset register	DEVICE_RESET Register (Offset = 14h) [reset = 0h]
15h	OFFSET_CAL	Offset calibration register	OFFSET_CAL Register (Offset = 15h) [reset = 0h]
17h	WKEY	Write key for writing into DEVICE_RESET register	WKEY Register (Offset = 17h) [reset = 0h]
18h	OSC_SEL	Oscillator selection register	OSC_SEL Register (Offset = 18h) [reset = 0h]

Copyright © 2018–2019, Texas Instruments Incorporated

Table 5. ADS7142-Q1 Registers (continued)

Offset	Acronym	Register Name	Section
19h	NCLK_SEL	nCLK selection register	NCLK_SEL Register (Offset = 19h) [reset = 0h]
1Ch	OPMODE_SEL	Device operation mode selection	OPMODE_SEL Register (Offset = 1Ch) [reset = 0h]
1Eh	START_SEQUENCE	Start channel scanning sequence register	START_SEQUENCE Register (Offset = 1Eh) [reset = 0h]
1Fh	ABORT_SEQUENCE	Abort channel sequence register	ABORT_SEQUENCE Register (Offset = 1Fh) [reset = 0h]
20h	AUTO_SEQ_CHEN	Auto sequencing channel select register	AUTO_SEQ_CHEN Register (Offset = 20h) [reset = 3h]
24h	CH_INPUT_CFG	Channel input configuration register	CH_INPUT_CFG Register (Offset = 24h) [reset = 0h]
28h	DOUT_FORMAT_CFG	Data buffer word configuration register	DOUT_FORMAT_CFG Register (Offset = 28h) [reset = 0h]
2Ch	DATA_BUFFER_OPMODE	Data buffer operation mode register	DATA_BUFFER_OPMODE Register (Offset = 2Ch) [reset = 1h]
30h	ACC_EN	Accumulator control register	ACC_EN Register (Offset = 30h) [reset = 0h]
34h	ALERT_CHEN	Alert channel enable register	ALERT_CHEN Register (Offset = 34h) [reset = 0h]
36h	PRE_ALT_MAX_EVENT_COUNT	Pre-alert count register	PRE_ALT_MAX_EVENT_COUNT Register (Offset = 36h) [reset = 0h]
37h	ALERT_DWC_EN	Alert digital window comparator register	ALERT_DWC_EN Register (Offset = 37h) [reset = 0h]
38h	DWC_HTH_CH0_LSB	CH0 high threshold LSB register	DWC_HTH_CH0_LSB Register (Offset = 38h) [reset = 0h]
39h	DWC_HTH_CH0_MSB	CH0 high threshold MSB register	DWC_HTH_CH0_MSB Register (Offset = 39h) [reset = 0h]
3Ah	DWC_LTH_CH0_LSB	CH0 low threshold LSB register	DWC_LTH_CH0_LSB Register (Offset = 3Ah) [reset = 0h]
3Bh	DWC_LTH_CH0_MSB	CH0 low threshold MSB register	DWC_LTH_CH0_MSB Register (Offset = 3Bh) [reset = 0h]

Copyright © 2018–2019, Texas Instruments Incorporated

Table 5. ADS7142-Q1 Registers (continued)

Offset	Acronym	Register Name	Section
3Ch	DWC_HTH_CH1_LSB	CH1 high threshold LSB register	DWC_HTH_CH1_LSB Register (Offset = 3Ch) [reset = 0h]
3Dh	DWC_HTH_CH1_MSB	CH1 high threshold MSB register	DWC_HTH_CH1_MSB Register (Offset = 3Dh) [reset = 0h]
3Eh	DWC_LTH_CH1_LSB	CH1 low threshold LSB register	DWC_LTH_CH1_LSB Register (Offset = 3Eh) [reset = 0h]
3Fh	DWC_LTH_CH1_MSB	CH1 low threshold MSB register	DWC_LTH_CH1_MSB Register (Offset = 3Fh) [reset = 0h]
40h	DWC_HYS_CH0	CH0 comparator hysterisis register	DWC_HYS_CH0 Register (Offset = 40h) [reset = 0h]
41h	DWC_HYS_CH1	CH1 comparator hysterisis register	DWC_HYS_CH1 Register (Offset = 41h) [reset = 0h]

Complex bit access types are encoded to fit into small table cells. Table 6 shows the codes that are used for access types in this section.

Table 6. ADS7142-Q1 Access Type Codes

Access Type	Code	Description
Read Type		
R	R	Read
Write Type		
W	W	Write
Reset or Default Value		
-n		Value after reset or the default value
Register Array Variables		
i,j,k,l,m,n		When these variables are used in a register name, an offset, or an address, they refer to the value of a register array where the register is part of a group of repeating registers. The register groups form a hierarchical structure and the array is represented with a formula.
y		When this variable is used in a register name, an offset, or an address it refers to the value of a register array.

7.6.1.1 OPMODE_I2CMODE_STATUS Register (Offset = 0h) [reset = 0h]

OPMODE_I2CMODE_STATUS is shown in Figure 67 and described in Table 7.

Return to the Summary Table.

Device operation mode register

Copyright © 2018–2019, Texas Instruments Incorporated

Figure 67. OPMODE_I2CMODE_STATUS Register

7	6	5	4	3	2	1	0
RESERVED					HS_MODE	DEV_OPMODE[1:0]	
R-00000b					R-0b	R-00b	

Table 7. OPMODE_I2CMODE_STATUS Register Field Descriptions

Bit	Field	Type	Reset	Description
7-3	RESERVED	R	00000b	Reserved bits. Read returns 00000b.
2	HS_MODE	R	0b	This bit indicates when device is in high speed mode for I2C Interface. 0b = 1 : Device is not in high speed mode for I2C Interface. 1b = 2 : Device is in high speed mode for I2C Interface.
1-0	DEV_OPMODE[1:0]	R	00b	These bits indicate funtional mode of the device. 00b = 1 : Device is operating in manual mode. 01b = 2 : Not used. 10b = 3 : Device is operating in autonomous monitoring mode. 11b = 4 : Device is operating in high precision mode.

7.6.1.2 DATA_BUFFER_STATUS Register (Offset = 1h) [reset = 0h]

DATA_BUFFER_STATUS is shown in Figure 68 and described in Table 8.

Return to the Summary Table.

Data buffer status register

Figure 68. DATA_BUFFER_STATUS Register

7	6	5	4	3	2	1	0
RESERVED				DATA_WORDCOUNT[4:0]			
R-000b				R-00000b			

Table 8. DATA_BUFFER_STATUS Register Field Descriptions

Bit	Field	Type	Reset	Description
7-5	RESERVED	R	000b	Reserved bits. Read returns 000b.
4-0	DATA_WORDCOUNT[4:0]	R	00000b	DATA_WORDCOUNT [00000] to [10000] = Number of entries filled in data buffer (0 to 16)

7.6.1.3 ACCUMULATOR_STATUS Register (Offset = 2h) [reset = 0h]

ACCUMULATOR_STATUS is shown in Figure 69 and described in Table 9.

Return to the Summary Table.

Status of ADC accumulator

Figure 69. ACCUMULATOR_STATUS Register

7	6	5	4	3	2	1	0
RESERVED				ACC_COUNT[3:0]			
R-0000b				R-0000b			

Table 9. ACCUMULATOR_STATUS Register Field Descriptions

Bit	Field	Type	Reset	Description
7-4	RESERVED	R	0000b	Reserved bits. Read returns 0000b.
3-0	ACC_COUNT[3:0]	R	0000b	ACC_COUNT = Number of accumulation completed till last finished conversion.

Copyright © 2018–2019, Texas Instruments Incorporated

7.6.1.4 ALERT_TRIG_CHID Register (Offset = 3h) [reset = 0h]

ALERT_TRIG_CHID is shown in Figure 70 and described in Table 10.

Return to the Summary Table.

Alert trigeer channel ID

Figure 70. ALERT_TRIG_CHID Register

7	6	5	4	3	2	1	0
ALERT_TRIG_CHID[3:0]				RESERVED			
R-0000b				R-0000b			

Table 10. ALERT_TRIG_CHID Register Field Descriptions

Bit	Field	Type	Reset	Description
7-4	ALERT_TRIG_CHID[3:0]	R	0000b	These bits provide the channel ID of channel which was first to set the alert output. 0000b = 1 : Channel 0. 0001b = 2 : Channel 1.
3-0	RESERVED	R	0000b	Reserved bits. Reads returns 0000b.

7.6.1.5 SEQUENCE_STATUS Register (Offset = 4h) [reset = 0h]

SEQUENCE_STATUS is shown in Figure 71 and described in Table 11.

Return to the Summary Table.

Sequence status register

Figure 71. SEQUENCE_STATUS Register

7	6	5	4	3	2	1	0
RESERVED					SEQ_ERR_ST[1:0]		RESERVED
R-00000b					R-00b		R-0b

Table 11. SEQUENCE_STATUS Register Field Descriptions

Bit	Field	Type	Reset	Description
7-3	RESERVED	R	00000b	Reserved bits. Read returns 00000b.
2-1	SEQ_ERR_ST[1:0]	R	00b	These bits give status of device sequence. 00b = 1 : Auto sequencing disabled, no error. 01b = 2 : Auto sequencing enabled, no error. 10b = 3 : Not used. 11b = 4 : Auto sequencing enabled, device in error.
0	RESERVED	R	0b	Reserved bit. Read returns 0b.

7.6.1.6 ACC_CH0_LSB Register (Offset = 8h) [reset = 0h]

ACC_CH0_LSB is shown in Figure 72 and described in Table 12.

Return to the Summary Table.

CH0 accumulator data register (LSB)

Figure 72. ACC_CH0_LSB Register

7	6	5	4	3	2	1	0
CH0_LSB[7:0]							
R-00000000b							

Copyright © 2018–2019, Texas Instruments Incorporated

Table 12. ACC_CH0_LSB Register Field Descriptions

Bit	Field	Type	Reset	Description
7-0	CH0_LSB[7:0]	R	00000000b	LSB of accumulated data for CH0.

7.6.1.7 ACC_CH0_MSB Register (Offset = 9h) [reset = 0h]

ACC_CH0_MSB is shown in Figure 73 and described in Table 13.

Return to the Summary Table.

CH0 accumulated data register (MSB)

Figure 73. ACC_CH0_MSB Register

7	6	5	4	3	2	1	0
CH0_MSB[7:0]							
R-00000000b							

Table 13. ACC_CH0_MSB Register Field Descriptions

Bit	Field	Type	Reset	Description
7-0	CH0_MSB[7:0]	R	00000000b	MSB of accumulated data for CH0.

7.6.1.8 ACC_CH1_LSB Register (Offset = Ah) [reset = 0h]

ACC_CH1_LSB is shown in Figure 74 and described in Table 14.

Return to the Summary Table.

CH1 accumulated data register (LSB)

Figure 74. ACC_CH1_LSB Register

7	6	5	4	3	2	1	0
CH1_LSB[7:0]							
R-00000000b							

Table 14. ACC_CH1_LSB Register Field Descriptions

Bit	Field	Type	Reset	Description
7-0	CH1_LSB[7:0]	R	00000000b	LSB of accumulated data for CH1.

7.6.1.9 ACC_CH1_MSB Register (Offset = Bh) [reset = 0h]

ACC_CH1_MSB is shown in Figure 75 and described in Table 15.

Return to the Summary Table.

CH1 accumulated data register (MSB)

Figure 75. ACC_CH1_MSB Register

7	6	5	4	3	2	1	0
CH1_MSB[7:0]							
R-00000000b							

Table 15. ACC_CH1_MSB Register Field Descriptions

Bit	Field	Type	Reset	Description
7-0	CH1_MSB[7:0]	R	00000000b	MSB of accumulated data for CH1.

Copyright © 2018–2019, Texas Instruments Incorporated

7.6.1.10 ALERT_LOW_FLAGS Register (Offset = Ch) [reset = 0h]

ALERT_LOW_FLAGS is shown in Figure 76 and described in Table 16.

Return to the Summary Table.

Alert low flags register

Figure 76. ALERT_LOW_FLAGS Register

7	6	5	4	3	2	1	0
RESERVED						ALERT_LOW_CH1	ALERT_LOW_CH0
R-000000b						R/W-0b	R/W-0b

Table 16. ALERT_LOW_FLAGS Register Field Descriptions

Bit	Field	Type	Reset	Description
7-2	RESERVED	R	000000b	Reserved bits. Read returns 000000b.
1	ALERT_LOW_CH1	R/W	0b	This bit indicates alert on low side comparator for CH1. 0b = 1 : Alert is not set for low side comparator for CH1. 1b = 2 : Alert is set for low side comparator for CH1.
0	ALERT_LOW_CH0	R/W	0b	This bit indicates alert on low side comparator for CH0. 0b = 1 : Alert is not set for low side comparator for CH0. 1b = 2 : Alert is set for low side comparator for CH0.

7.6.1.11 ALERT_HIGH_FLAGS Register (Offset = Eh) [reset = 0h]

ALERT_HIGH_FLAGS is shown in Figure 77 and described in Table 17.

Return to the Summary Table.

Alert high flags register

Figure 77. ALERT_HIGH_FLAGS Register

7	6	5	4	3	2	1	0
RESERVED						ALERT_HIGH_CH1	ALERT_HIGH_CH0
R-000000b						R/W-0b	R/W-0b

Table 17. ALERT_HIGH_FLAGS Register Field Descriptions

Bit	Field	Type	Reset	Description
7-2	RESERVED	R	000000b	Reserved bits. Read returns 000000b.
1	ALERT_HIGH_CH1	R/W	0b	This bit indicates alert on high side comparator of CH1. 0b = 1 : Alert is not set for high side comparator for CH1. 1b = 2 : Alert is set for high side comparator for CH1.
0	ALERT_HIGH_CH0	R/W	0b	This bit indicates alert on high side comparator for CH0. 0b = 1 : Alert is not set for high side comparator for CH0. 1b = 2 : Alert is set for high side comparator for CH0.

7.6.1.12 DEVICE_RESET Register (Offset = 14h) [reset = 0h]

DEVICE_RESET is shown in Figure 78 and described in Table 18.

Return to the Summary Table.

Device reset register

Copyright © 2018–2019, Texas Instruments Incorporated

Figure 78. DEVICE_RESET Register

7	6	5	4	3	2	1	0
RESERVED							DEV_RST
R-0000000b							W-0b

Table 18. DEVICE_RESET Register Field Descriptions

Bit	Field	Type	Reset	Description
7-1	RESERVED	R	0000000b	Reserved bits. Read returns 0000000b.
0	DEV_RST	W	0b	Writing 1 to this bit resets the device.

7.6.1.13 OFFSET_CAL Register (Offset = 15h) [reset = 0h]

OFFSET_CAL is shown in Figure 79 and described in Table 19.

Return to the Summary Table.

Offset calibration register

Figure 79. OFFSET_CAL Register

7	6	5	4	3	2	1	0
RESERVED							TRIG_OFFCAL
R-0000000b							W-0b

Table 19. OFFSET_CAL Register Field Descriptions

Bit	Field	Type	Reset	Description
7-1	RESERVED	R	0000000b	Reserved bits. Read returns 0000000b.
0	TRIG_OFFCAL	W	0b	Writing 1 into this bit triggers internal offset calibration.

7.6.1.14 WKEY Register (Offset = 17h) [reset = 0h]

WKEY is shown in Figure 80 and described in Table 20.

Return to the Summary Table.

Write key for writing into DEVICE_RESET register

Figure 80. WKEY Register

7	6	5	4	3	2	1	0
RESERVED				WKEY[3:0]			
R-0000b				R/W-0000b			

Table 20. WKEY Register Field Descriptions

Bit	Field	Type	Reset	Description
7-4	RESERVED	R	0000b	Reserved bits. Do not write. Read returns 0000b.
3-0	WKEY[3:0]	R/W	0000b	Write 1010b into these bits to get write access for the DEVICE_RESET and OFFSET_CAL register. WKEY register is not reset to default value on device reset (see Reset section). After coming out of device reset, write 00h to the WKEY register to prevent erroneous reset.

7.6.1.15 OSC_SEL Register (Offset = 18h) [reset = 0h]

OSC_SEL is shown in Figure 81 and described in Table 21.

Return to the Summary Table.

Oscillator selection register

Copyright © 2018–2019, Texas Instruments Incorporated

Figure 81. OSC_SEL Register

7	6	5	4	3	2	1	0
RESERVED							HSZ_LP
R-0000000b							R/W-0b

Table 21. OSC_SEL Register Field Descriptions

Bit	Field	Type	Reset	Description
7-1	RESERVED	R	0000000b	Reserved bits. Read returns 0000000b.
0	HSZ_LP	R/W	0b	This bit selects oscillator used for the conversion process and cycle time for a single conversion. 0b = 1 : Device uses high speed oscillator. 1b = 2 : Device uses low power oscillator.

7.6.1.16 NCLK_SEL Register (Offset = 19h) [reset = 0h]

NCLK_SEL is shown in Figure 82 and described in Table 22.

Return to the Summary Table.

nCLK selection register

Figure 82. NCLK_SEL Register

7	6	5	4	3	2	1	0
NCLK[7:0]							
R/W-00000000b							

Table 22. NCLK_SEL Register Field Descriptions

Bit	Field	Type	Reset	Description
7-0	NCLK[7:0]	R/W	00000000b	Sets number of clocks of the oscillator that the device uses for one conversion cycle. When using the High Speed Oscillator: For Value x written into the nCLK register • if x ≤ 21, nCLK is set to 21 (00010101b) • if x > 21, nCLK is set to x When using the Low Power Oscillator, For Value x written into the nCLK register: • if x ≤ 18, nCLK is set to 18 (00010010b) • if x > 18, nCLK is set to x

7.6.1.17 OPMODE_SEL Register (Offset = 1Ch) [reset = 0h]

OPMODE_SEL is shown in Figure 83 and described in Table 23.

Return to the Summary Table.

Device operation mode selection

Figure 83. OPMODE_SEL Register

7	6	5	4	3	2	1	0
RESERVED					SEL_OPMODE[2:0]		
R-00000b					R/W-000b		

Copyright © 2018–2019, Texas Instruments Incorporated

Table 23. OPMODE_SEL Register Field Descriptions

Bit	Field	Type	Reset	Description
7-3	RESERVED	R	00000b	Reserved bits. Read returns 00000b
2-0	SEL_OPMODE[2:0]	R/W	000b	These bits set the functional mode for the device. 000b = 1 : Manual mode with CH0 only (Default mode). 001b = 2 : Manual mode with CH0 only (Default mode). 010b = 3 : Reserved. Do not use. 011b = 4 : Reserved. Do not use. 100b = 5 : Manual mode with AUTO Sequencing enabled. 101b = 6 : Manual Mode with AUTO Sequencing enabled. 110b = 7 : Autonomous monitoring mode with AUTO sequencing enabled. 111b = 8 : High precision mode with AUTO sequencing enabled.

7.6.1.18 START_SEQUENCE Register (Offset = 1Eh) [reset = 0h]

START_SEQUENCE is shown in Figure 84 and described in Table 24.

Return to the Summary Table.

Start channel scanning sequence register

Figure 84. START_SEQUENCE Register

7	6	5	4	3	2	1	0
RESERVED							SEQ_START
R-0000000b							W-0b

Table 24. START_SEQUENCE Register Field Descriptions

Bit	Field	Type	Reset	Description
7-1	RESERVED	R	0000000b	Reserved bits. Read returns 0000000b.
0	SEQ_START	W	0b	Setting this bit to 1 brings the BUSY/RDY pin high and starts the first conversion in the sequence.

7.6.1.19 ABORT_SEQUENCE Register (Offset = 1Fh) [reset = 0h]

ABORT_SEQUENCE is shown in Figure 85 and described in Table 25.

Return to the Summary Table.

Abort channel sequence register

Figure 85. ABORT_SEQUENCE Register

7	6	5	4	3	2	1	0
RESERVED							SEQ_ABORT
R-0000000b							W-0b

Table 25. ABORT_SEQUENCE Register Field Descriptions

Bit	Field	Type	Reset	Description
7-1	RESERVED	R	0000000b	Reserved bits. Read returns 0000000b.
0	SEQ_ABORT	W	0b	Setting this bit to 1 aborts the ongoing conversion and brings the BUSY/RDY pin low.

Copyright © 2018–2019, Texas Instruments Incorporated

7.6.1.20 AUTO_SEQ_CHEN Register (Offset = 20h) [reset = 3h]

AUTO_SEQ_CHEN is shown in Figure 86 and described in Table 26.

Return to the Summary Table.

Auto sequencing channel select register

Figure 86. AUTO_SEQ_CHEN Register

7	6	5	4	3	2	1	0
RESERVED						AUTOSEQ_EN_CH1	AUTOSEQ_EN_CH0
R-000000b						R/W-1b	R/W-1b

Table 26. AUTO_SEQ_CHEN Register Field Descriptions

Bit	Field	Type	Reset	Description
7-2	RESERVED	R	000000b	Reserved bits. Read returns 000000b.
1	AUTOSEQ_EN_CH1	R/W	1b	This bit selects CH1 for auto sequencing. 0b = 1 : Channel 1 is not selected for auto sequencing. 1b = 2 : Channel 1 is selected for auto sequencing.
0	AUTOSEQ_EN_CH0	R/W	1b	This bit selects CH0 for auto sequencing. 0b = 1 : Channel 0 is not selected for auto sequencing. 1b = 2 : Channel 0 is selected for auto sequencing.

7.6.1.21 CH_INPUT_CFG Register (Offset = 24h) [reset = 0h]

CH_INPUT_CFG is shown in Figure 87 and described in Table 27.

Return to the Summary Table.

Channel input configuration register

Figure 87. CH_INPUT_CFG Register

7	6	5	4	3	2	1	0
RESERVED						CH0_CH1_IP_CFG[1:0]	
R-000000b						R/W-00b	

Table 27. CH_INPUT_CFG Register Field Descriptions

Bit	Field	Type	Reset	Description
7-2	RESERVED	R	000000b	Reserved bits. Read returns 000000b.
1-0	CH0_CH1_IP_CFG[1:0]	R/W	00b	This bit selects configuration for the input pins. 00b = 1 : Two-channel, single-ended configuration. 01b = 2 : Single-channel, single-ended configuration with remote ground sensing. 10b = 3 : Single-channel, pseudo-differential configuration. 11b = 4 : Two-channel, single-ended configuration.

7.6.1.22 DOUT_FORMAT_CFG Register (Offset = 28h) [reset = 0h]

DOUT_FORMAT_CFG is shown in Figure 88 and described in Table 28.

Return to the Summary Table.

Data buffer word configuration register

Copyright © 2018–2019, Texas Instruments Incorporated

Figure 88. DOUT_FORMAT_CFG Register

7	6	5	4	3	2	1	0
RESERVED						DOUT_FORMAT[1:0]	
R-000000b						R/W-00b	

Table 28. DOUT_FORMAT_CFG Register Field Descriptions

Bit	Field	Type	Reset	Description
7-2	RESERVED	R	000000b	Reserved bits. Read returns 000000b.
1-0	DOUT_FORMAT[1:0]	R/W	00b	These bits select 16-bit content of the data word in the data buffer. 00b = 1 : 12-bit conversion result followed by 0000b. 01b = 2 : 12-bit conversion result followed by 3-bit channel ID (000b for CH0, 001b for CH1). 10b = 3 : 12-bit conversion result followed by 3-bit channel ID (000b for CH0, 001b for CH1) followed by DATA_VALID bit. 11b = 4 : 12-bit conversion result followed by 0000b.

7.6.1.23 DATA_BUFFER_OPMODE Register (Offset = 2Ch) [reset = 1h]

DATA_BUFFER_OPMODE is shown in Figure 89 and described in Table 29.

Return to the Summary Table.

Data buffer operation mode register

Figure 89. DATA_BUFFER_OPMODE Register

7	6	5	4	3	2	1	0
RESERVED					STARTSTOP_CNTRL[2:0]		
R-00000b					R/W-001b		

Table 29. DATA_BUFFER_OPMODE Register Field Descriptions

Bit	Field	Type	Reset	Description
7-3	RESERVED	R	00000b	Reserved bits. Read returns 00000b.
2-0	STARTSTOP_CNTRL[2:0]	R/W	001b	These bits select data buffer mode of operation. 000b = 1 : Stop burst mode. 001b = 2 : Start burst mode, default. 010b = 3 : Reserved, do not use. 011b = 4 : Reserved, do not use. 100b = 5 : Pre alert data mode. 101b = 6 : Reserved, do not use. 110b = 7 : Post alert data mode. 111b = 8 : Reserved, do not use.

7.6.1.24 ACC_EN Register (Offset = 30h) [reset = 0h]

ACC_EN is shown in Figure 90 and described in Table 30.

Return to the Summary Table.

Accumulator control register

Figure 90. ACC_EN Register

7	6	5	4	3	2	1	0
RESERVED				EN_ACC[3:0]			
R-0000b				R/W-0000b			

Copyright © 2018–2019, Texas Instruments Incorporated

Table 30. ACC_EN Register Field Descriptions

Bit	Field	Type	Reset	Description
7-4	RESERVED	R	0000b	Reserved bits. Read returns 0000b.
3-0	EN_ACC[3:0]	R/W	0000b	These bits enable accumulator function of device. 0001b to 1110b settings are reserved. Do not use. 0000b = 1 : Accumulator is enabled.

7.6.1.25 ALERT_CHEN Register (Offset = 34h) [reset = 0h]

ALERT_CHEN is shown in Figure 91 and described in Table 31.

Return to the Summary Table.

Alert channel enable register

Figure 91. ALERT_CHEN Register

7	6	5	4	3	2	1	0
RESERVED						ALERT_EN_CH1	ALERT_EN_CH0
R-000000b						R/W-0b	R/W-0b

Table 31. ALERT_CHEN Register Field Descriptions

Bit	Field	Type	Reset	Description
7-2	RESERVED	R	000000b	Reserved bits. Read returns 000000b.
1	ALERT_EN_CH1	R/W	0b	This bit enables alert functionality of CH1. 0b = 1 : Alert is disabled for CH1, default. 1b = 2 : Alert is enabled for CH1.
0	ALERT_EN_CH0	R/W	0b	This bit enables alert functionality for CH0. 0b = 1 : Alert is disabled for CH0, default. 1b = 2 : Alert is enabled for CH0.

7.6.1.26 PRE_ALT_MAX_EVENT_COUNT Register (Offset = 36h) [reset = 0h]

PRE_ALT_MAX_EVENT_COUNT is shown in Figure 92 and described in Table 32.

Return to the Summary Table.

Pre-alert count register

Figure 92. PRE_ALT_MAX_EVENT_COUNT Register

7	6	5	4	3	2	1	0
PREALERT_COUNT[3:0]				RESERVED			
R/W-0000b				R-0000b			

Table 32. PRE_ALT_MAX_EVENT_COUNT Register Field Descriptions

Bit	Field	Type	Reset	Description
7-4	PREALERT_COUNT[3:0]	R/W	0000b	These bits set the Pre-Alert Event Count = PREALERT_COUNT [7:4] + 1
3-0	RESERVED	R	0000b	Reserved bits. Read returns 0000b.

7.6.1.27 ALERT_DWC_EN Register (Offset = 37h) [reset = 0h]

ALERT_DWC_EN is shown in Figure 93 and described in Table 33.

Return to the Summary Table.

Alert digital window comparator register

Copyright © 2018–2019, Texas Instruments Incorporated

Figure 93. ALERT_DWC_EN Register

7	6	5	4	3	2	1	0
RESERVED							DWC_BLOCK_EN
R-0000000b							R/W-0b

Table 33. ALERT_DWC_EN Register Field Descriptions

Bit	Field	Type	Reset	Description
7-1	RESERVED	R	0000000b	Reserved bits. Read returns 0000000b.
0	DWC_BLOCK_EN	R/W	0b	This bit enables digital window comparator block. 0b = 1 : Disables digital window comparator. 1b = 2 : Enables digital window comparator.

7.6.1.28 DWC_HTH_CH0_LSB Register (Offset = 38h) [reset = 0h]

DWC_HTH_CH0_LSB is shown in Figure 94 and described in Table 34.

Return to the Summary Table.

CH0 high threshold LSB register

Figure 94. DWC_HTH_CH0_LSB Register

7	6	5	4	3	2	1	0
HTH_CH0_LSB[7:0]							
R/W-00000000b							

Table 34. DWC_HTH_CH0_LSB Register Field Descriptions

Bit	Field	Type	Reset	Description
7-0	HTH_CH0_LSB[7:0]	R/W	00000000b	These are 8 least significant bits of high threshold for CH0.

7.6.1.29 DWC_HTH_CH0_MSB Register (Offset = 39h) [reset = 0h]

DWC_HTH_CH0_MSB is shown in Figure 95 and described in Table 35.

Return to the Summary Table.

CH0 high threshold MSB register

Figure 95. DWC_HTH_CH0_MSB Register

7	6	5	4	3	2	1	0
RESERVED				HTH_CH0_MSB[3:0]			
R-0000b				R/W-0000b			

Table 35. DWC_HTH_CH0_MSB Register Field Descriptions

Bit	Field	Type	Reset	Description
7-4	RESERVED	R	0000b	Reserved bits. Read returns 0000b.
3-0	HTH_CH0_MSB[3:0]	R/W	0000b	These are 4 most significant bits of high threshold for CH0.

7.6.1.30 DWC_LTH_CH0_LSB Register (Offset = 3Ah) [reset = 0h]

DWC_LTH_CH0_LSB is shown in Figure 96 and described in Table 36.

Return to the Summary Table.

CH0 low threshold LSB register

Copyright © 2018–2019, Texas Instruments Incorporated

Figure 96. DWC_LTH_CH0_LSB Register

7	6	5	4	3	2	1	0
LTH_CH0_LSB[7:0]							
R/W-00000000b							

Table 36. DWC_LTH_CH0_LSB Register Field Descriptions

Bit	Field	Type	Reset	Description
7-0	LTH_CH0_LSB[7:0]	R/W	00000000b	These are 8 least significant bits of low threshold for CH0.

7.6.1.31 DWC_LTH_CH0_MSB Register (Offset = 3Bh) [reset = 0h]

DWC_LTH_CH0_MSB is shown in Figure 97 and described in Table 37.

Return to the Summary Table.

CH0 low threshold MSB register

Figure 97. DWC_LTH_CH0_MSB Register

7	6	5	4	3	2	1	0
RESERVED				LTH_CH0_MSB[3:0]			
R-0000b				R/W-0000b			

Table 37. DWC_LTH_CH0_MSB Register Field Descriptions

Bit	Field	Type	Reset	Description
7-4	RESERVED	R	0000b	Reserved bits. Read returns 0000b.
3-0	LTH_CH0_MSB[3:0]	R/W	0000b	These are 4 most significant bits of low threshold for CH0.

7.6.1.32 DWC_HTH_CH1_LSB Register (Offset = 3Ch) [reset = 0h]

DWC_HTH_CH1_LSB is shown in Figure 98 and described in Table 38.

Return to the Summary Table.

CH1 high threshold LSB register

Figure 98. DWC_HTH_CH1_LSB Register

7	6	5	4	3	2	1	0
HTH_CH1_LSB[7:0]							
R/W-00000000b							

Table 38. DWC_HTH_CH1_LSB Register Field Descriptions

Bit	Field	Type	Reset	Description
7-0	HTH_CH1_LSB[7:0]	R/W	00000000b	These are 8 least significant bits of high threshold for CH1.

7.6.1.33 DWC_HTH_CH1_MSB Register (Offset = 3Dh) [reset = 0h]

DWC_HTH_CH1_MSB is shown in Figure 99 and described in Table 39.

Return to the Summary Table.

CH1 high threshold MSB register

Figure 99. DWC_HTH_CH1_MSB Register

7	6	5	4	3	2	1	0
RESERVED				HTH_CH1_MSB[3:0]			
R-0000b				R/W-0000b			

Copyright © 2018–2019, Texas Instruments Incorporated

Table 39. DWC_HTH_CH1_MSB Register Field Descriptions

Bit	Field	Type	Reset	Description
7-4	RESERVED	R	0000b	Reserved bits. Read returns 0000b.
3-0	HTH_CH1_MSB[3:0]	R/W	0000b	These are 4 most significant bits of high threshold for CH1.

7.6.1.34 DWC_LTH_CH1_LSB Register (Offset = 3Eh) [reset = 0h]

DWC_LTH_CH1_LSB is shown in Figure 100 and described in Table 40.

Return to the Summary Table.

CH1 low threshold LSB register

Figure 100. DWC_LTH_CH1_LSB Register

7	6	5	4	3	2	1	0
LTH_CH1_LSB[7:0]							
R/W-00000000b							

Table 40. DWC_LTH_CH1_LSB Register Field Descriptions

Bit	Field	Type	Reset	Description
7-0	LTH_CH1_LSB[7:0]	R/W	00000000b	These are 8 least significant bits of low threshold for CH1.

7.6.1.35 DWC_LTH_CH1_MSB Register (Offset = 3Fh) [reset = 0h]

DWC_LTH_CH1_MSB is shown in Figure 101 and described in Table 41.

Return to the Summary Table.

CH1 low threshold MSB register

Figure 101. DWC_LTH_CH1_MSB Register

7	6	5	4	3	2	1	0
RESERVED				LTH_CH1_MSB[3:0]			
R-0000b				R/W-0000b			

Table 41. DWC_LTH_CH1_MSB Register Field Descriptions

Bit	Field	Type	Reset	Description
7-4	RESERVED	R	0000b	Reserved bits. Read returns 0000b.
3-0	LTH_CH1_MSB[3:0]	R/W	0000b	These are 4 most significant bits of low threshold for CH1.

7.6.1.36 DWC_HYS_CH0 Register (Offset = 40h) [reset = 0h]

DWC_HYS_CH0 is shown in Figure 102 and described in Table 42.

Return to the Summary Table.

CH0 comparator hysterisis register

Figure 102. DWC_HYS_CH0 Register

7	6	5	4	3	2	1	0
RESERVED		HYS_CH0[5:0]					
R-00b		R/W-000000b					

Copyright © 2018–2019, Texas Instruments Incorporated

Table 42. DWC_HYS_CH0 Register Field Descriptions

Bit	Field	Type	Reset	Description
7-6	RESERVED	R	00b	Reserved bits. Read returns 00b.
5-0	HYS_CH0[5:0]	R/W	000000b	These bits set hysteresis for both comparators for CH0.

7.6.1.37 DWC_HYS_CH1 Register (Offset = 41h) [reset = 0h]

DWC_HYS_CH1 is shown in Figure 103 and described in Table 43.

Return to the Summary Table.

CH1 comparator hysterisis register

Figure 103. DWC_HYS_CH1 Register

7	6	5	4	3	2	1	0
RESERVED		HYS_CH1[5:0]					
R-00b		R/W-000000b					

Table 43. DWC_HYS_CH1 Register Field Descriptions

Bit	Field	Type	Reset	Description
7-6	RESERVED	R	00b	Reserved bits. Read returns 00b.
5-0	HYS_CH1[5:0]	R/W	000000b	These bits set hysteresis for both comparators for CH1.

版权 © 2018–2019, Texas Instruments Incorporated

8 Application and Implementation

注

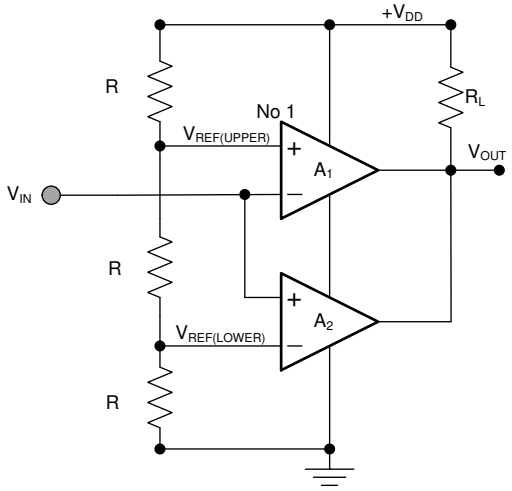
Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

8.1 Application Information

In an increasing number of industrial applications, data acquisition sub-systems are collecting more data about the environment in which the system is operating and applying deep learning algorithms in order to improve system reliability, implement preventative maintenance, and/or enhance the quality of data collected by the system. The ADS7142-Q1 can be used to connect to a variety of sensors and can provide deeper data analytics at lower power levels than existing solutions. The depth of analysis that can be performed on the data collected by the ADS7142-Q1 is enhanced by the internal data buffer, programmable alarm thresholds and hysteresis, event counter, and internal calibration circuitry. The applications circuits described in this section highlight specific use-cases of the ADS7142-Q1 for data collection that can further increase the depth and quality of the data being measured by the system.

8.2 Typical Applications

8.2.1 ADS7142-Q1 as a Programmable Comparator With False Trigger Prevention and Diagnostics



Copyright © 2017, Texas Instruments Incorporated

图 104. Analog Window Comparator

8.2.1.1 Design Requirements

In many automotive sensor monitors there is a need to make a decision at the system-level when the input signal crosses a predefined threshold. Analog window comparators are being used extensively in such applications.

An analog window comparator has a set of comparators. The external input signal is connected to the inverting terminal of one comparator and the noninverting terminal of the other comparator. The remaining input of each comparator is connected to the internal reference. The outputs are tied together and are often connected to a reset or general-purpose input of a processor (such as a digital signal processor, field-programmable gate array, or application-specific integrated circuit) or the enable input of a voltage regulator (such as a DC-DC or low-dropout regulator). 图 104 shows the circuit diagram for an analog window comparator.

Though analog comparators are easy to design, there are certain disadvantages associated with analog comparators.

- Higher Power Consumption: If the voltage that is monitored is greater than the window comparator supply voltage, then there is a need for a resistive divider ladder to scale down that voltage. This resistive ladder

Typical Applications (接下页)

draws a constant current and adds to the power consumption of the system. In battery powered applications, this becomes a challenge and can adversely affect the battery life.

- Fixed Threshold Voltages: The window comparator thresholds cannot be changed on-the-fly since these are set by hardware (typically with a resistive ladder). This may add a limitation if user wants to change the comparator thresholds during operation without switching in a new resistor ladder.

Automotive systems often require a device which monitors either critical voltage rails, temperature of the critical blocks or sensors and gives an alert/interrupt to the host MCU only when the input that being monitored falls crosses a predefined, programmable threshold. The ADS7142-Q1 is an excellent fit for such system level monitoring due to its ability to autonomously monitor sensor output and wake up the host controller whenever the sensor output crosses pre-defined thresholds. Additionally, the ADS7142-Q1 has an internal data buffer which can store 16 sample data which the user can read in case further analysis is required. 图 105 shows typical block diagram of ADS7142-Q1 as sensor monitor. As is shown in this figure, the sensor can be connected directly to the input of the ADC (depending on the sensor output signal characteristics).

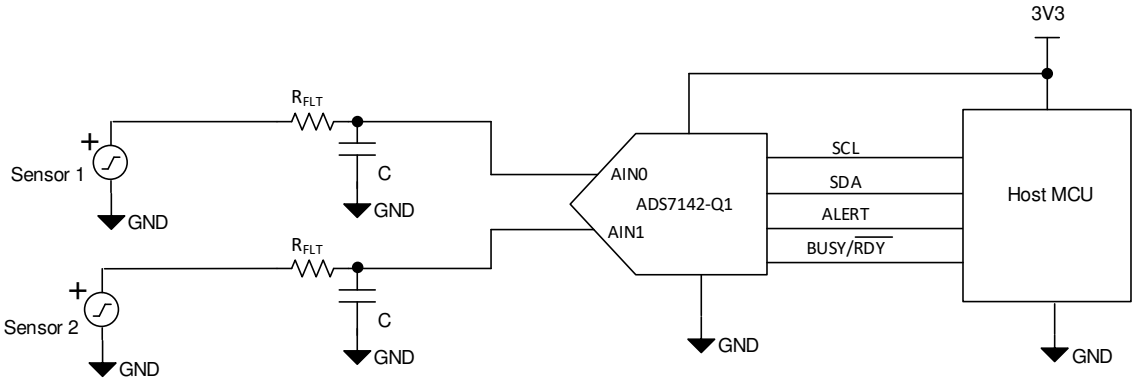


图 105. Sensor Monitor Circuit with ADS7142-Q1

8.2.1.2 Detailed Design Procedure

8.2.1.2.1 Programmable Thresholds and Hysteresis

The ADS7142-Q1 can be programmed to monitor sensor output voltages and generate an ALERT signal for the host controller if the sensor output voltage crosses a threshold.

The device can be configured to monitor for signals rising above a programmed threshold. 图 106 illustrates the operation of the device when monitoring for signal crossings on the low threshold by setting the high threshold to 0xFFF. In this case, the output of the low-side comparator is set whenever the ADC conversion result is less than or equal to the low threshold, and the output of the high-side comparator is only set when the ADC conversion result is equal to 0xFFF.

The device can also be configured to monitor for signals falling below a programmed threshold. 图 107 illustrates the operation of the device when monitoring for signal crossings on the high threshold by setting the low threshold to 0x000. In this case, the output of high-side comparator is set whenever the ADC conversion result is greater than or equal to the high threshold and the output of the low-side comparator will only be set when the ADC conversion result is equal to 0x000.

版权 © 2018–2019, Texas Instruments Incorporated

Typical Applications (接下页)

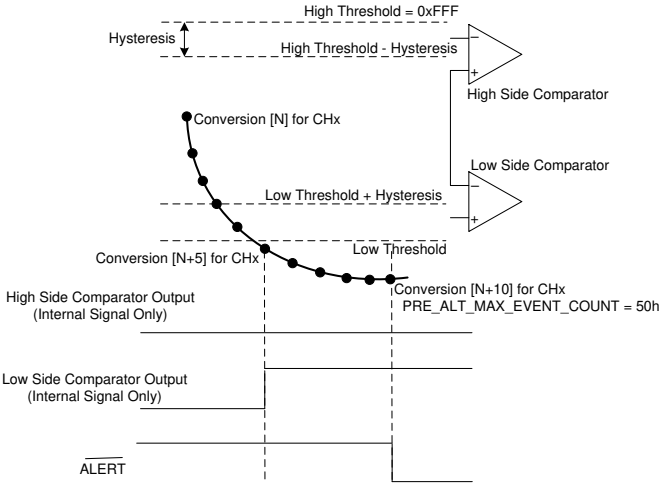


图 106. Low Alert with ADS7142-Q1

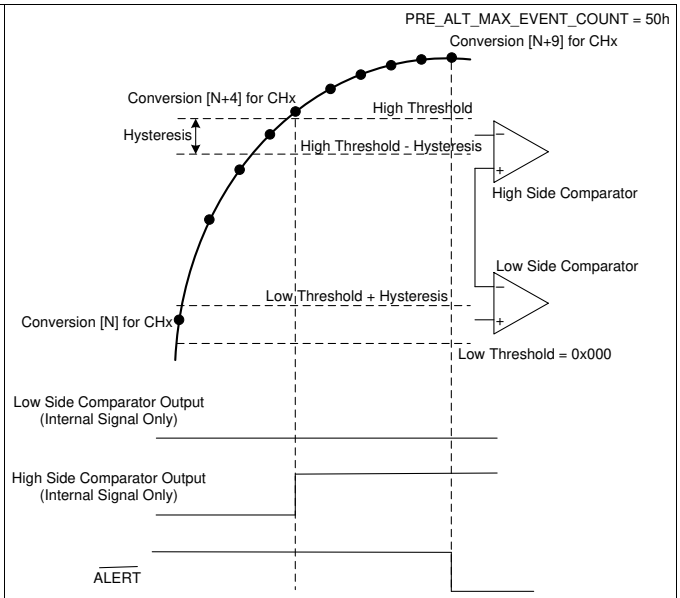


图 107. High Alert with ADS7142-Q1

The device can also be configured to monitor for signals falling outside of a programmed window. 图 108 illustrates the operation of the device for an out-of-range alert where the signal leaves the pre-defined window and crosses either the high or low threshold. In this case, the output of low side comparator is set whenever the ADC conversion result is less than or equal to the low threshold, and the output of high side comparator is set when the ADC conversion result is greater than or equal to the high threshold.

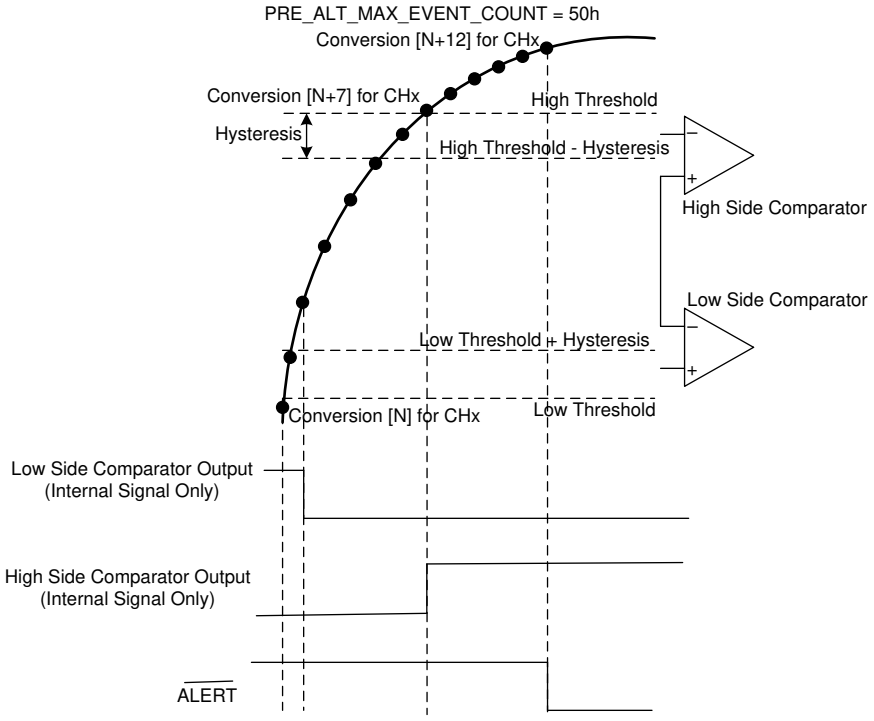


图 108. Out of Range Alert with ADS7142-Q1

Typical Applications (接下页)

8.2.1.2.2 False Trigger Prevention with Event Counter

The Pre-Alert event counter in the *Digital Window Comparator* helps to prevent false triggers. The alert output is not set until the output of the comparator remains set for a pre-defined number (count) of consecutive conversions.

8.2.1.2.3 Fault Diagnostics with Data Buffer

The modes which are specifically designed for autonomous sensor monitor applications are Pre-Alert mode and Post-Alert mode. In Pre-Alert mode, the ADS7142-Q1 can be configured to monitor sensor outputs and continuously fill the internal data buffer until a threshold crossing occurs. The ADS7142-Q1 will generate an ALERT signal when the sensor output falls outside of the predefined window of operation. In this particular mode, the ADS7142-Q1 stops filling the data buffer when the threshold is crossed and provides the last 16 samples (15 sample data preceding the sample at which the ALERT is generated and 1 sample data for which the ALERT is generated). 图 109 shows the ADS7142-Q1 operation in Pre-Alert mode showing 16 data samples before the sensor output crosses the low threshold. This is useful for applications where the state of the signal before the threshold is crossed is important to capture. Using the data captured before the alert, deep data analysis can be performed to determine the state of the system before the alert. This type of data is not available with analog comparators.

In Post-Alert mode, ADS7142-Q1 can be configured to monitor sensor outputs and start filling the internal data buffer after a threshold crossing occurs. The ADS7142-Q1 generates an ALERT signal when the sensor output falls outside of the predefined window of operation. In this particular mode, the ADS7142-Q1 continues to fill the data buffer after the threshold is crossed for a total of 16 samples (1 sample data for which ALERT is generated and 15 sample data after the sample at which ALERT is generated). 图 110 shows the ADS7142-Q1 operation in Post-Alert mode showing 16 data samples after the sensor output crosses the high threshold. This is useful for applications where the state of the signal after the threshold is crossed is important to capture. Using the data captured after the alert, deep data analysis can be performed for to determine the state of the system after the alert to detect system-level events such as saturation. This data is not available with analog comparators.

版权 © 2018–2019, Texas Instruments Incorporated

Typical Applications (接下页)

8.2.1.3 Application Curves



图 109. Pre-Alert Data Capture



图 110. Post Alert Data Capture

Typical Applications (接下页)

8.2.2 Voltage and Temperature Monitoring in Remote Camera Modules Using the ADS7142-Q1

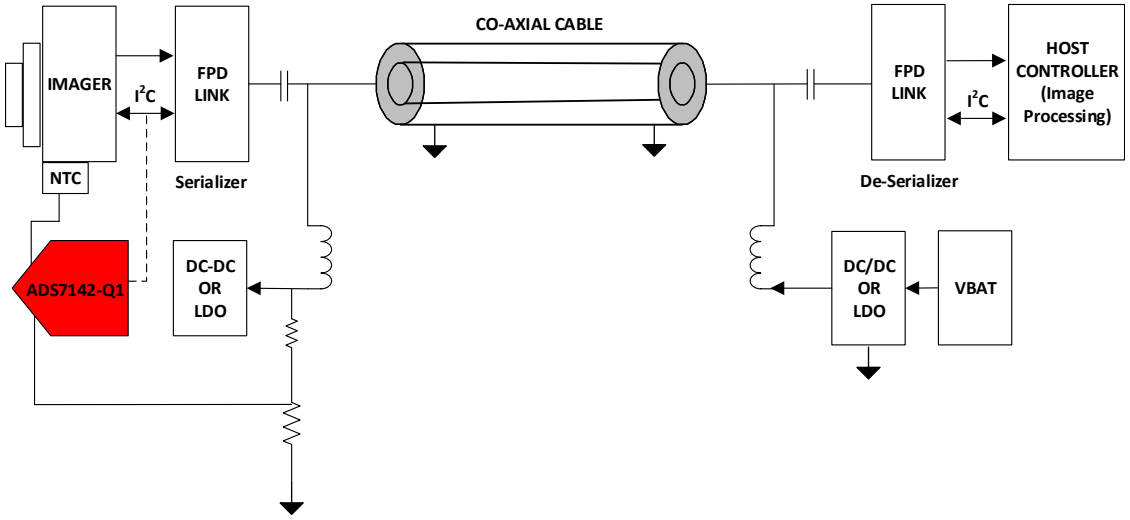


图 111. Voltage and Temperature Sensing in Remote Camera Modules Using the ADS7142-Q1

8.2.2.1 Design Requirements

Camera modules are an integral part of advanced driver assistance systems (ADAS), which are designed to make cars safer. Automotive cameras and camera modules are often assist in blind spot detection, nap prevention, lane and border detection, surround view and parking. Based on application, there are multiple types of camera modules available such as front camera, rear camera, night vision camera. 图 111 shows the typical block diagram of camera module used in an automotive environment with key electronics building blocks in the system.

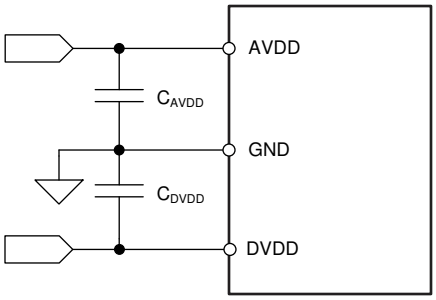
The camera module is usually situated externally at front, back or either side of the vehicle. Many times the main controller that does the data processing can not be used on camera module side due to size constraints. The camera module unit communicates with central processor over co-axial cable. The camera module data is transmitted over co-axial cable using a serializer. On data processing unit, De-serializer is used to communicate this data with host processor. The power to the camera module is also transmitted over co-axial cable. As the camera module is remotely placed and power is transferred over co-axial cable which can be few meters long, voltage received by camera module and critical voltage rails powering image sensors are often monitored against permissible variations. Also the difference between camera lens and external ambient temperature can introduce dampness and degrade video quality. To ensure optimal video quality camera lens temperature is often monitored for any possible correction. The device monitoring these system level parameters has to be small size due to limited board space available on the camera module side. Also I2C interface is preferred as it enables user to connect multiple monitoring and sensing devices on the same I^2C bus. ADS7142-Q1 small footprint (2mm x3mm, QFN package) and its I^2C interface capable of working over wide digital I/O voltages enable this device in camera module monitoring application without demanding extra board space.

版权 © 2018–2019, Texas Instruments Incorporated

9 Power Supply Recommendations

9.1 AVDD and DVDD Supply Recommendations

The ADS7142-Q1 has two separate power supplies: AVDD and DVDD. The device operates on AVDD; DVDD is used for the interface circuits. AVDD and DVDD can be independently set to any value within the permissible ranges. The AVDD supply also defines the full-scale input range of the device. Always set the AVDD supply to be greater than or equal to the maximum input signal to avoid saturation of codes. Decouple the AVDD and DVDD pins respectively with C_{AVDD} = 220 nF and C_{DVDD} = 100 nF ceramic decoupling capacitors, as shown in 图 112.



Copyright © 2016, Texas Instruments Incorporated

图 112. Power-Supply Decoupling

10 Layout

10.1 Layout Guidelines

- Use a solid ground plane underneath the device and partition the PCB into analog and digital sections.
- Avoid crossing digital lines with the analog signal path and keep the analog input signals and the reference input signals away from noise sources.
- The power sources to the device must be clean and well-bypassed. Use C_{AVDD} decoupling capacitors in close proximity to the analog (AVDD) power supply pin.
- Use a C_{DVDD} decoupling capacitor close to the digital (DVDD) power-supply pin.
- Avoid placing vias between the AVDD and DVDD pins and the bypass capacitors.
- Connect the ground pin to the ground plane using a short, low-impedance path. Thermal pad should also be connected to the ground plane.
- Place the charge kickback filter components close to the device.

Among ceramic surface-mount capacitors, COG (NPO) ceramic capacitors are recommended because these components provide the most stable electrical properties over voltage, frequency, and temperature changes.

图 113 shows the typical connection diagram of ADS7142-Q1.

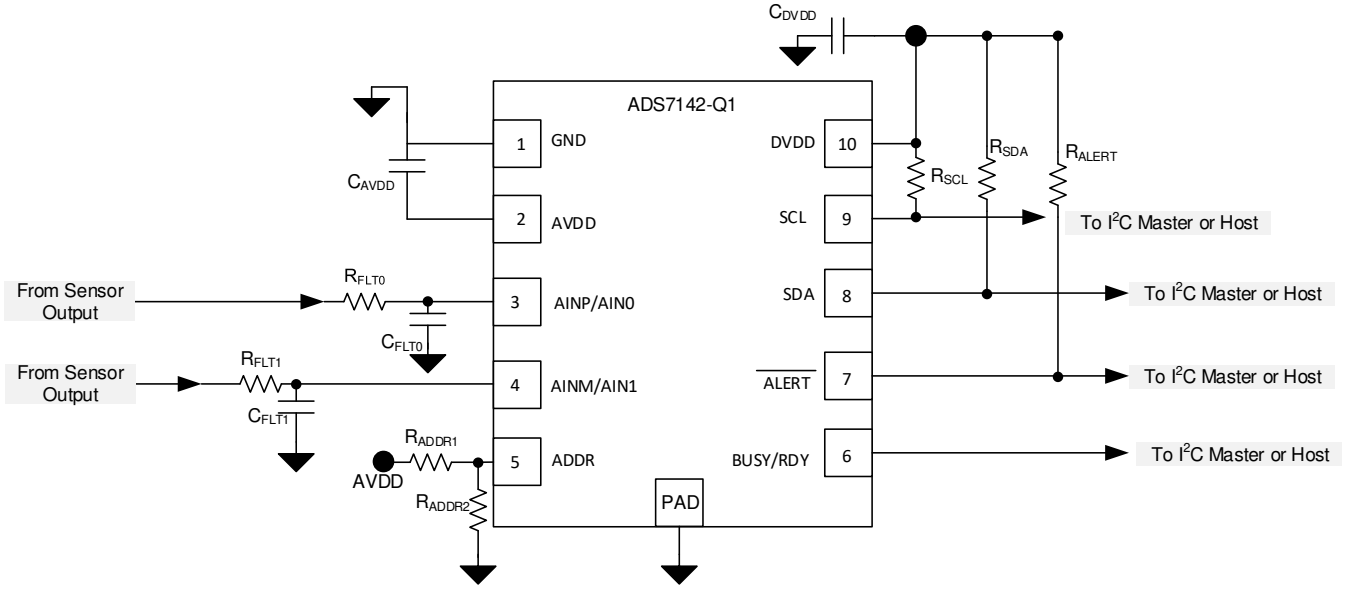


图 113. Example Schematic

版权 © 2018–2019, Texas Instruments Incorporated

10.2 Layout Example

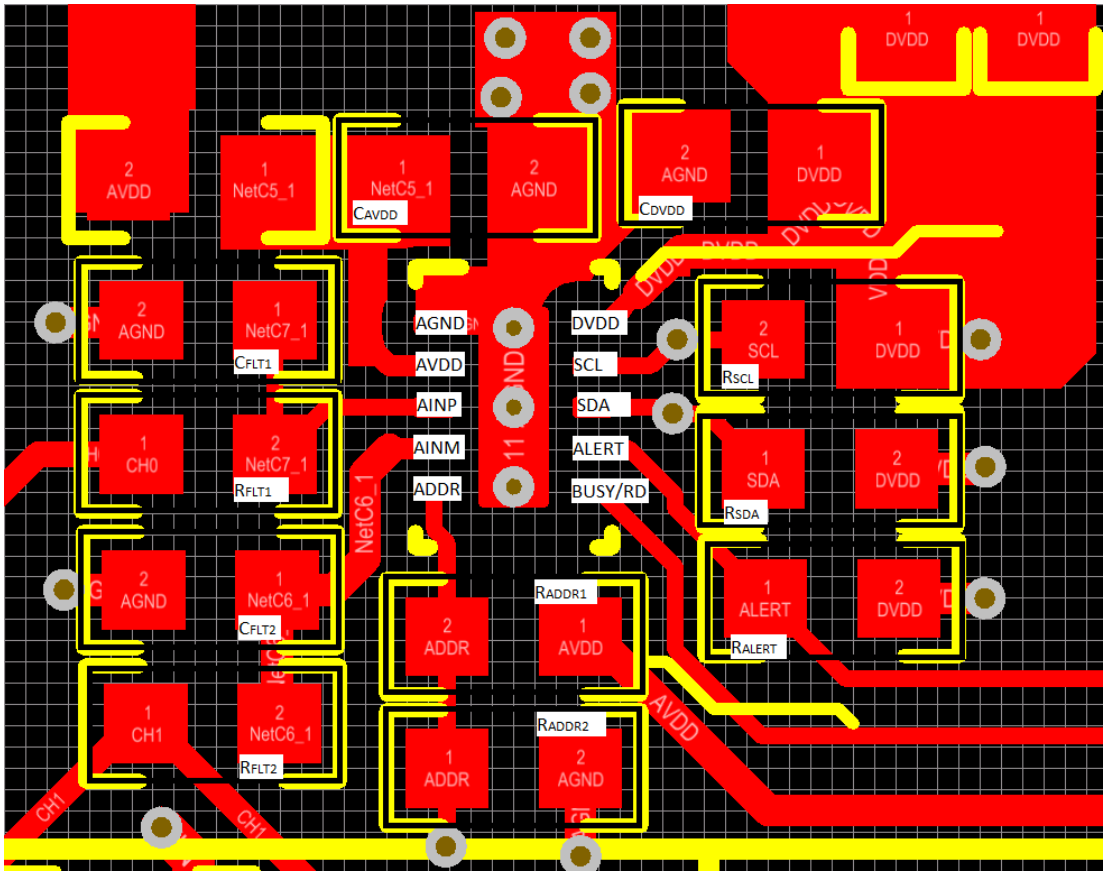


图 114. Example Layout

11 器件和文档支持

11.1 接收文档更新通知

要接收文档更新通知，请导航至 ti.com. 上的器件产品文件夹。单击右上角的*通知我*进行注册，即可每周接收产品信息更改摘要。有关更改的详细信息，请查看任何已修订文档中包含的修订历史记录。

11.2 社区资源

TI E2E™ support forums are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

Linked content is provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's Terms of Use.

11.3 商标

E2E is a trademark of Texas Instruments.
All other trademarks are the property of their respective owners.

11.4 静电放电警告



ESD 可能会损坏该集成电路。德州仪器 (TI) 建议通过适当的预防措施处理所有集成电路。如果不遵守正确的处理措施和安装程序，可能会损坏集成电路。

ESD 的损坏小至导致微小的性能降级，大至整个器件故障。 精密的集成电路可能更容易受到损坏，这是因为非常细微的参数更改都可能会导致器件与其发布的规格不相符。

11.5 Glossary

SLYZ022 — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

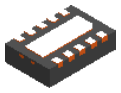
版权 © 2018–2019, Texas Instruments Incorporated

12 机械、封装和可订购信息

以下页面包含机械、封装和可订购信息。这些信息是指定器件的最新可用数据。数据如有变更，恕不另行通知，且不会对此文档进行修订。如需获取此数据表的浏览器版本，请查阅左侧的导航栏。

版权 © 2018–2019, Texas Instruments Incorporated

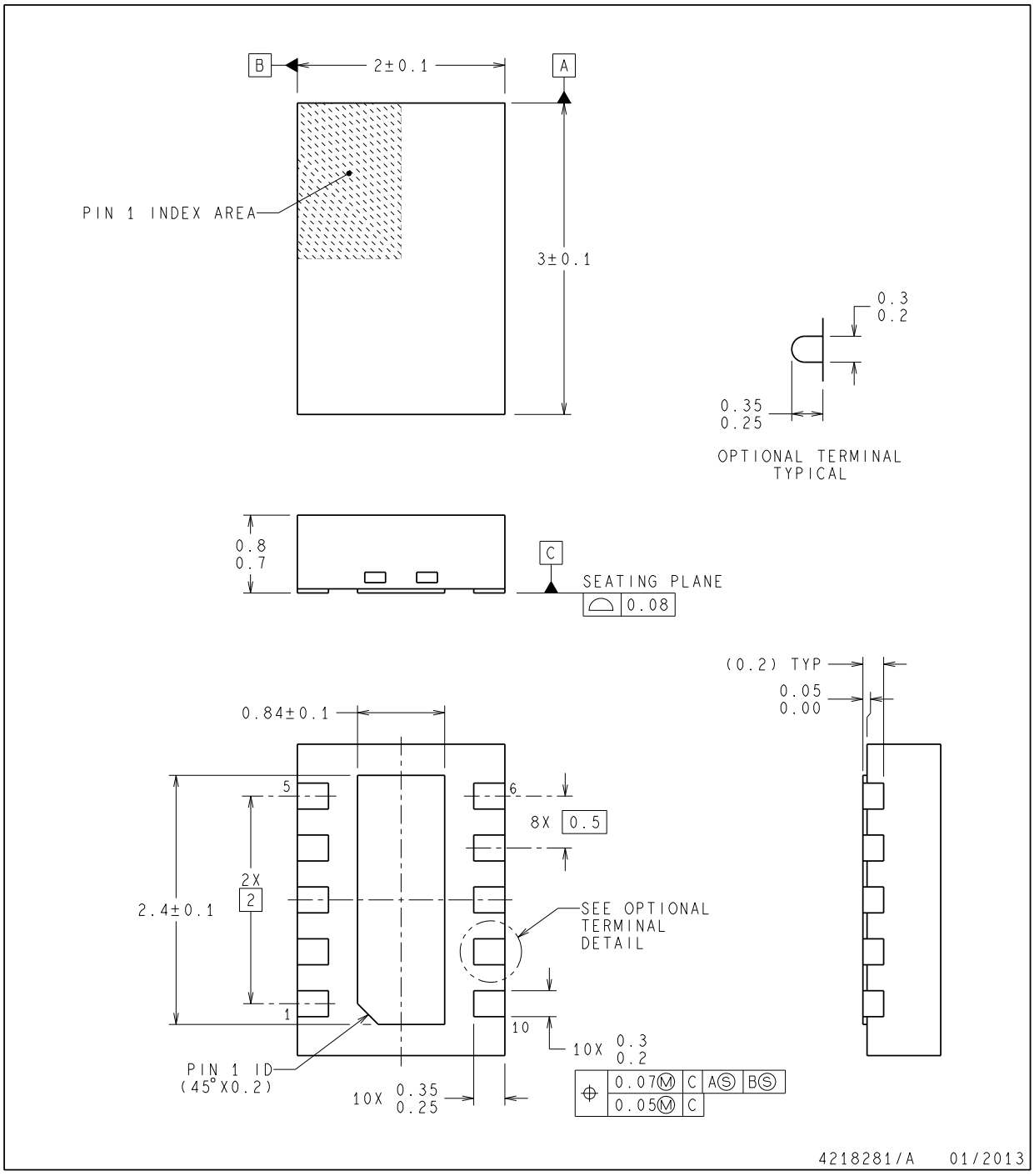
MECHANICAL DATA



DQC0010A

WSON - 0.8mm max height

QFN (PLASTIC QUAD FLATPACK-NO LEAD)



NOTES:
1. DIMENSIONS ARE IN MILLIMETERS. DIMENSIONS IN PARENTHESIS ARE FOR REFERENCE ONLY.
2. THIS DRAWING IS SUBJECT TO CHANGE WITHOUT NOTICE.
3. THE PACKAGE THERMAL PAD MUST BE SOLDERED TO THE PRINTED CIRCUIT BOARD FOR THERMAL AND MECHANICAL PERFORMANCE.
4. R-PWSON-N10.

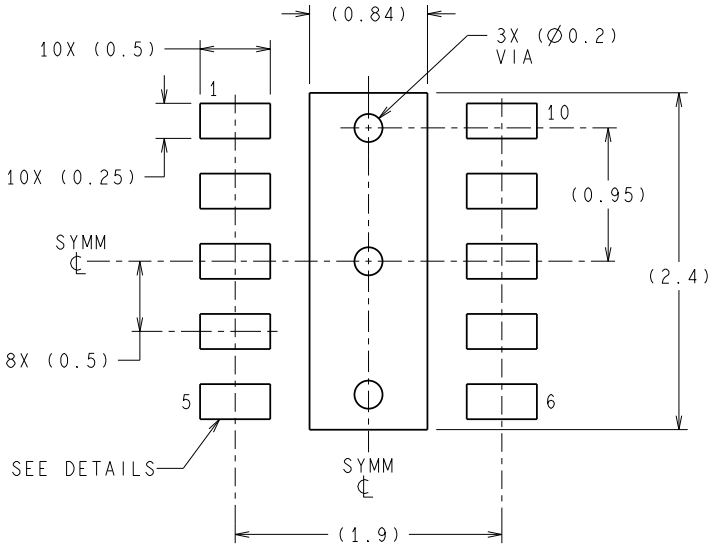
版权 © 2018–2019, Texas Instruments Incorporated

MECHANICAL DATA

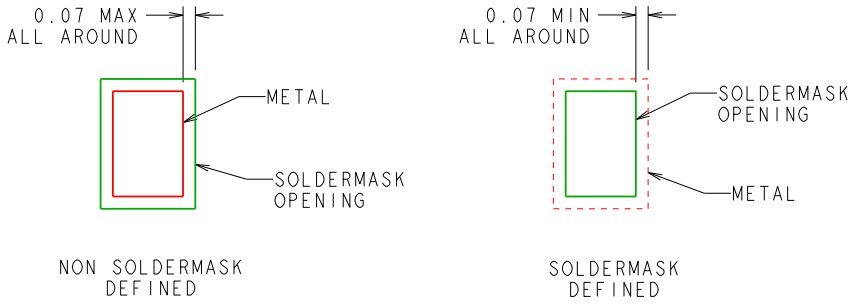
DQC0010A

WSON - 0.8mm max height

QFN (PLASTIC QUAD FLATPACK-NO LEAD)



RECOMMENDED LAND PATTERN



SOLDERMASK DETAILS

4218281/A 01/2013

NOTES: 1. FOR PCB LAYOUT AND ASSEMBLY CONSIDERATIONS PLEASE REFER TO SLUA271 APPLICATION REPORT AVAILABLE AT www.ti.com.

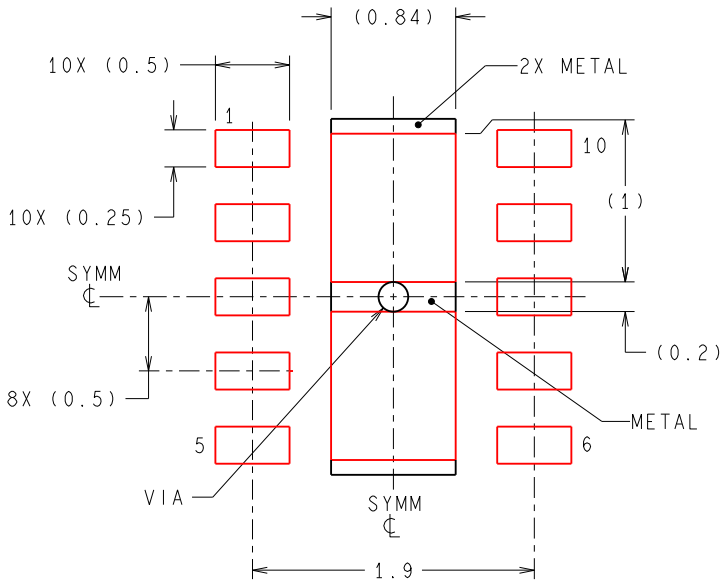
版权 © 2018–2019, Texas Instruments Incorporated

MECHANICAL DATA

DQC0010A

WSON - 0.8mm max height

QFN (PLASTIC QUAD FLATPACK-NO LEAD)



RECOMMENDED SOLDERPASTE
EXPOSED PAD
83% PRINTED SOLDER COVERAGE BY AREA

4218281/A 01/2013

版权 © 2018–2019, Texas Instruments Incorporated

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
ADS7142QDQCRQ1	ACTIVE	WSON	DQC	10	3000	RoHS & Green	SN	Level-2-260C-1 YEAR	-40 to 125	1AU	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".
RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.
Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF ADS7142-Q1 :

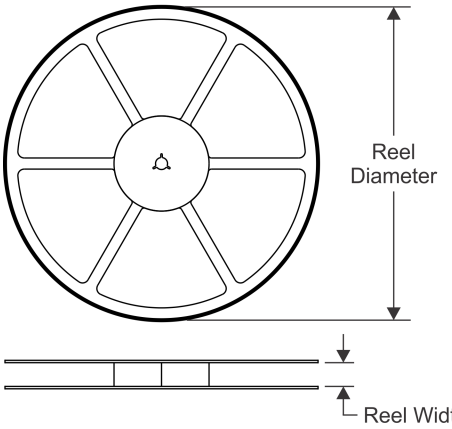
- Catalog : ADS7142

NOTE: Qualified Version Definitions:

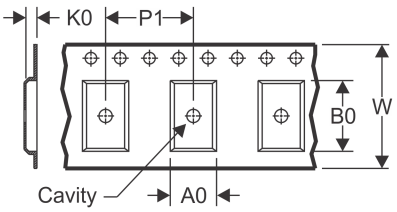
- Catalog - TI's standard catalog product

TAPE AND REEL INFORMATION

REEL DIMENSIONS

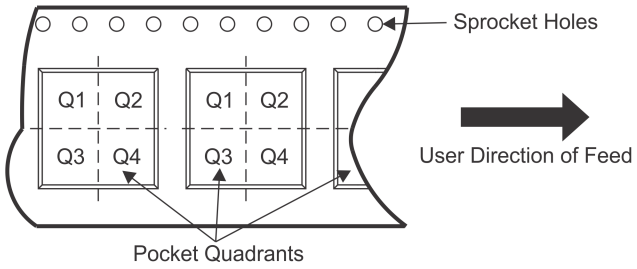


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

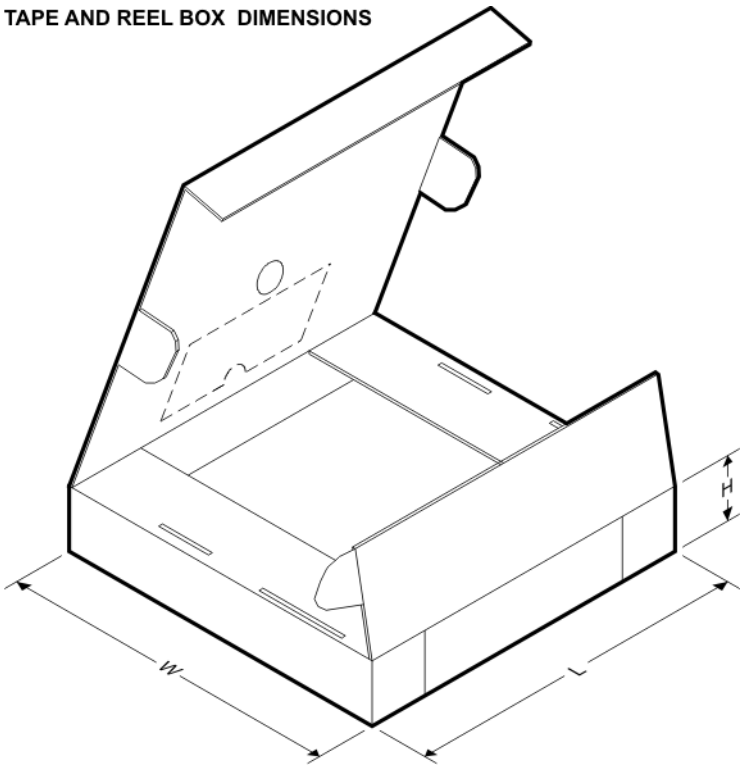
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
ADS7142QDQCRQ1	WSON	DQC	10	3000	180.0	8.4	2.3	3.2	1.0	4.0	8.0	Q1

TAPE AND REEL BOX DIMENSIONS



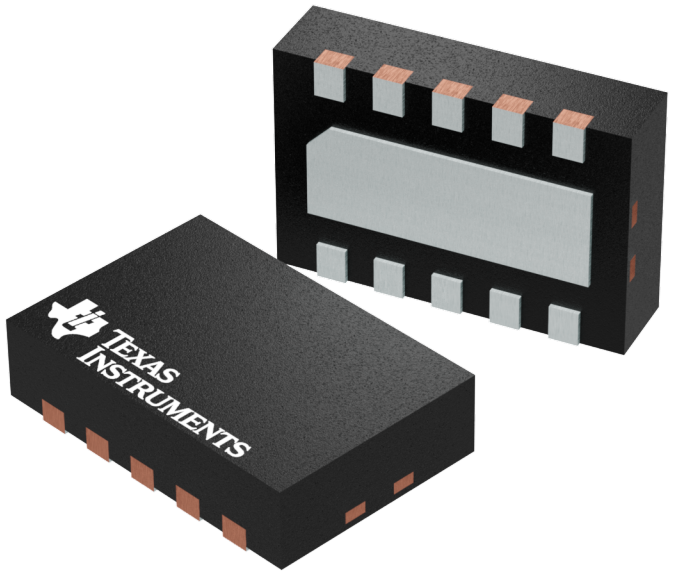
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
ADS7142QDQCRQ1	WSON	DQC	10	3000	213.0	191.0	35.0

GENERIC PACKAGE VIEW

DQC 10 WSON - 0.8 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



Images above are just a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.

4209674/B

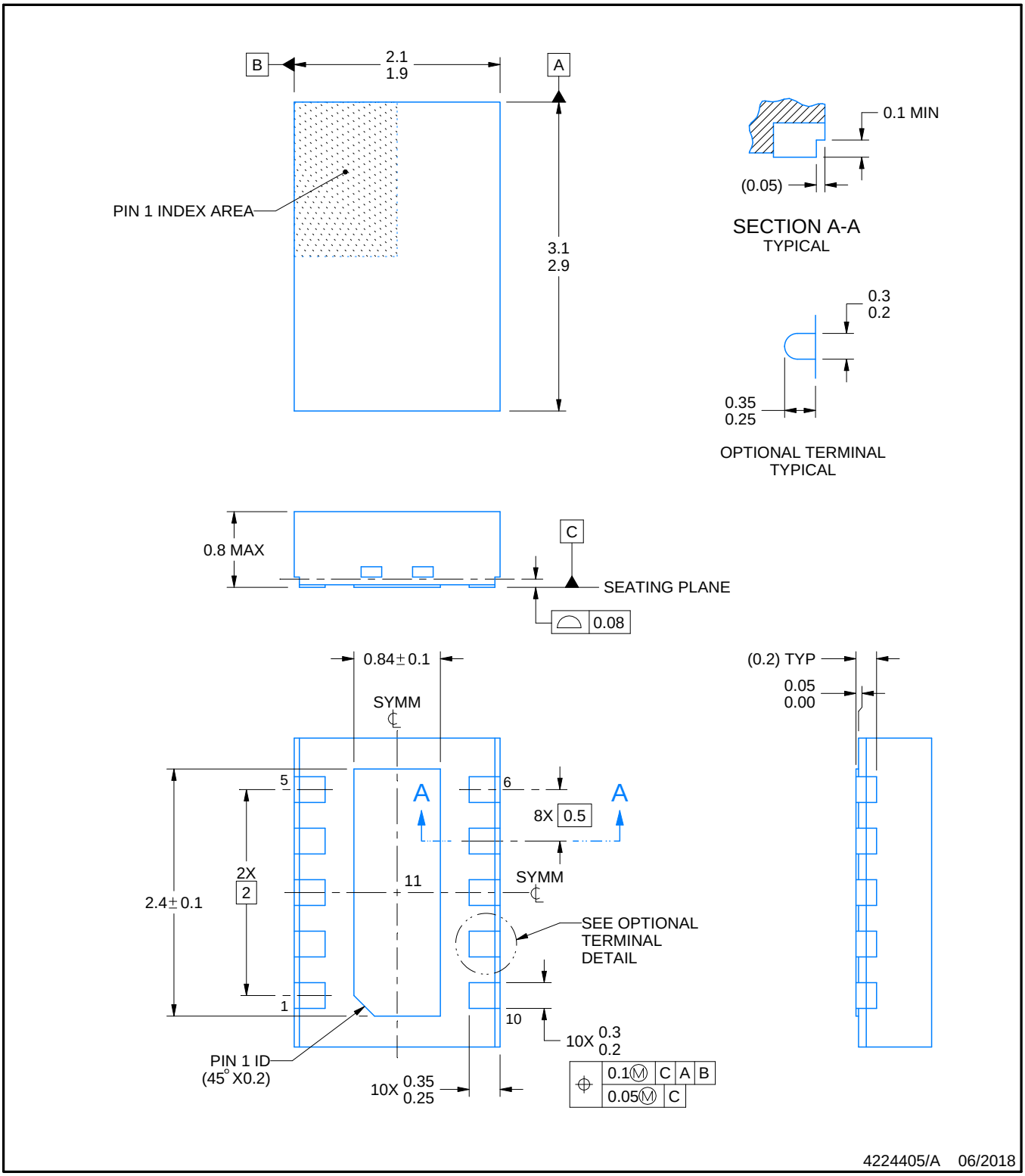


PACKAGE OUTLINE

DQC0010B

WSON - 0.8mm max height

PLASTIC SMALL OUTLINE - NO LEAD



NOTES:

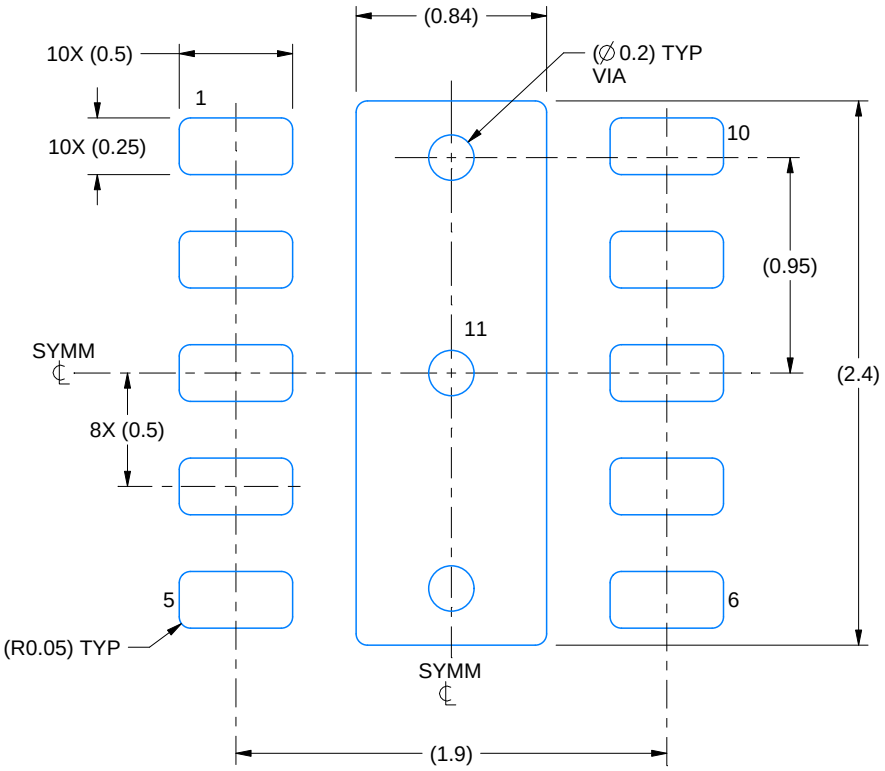
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.

EXAMPLE BOARD LAYOUT

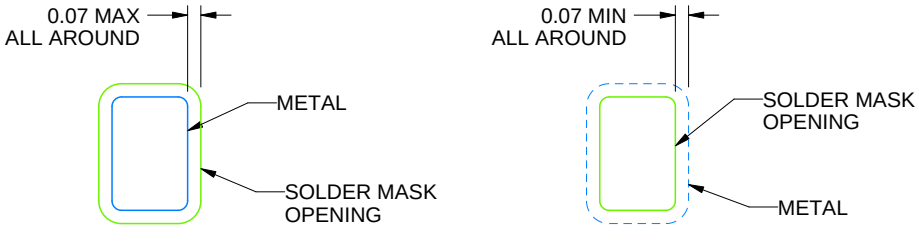
DQC0010B

WSON - 0.8mm max height

PLASTIC SMALL OUTLINE - NO LEAD



LAND PATTERN EXAMPLE
SCALE: 30X



SOLDER MASK DETAILS

4224405/A 06/2018

NOTES: (continued)

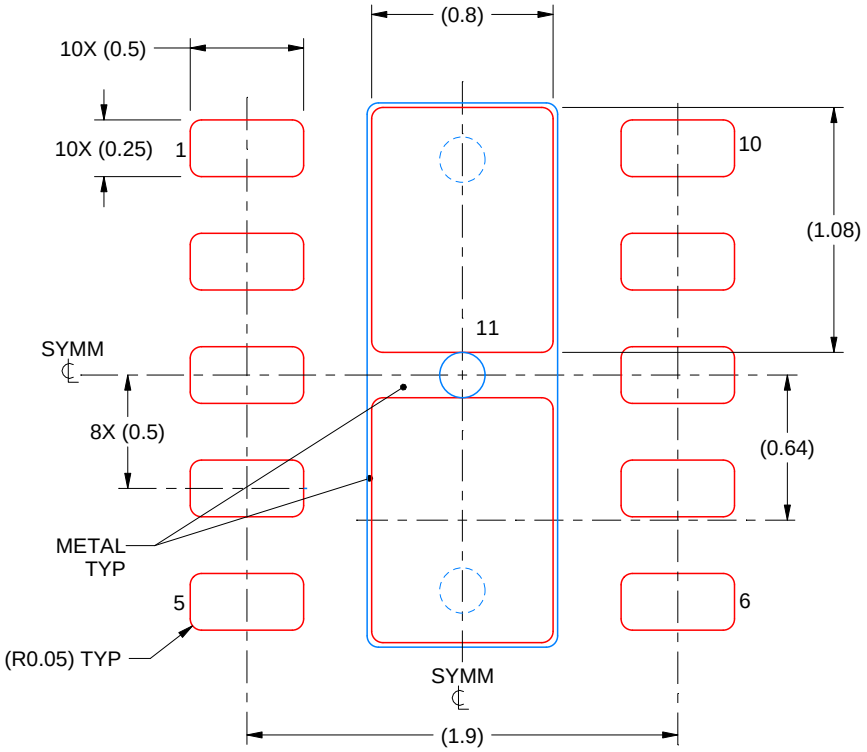
4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).
5. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.

EXAMPLE STENCIL DESIGN

DQC0010B

WSON - 0.8mm max height

PLASTIC SMALL OUTLINE - NO LEAD



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL

EXPOSED PAD 11:
86% PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE
SCALE: 30X

4224405/A 06/2018

NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

重要声明和免责声明

TI 提供技术和可靠性数据（包括数据表）、设计资源（包括参考设计）、应用或其他设计建议、网络工具、安全信息和其他资源，不保证没有瑕疵且不做出任何明示或暗示的担保，包括但不限于对适销性、某特定用途方面的适用性或不侵犯任何第三方知识产权的暗示担保。

这些资源可供使用 TI 产品进行设计的熟练开发人员使用。您将自行承担以下全部责任：(1) 针对您的应用选择合适的 TI 产品，(2) 设计、验证并测试您的应用，(3) 确保您的应用满足相应标准以及任何其他安全、安保或其他要求。这些资源如有变更，恕不另行通知。TI 授权您仅可将这些资源用于研发本资源所述的 TI 产品的应用。严禁对这些资源进行其他复制或展示。您无权使用任何其他 TI 知识产权或任何第三方知识产权。您应全额赔偿因在这些资源的使用中对 TI 及其代表造成的任何索赔、损害、成本、损失和债务，TI 对此概不负责。

TI 提供的产品受 TI 的销售条款 (https:www.ti.com.cn/zh-cn/legal/termsofsale.html) 或 ti.com.cn 上其他适用条款/TI 产品随附的其他适用条款的约束。TI 提供这些资源并不会扩展或以其他方式更改 TI 针对 TI 产品发布的适用的担保或担保免责声明。

邮寄地址：上海市浦东新区世纪大道 1568 号中建大厦 32 楼，邮政编码：200122
Copyright © 2021 德州仪器半导体技术（上海）有限公司